

MOS INTEGRATED CIRCUIT

μ PD17145, 17147, 17149, 17145(A), 17147(A), 17149(A)

SMALL GENERAL-PURPOSE 4 BIT SINGLE-CHIP MICROCONTROLLER

The μ PD17145, μ PD17147, μ PD17149, μ PD17145(A), μ PD17147(A), and μ PD17149(A) are 4-bit single-chip microcontrollers containing an 8-bit A/D converter (four channels), three timers, and a serial interface.

For the CPU, the μ PD17145, μ PD17147, μ PD17149, μ PD17145(A), μ PD17147(A), and μ PD17149(A) use general registers. They can perform operations directly on data memory and transfer data directly between memory, allowing programming to be done efficiently. Each instruction is 16 bits (one word) long.

Since the μ PD17145, μ PD17147, μ PD17149, μ PD17145(A), μ PD17147(A), and μ PD17149(A) have an on-chip A/D converter and serial interface, they are suitable for electronic control in various applications such as electric home appliances. The μ PD17P149, a one-time PROM product, is available for evaluation of the μ PD17145, μ PD17147, μ PD17149, μ PD17145(A), μ PD17147(A), and μ PD17149(A) and for small-scale production of general electronic equipment.

The following user's manual completely describes the functions of the μ PD17145, μ PD17147, μ PD17149, μ PD17145(A), μ PD17147(A), and μ PD17149(A). Be sure to read it before designing an application system.

μ PD17145 Sub-Series User's Manual: U10261E

FEATURES

- 17K architecture: General registers, 16-bit instructions
- Program memory (ROM):
 - μ PD17145: 2K bytes (1024 \times 16 bits)
 - μ PD17147: 4K bytes (2048 \times 16 bits)
 - μ PD17149: 8K bytes (4096 \times 16 bits)
- Data memory (RAM): 110 \times 4 bits
- External interrupt: 1 line (INT pin, with sensor input)
- Instruction execution time: 2 μ s (when $f_x = 8$ MHz, ceramic oscillation)
- 8-bit A/D converter: 4 channels
 - Absolute accuracy: ± 1.5 LSB or lower ($V_{DD} = 4.0$ to 5.5 V)
- Timer function: 3 channels
- Serial interface: 1 channel (three-wire synchronous mode)
- POC circuit (mask option)
- Supply voltage:
 - $V_{DD} = 2.7$ to 5.5 V (when $f_x = 400$ kHz to 2 MHz)
 - $V_{DD} = 4.5$ to 5.5 V (when $f_x = 400$ kHz to 8 MHz)

APPLICATIONS

- μ PD17145, μ PD17147, and μ PD17149 : Electric appliances, battery chargers, cameras, electronic measuring instruments
- μ PD17145(A), μ PD17147(A), and μ PD17149(A) : Electrical equipment for automobile

In this manual, the product described is the μ PD17149 unless otherwise specified.

The information in this document is subject to change without notice.

ORDERING INFORMATION

Part number	Package	Quality grade
μPD17145CT-xxx	28-pin plastic shrink DIP (400 mil)	Standard
μPD17145GT-xxx	28-pin plastic SOP (375 mil)	Standard
μPD17147CT-xxx	28-pin plastic shrink DIP (400 mil)	Standard
μPD17147GT-xxx	28-pin plastic SOP (375 mil)	Standard
μPD17149CT-xxx	28-pin plastic shrink DIP (400 mil)	Standard
μPD17149GT-xxx	28-pin plastic SOP (375 mil)	Standard
μPD17145CT(A)-xxx	28-pin plastic shrink DIP (400 mil)	Special
μPD17145GT(A)-xxx	28-pin plastic SOP (375 mil)	Special
μPD17147CT(A)-xxx	28-pin plastic shrink DIP (400 mil)	Special
μPD17147GT(A)-xxx	28-pin plastic SOP (375 mil)	Special
μPD17149CT(A)-xxx	28-pin plastic shrink DIP (400 mil)	Special
μPD17149GT(A)-xxx	28-pin plastic SOP (375 mil)	Special

Remark xxx is a ROM code

The μPD17145, μPD17147, and μPD17149 differ from those suffixed with (A) in quality grades only.

Please refer to "Quality Grades on NEC Semiconductor Devices" (Document No. C11531E) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

FUNCTIONS

Product	μPD17145	μPD17147	μPD17149
ROM	2K bytes (1024 × 16 bits)	4K bytes (2048 × 16 bits)	8K bytes (4096 × 16 bits)
RAM	110 × 4 bits		
Stack	5 address stacks, 3 interrupt stacks		
Number of I/O ports	23 { <ul style="list-style-type: none"> • 20 I/O ports • 2 general input ports • 1 sensor input port (INT pin^{Note}) 		
A/D converter input	4 channels (shared with ports) with an absolute accuracy of ±1.5 LSB or less (supply voltage (V _{DD}): 4.0 to 5.5 V)		
Timer	3 channels { <ul style="list-style-type: none"> • 2 channels for 8-bit timer counter (They can be used together as one 16-bit timer.) • 1 channel for 7-bit basic interval timer (can be used as a watchdog timer) 		
Serial interface	1 channel (3-wire type)		
Interrupt	<ul style="list-style-type: none"> • Up to 3 levels of multiple hardware interrupt • 1 external interrupt (INT) { <ul style="list-style-type: none"> Detection of the rising edge Detection of the falling edge Detection of both edges } Selectable • 4 internal interrupts { <ul style="list-style-type: none"> • Timer 0 (TM0) • Timer 1 (TM1) • Basic interval timer (BTM) • Serial interface (SIO) 		
Execution time of an instruction	2 μs (at f _x = 8 MHz, ceramic oscillation)		
Standby function	STOP/HALT		
POC circuit	Mask option (Can be used in an application circuit where V _{DD} is 5 V ±10 % and the clock frequency ranges from 400 kHz to 4 MHz)		
Operating supply voltage	<ul style="list-style-type: none"> • V_{DD} = 2.7 to 5.5 V (at 400 kHz to 2 MHz) • V_{DD} = 4.5 to 5.5 V (at 400 kHz to 8 MHz) 		
Package	<ul style="list-style-type: none"> • 28-pin plastic shrink DIP (400 mil) • 28-pin plastic SOP (375 mil) 		
One-time PROM	μPD17P149		

★

Note The INT pin can be used as an input pin (sensor input) when the external interrupt function is not used. The status of the pin is read with the INT flag of the control register, not with the port register.

Caution Although a PROM product is highly compatible with a masked ROM product in respect of functions, they differ in internal ROM circuits and part of electrical characteristics. Before changing the PROM product to the masked ROM product in an application system, evaluate the system carefully using the masked ROM product.

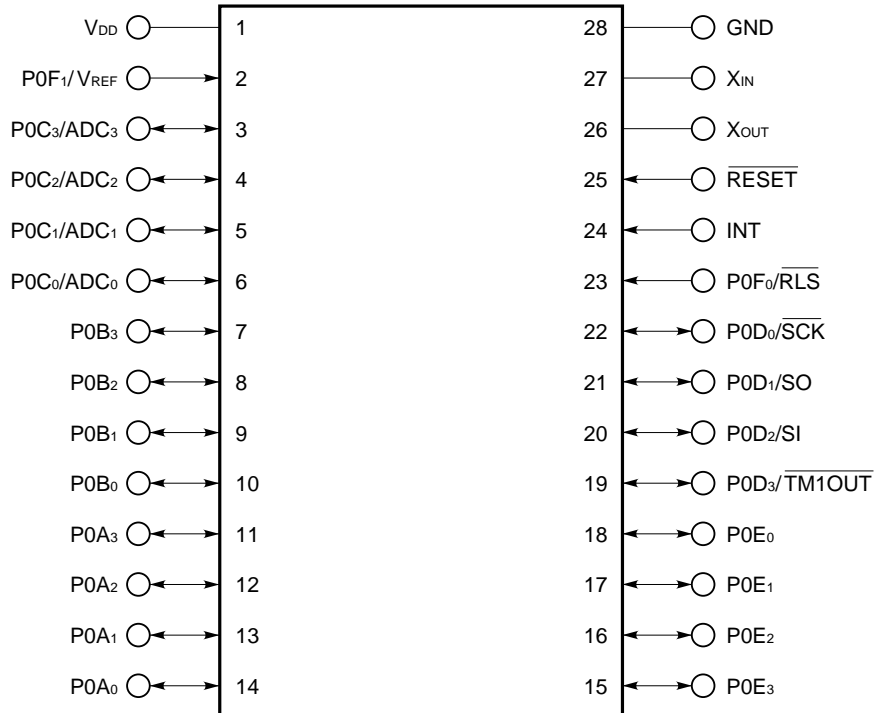
PIN CONFIGURATION (TOP VIEW)

• **28-pin plastic shrink DIP (400 mil)**

μPD17145CT-xxx, μPD17147CT-xxx, μPD17149CT-xxx, μPD17145CT(A)-xxx, μPD17147CT(A)-xxx, μPD17149CT(A)-xxx

• **28-pin plastic SOP (375 mil)**

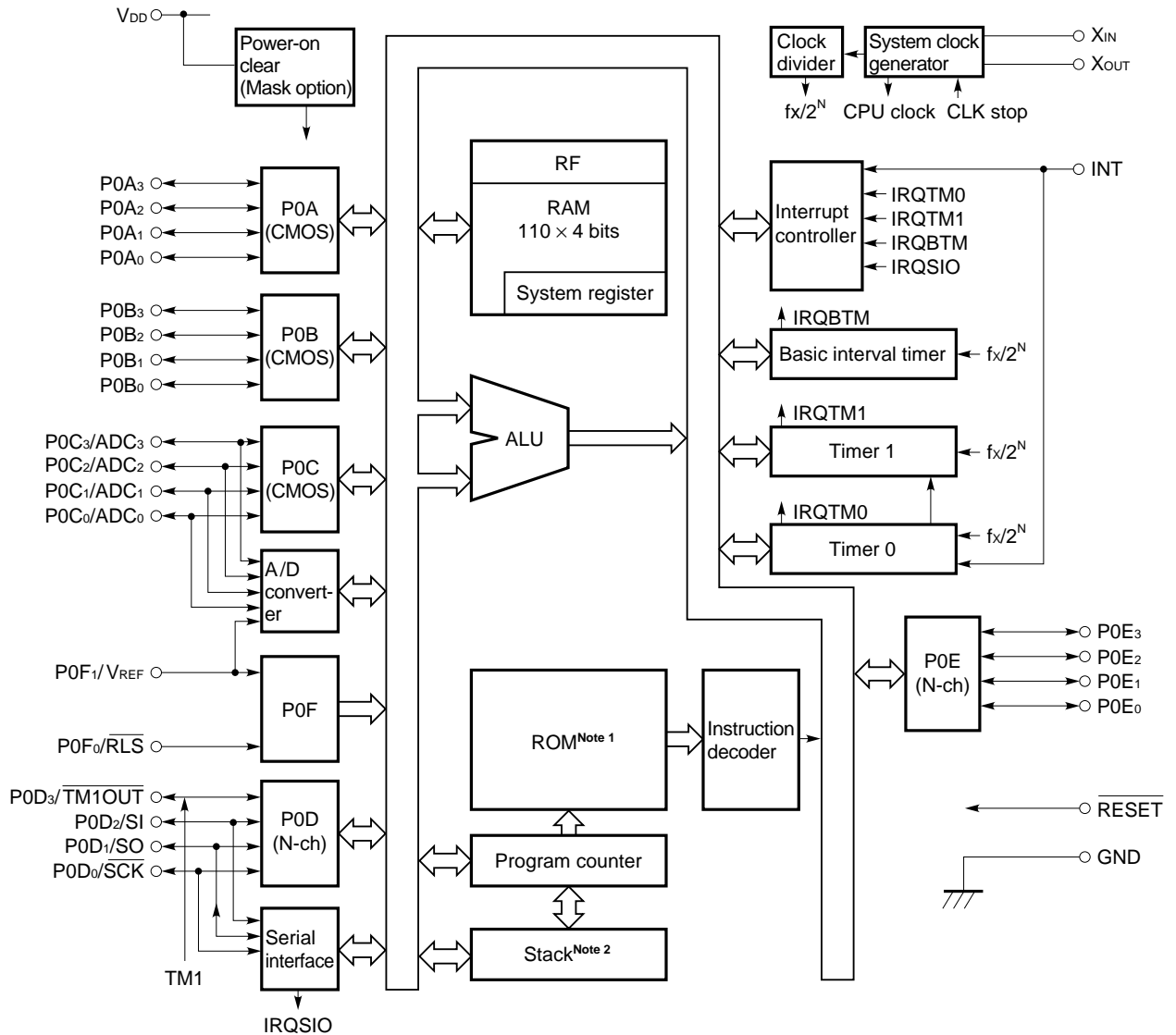
μPD17145GT-xxx, μPD17147GT-xxx, μPD17149GT-xxx, μPD17145GT(A)-xxx, μPD17147GT(A)-xxx, μPD17149GT(A)-xxx



ADC₀ - ADC₃ : Analog input converter
 GND : Ground
 INT : External interrupt input
 P0A₀ - P0A₃ : Port 0A
 P0B₀ - P0B₃ : Port 0B
 P0C₀ - P0C₃ : Port 0C
 P0D₀ - P0D₃ : Port 0D
 P0E₀ - P0E₃ : Port 0E
 P0F₀ and P0F₁ : Port 0F

$\overline{\text{RESET}}$: Reset input
 $\overline{\text{RLS}}$: Standby release signal input
 $\overline{\text{SCK}}$: Serial clock input/output
 SI : Serial data input
 SO : Serial data output
 $\overline{\text{TM1OUT}}$: Timer 1 carry output
 V_{DD} : Power supply
 V_{REF} : Reference voltage for the A/D converter
 X_{IN}, X_{OUT} : System clock oscillation

BLOCK DIAGRAM



Notes 1. The capacity of the ROM depends on the product, as follows.

1024 × 16 bits: μ PD17145

2048 × 16 bits: μ PD17147

4096 × 16 bits: μ PD17149

2. The capacity of the stack depends on the product, as follows.

5 × 10 bits: μ PD17145

5 × 11 bits: μ PD17147

5 × 12 bits: μ PD17149

Remark The terms CMOS and N-ch in parentheses indicate the output form of the port.

CMOS : CMOS push-pull output

N-ch : N-channel open-drain output

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1. PINS

1.1 PIN FUNCTIONS

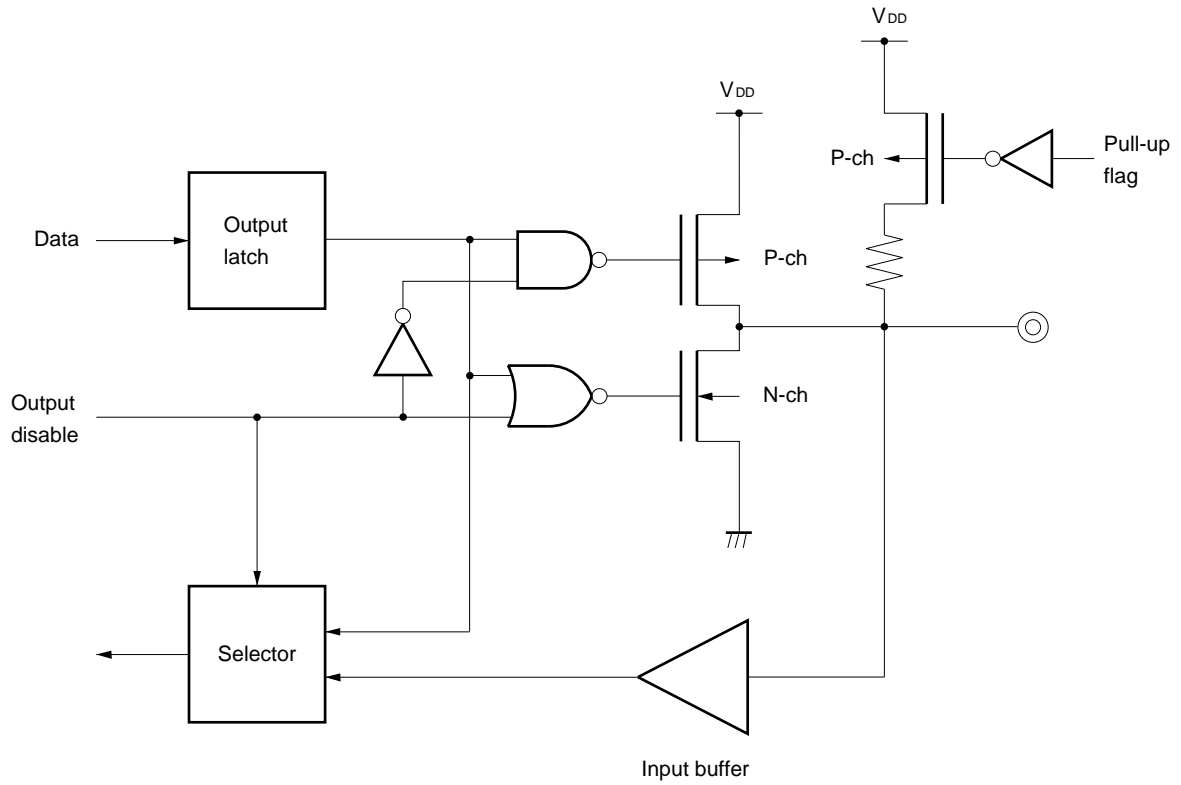
Pin No.	Symbol	Function	Output	After reset
1	V _{DD}	Power supply	-	-
2	P0F ₁ /V _{REF}	Port 0F. The reference voltage is supplied to the A/D converter through this pin. <ul style="list-style-type: none"> • Pull-up resistor incorporation specifiable by mask option • P0F₁ <ul style="list-style-type: none"> • Bit 1 of 2-bit input port P0F • V_{REF} <ul style="list-style-type: none"> • Reference voltage input for the A/D converter 	Input	Input (P0F ₁)
3 - 6	P0C ₃ /ADC ₃ - P0C ₀ /ADC ₀	Port 0C. Analog voltage is supplied to the A/D converter through these pins. <ul style="list-style-type: none"> • P0C₃ - P0C₀ <ul style="list-style-type: none"> • 4-bit input/output port • Input/output setting allowed in units of 1 bit • ADC₃ - ADC₀ <ul style="list-style-type: none"> • Analog input for the A/D converter 	CMOS push-pull	Input (P0C)
7 8 9 10	P0B ₃ P0B ₂ P0B ₁ P0B ₀	Port 0B <ul style="list-style-type: none"> • 4-bit input/output port • Input/output setting allowed in units of 4 bits • Pull-up resistor incorporation specifiable by program in units of 4 bits 	CMOS push-pull	Input
11 12 13 14	P0A ₃ P0A ₂ P0A ₁ P0A ₀	Port 0A <ul style="list-style-type: none"> • 4-bit input/output port • Input/output setting allowed in units of 4 bits • Pull-up resistor incorporation specifiable by program in units of 4 bits 	CMOS push-pull	Input
★ 15 16 17 18	P0E ₃ P0E ₂ P0E ₁ P0E ₀	Port 0E <ul style="list-style-type: none"> • 4-bit input/output port • Input/output setting allowed in units of 4 bits • Pull-up resistor incorporation specifiable by program in units of 4 bits 	N-ch open drain (withstand voltage: V _{DD} (max.))	Input

Pin No.	Symbol	Function	Output	After reset
19	P0D ₃ /TM1OUT	Pin for port 0D, timer 1 output, serial data input, serial data output, and serial clock input/output <ul style="list-style-type: none"> • Pull-up resistor incorporation specified by program bit by bit • P0D₃ - P0D₀ <ul style="list-style-type: none"> • 4-bit input/output port • Input/output setting allowed bit by bit • TM1OUT <ul style="list-style-type: none"> • Timer 1 output 	N-ch open drain (withstand voltage: V _{DD} (max.))	Input (P0D)
20	P0D ₂ /SI	<ul style="list-style-type: none"> • SI <ul style="list-style-type: none"> • Serial data input 		
21	P0D ₁ /SO	<ul style="list-style-type: none"> • SO <ul style="list-style-type: none"> • Serial data output 		
22	P0D ₀ /SCK	<ul style="list-style-type: none"> • SCK <ul style="list-style-type: none"> • Serial clock input/output 		
23	P0F ₀ /RLS	Pin for port 0F and input for standby mode release signal <ul style="list-style-type: none"> • Pull-up resistor incorporation specifiable by mask option • P0F₀ <ul style="list-style-type: none"> • Bit 0 of 2-bit input port P0F • RLS <ul style="list-style-type: none"> • Input for standby mode release signal 	Input	Input (P0F ₀)
24	INT	Input for an external interrupt request signal and standby mode release signal. <ul style="list-style-type: none"> • Pull-up resistor incorporation specifiable by mask option. 	Input	Input
25	RESET	System reset input pin <ul style="list-style-type: none"> • Pull-up resistor incorporation specifiable by mask option 	Input	Input
26	X _{OUT}	For system clock oscillation	-	-
27	X _{IN}	The ceramic resonator is connected between X _{IN} and X _{OUT} .		
28	GND	Ground	-	-

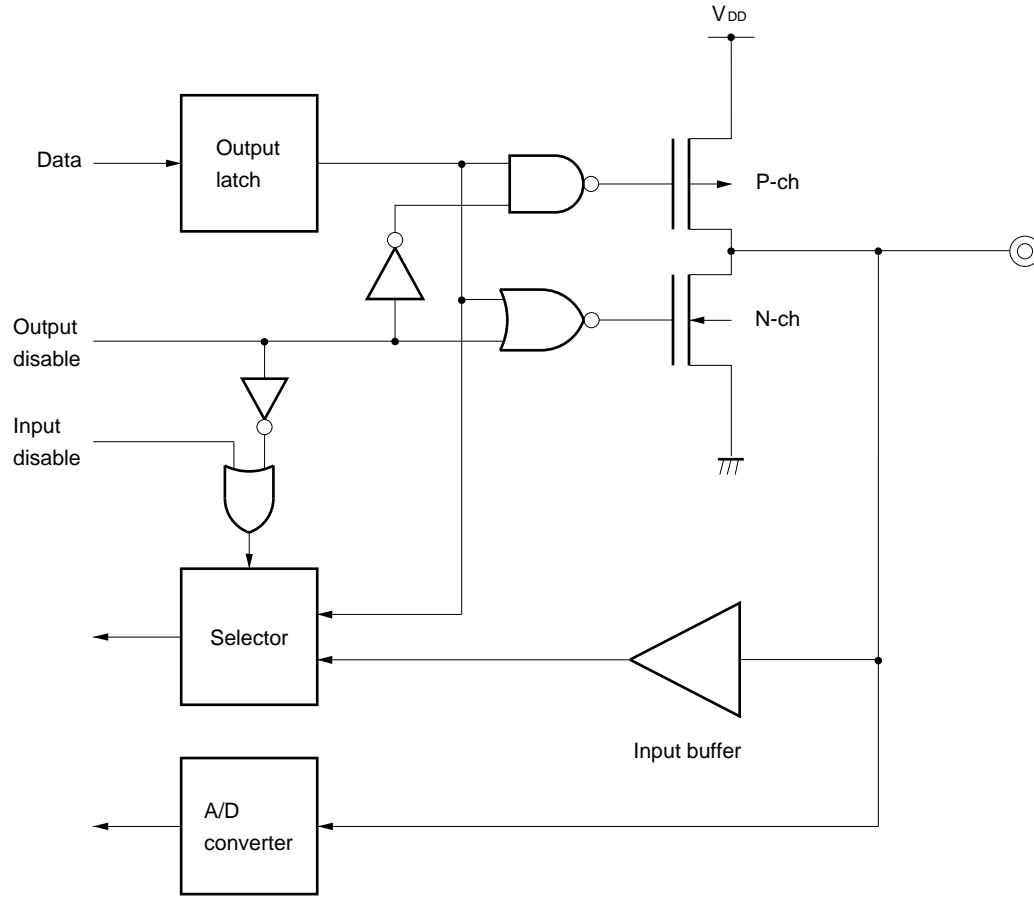
1.2 EQUIVALENT INPUT/OUTPUT CIRCUITS

Below are simplified diagrams of the input/output circuits for each pin.

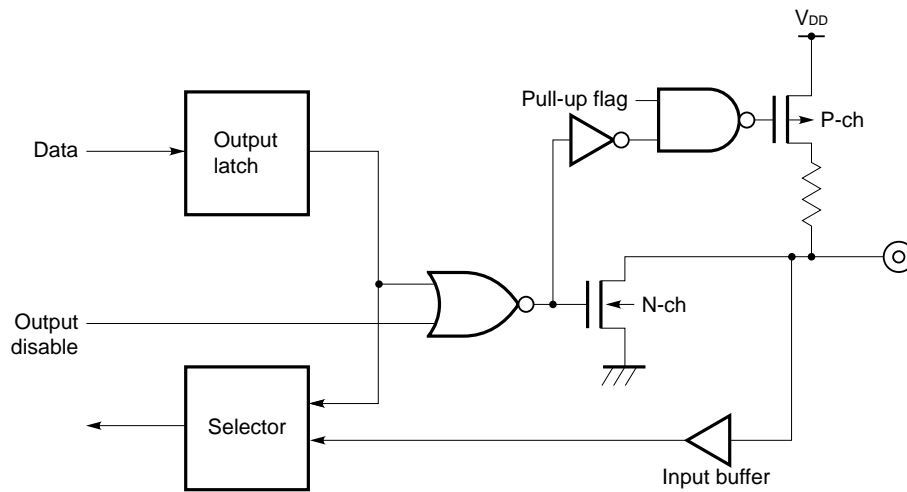
(1) P0A₀ - P0A₃, P0B₀ - P0B₃



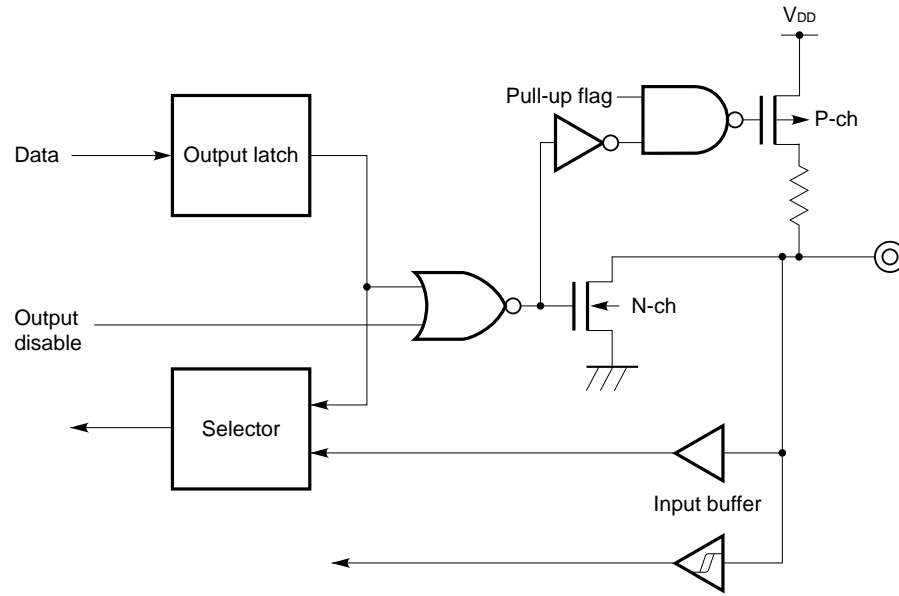
(2) P0C0/ADC0 - P0C3/ADC3



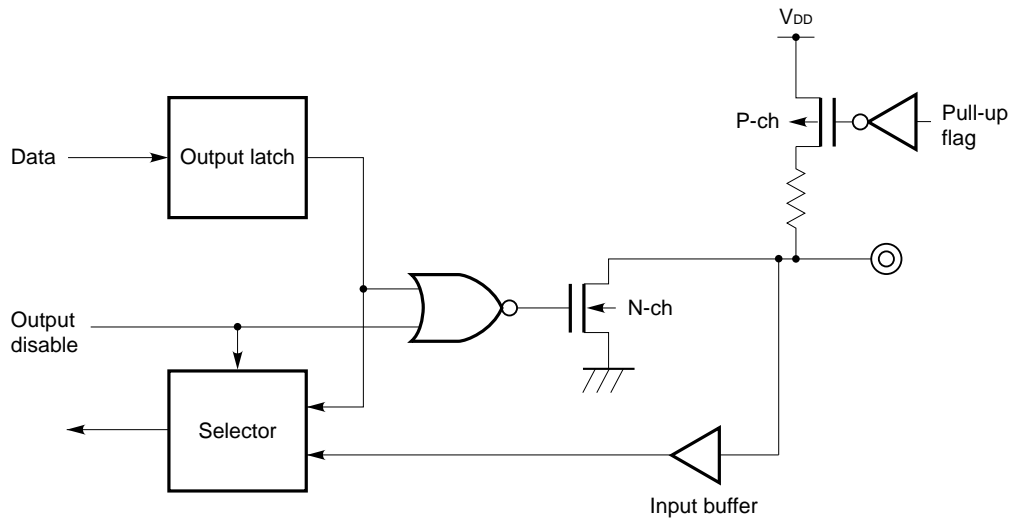
(3) P0D3/TM1OUT, P0D1/SO



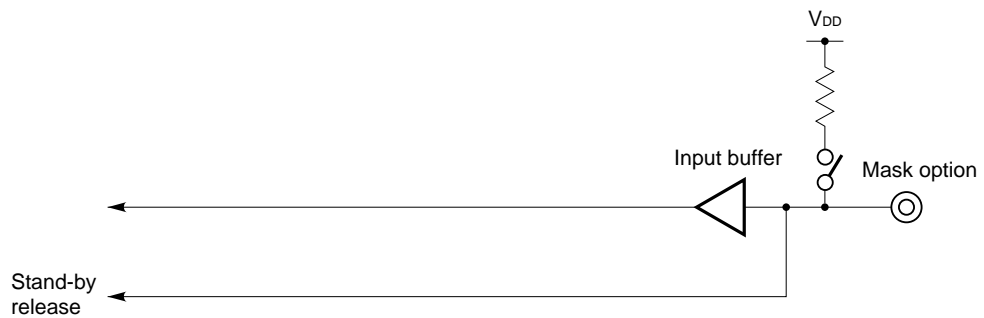
(4) P0D2/SI, P0D0/ $\overline{\text{SCK}}$



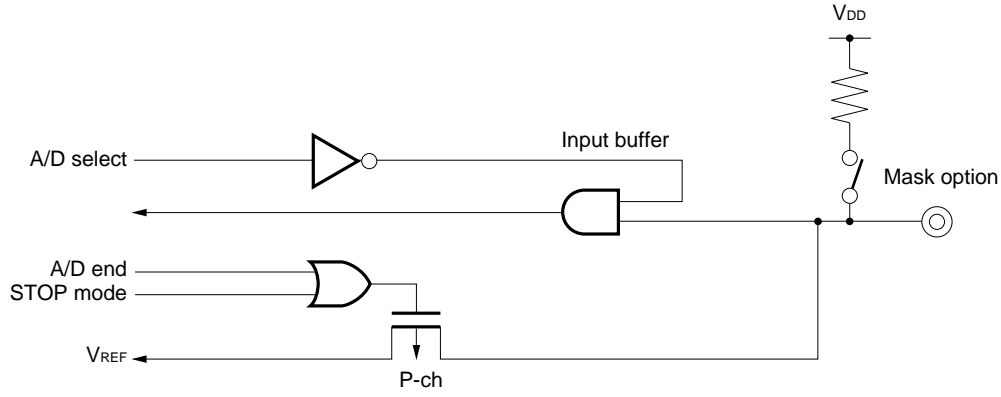
(5) P0E₀ - P0E₃



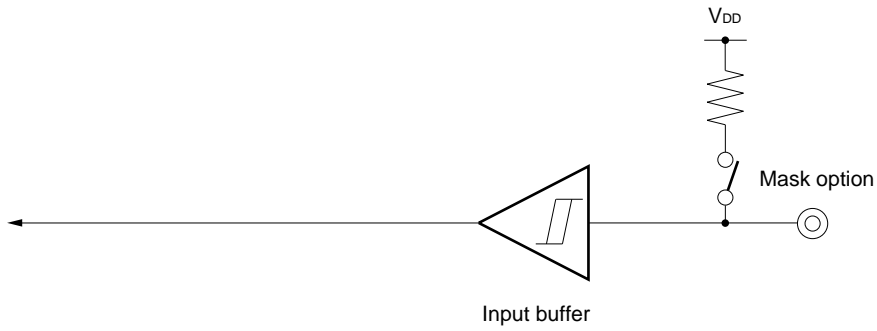
(6) P0F0/ $\overline{\text{RLS}}$



(7) P0F1/VREF



(8) $\overline{\text{RESET}}$, INT



1.3 HANDLING UNUSED PINS

The unused pins should be handled as described in Table 1-1.

Table 1-1 Handling Unused Pins

Pin		Conditions and handling		
		Internal	External	
Port	Input mode	P0A, P0B, P0D, P0E	Pull-up resistors that can be specified with the software are incorporated.	Leave open.
		P0C	-	Connect to V _{DD} or to ground through separate resistors ^{Note 1}
		P0F ₁	Pull-up resistors that can be specified with the mask option are not incorporated.	Connect directly to ground.
			Pull-up resistors that can be specified with the mask option are incorporated.	Leave open.
		P0F ₀ ^{Note 2}	Pull-up resistors that can be specified with the mask option are not incorporated.	Connect directly to ground.
	Output mode	P0A, P0B, P0C (CMOS ports)	-	Leave open.
		P0D (N-ch open-drain port)	Outputs low level.	
		P0E (N-ch open-drain port)	Outputs low level without pull-up resistors that can be specified with the software.	
	Outputs high level with pull-up resistors that can be specified with the software.			
	External interrupt (INT)		Pull-up resistors that can be specified with the mask option are not incorporated.	Connect directly to V _{DD} or ground.
Pull-up resistors that can be specified with the mask option are incorporated.			Leave open.	
RESET ^{Note 3} (When use only internal POC circuit)		Pull-up resistors that can be specified with the mask option are not incorporated.	Connect directly to V _{DD} .	
		Pull-up resistors that can be specified with the mask option are incorporated.		

- ★ **Notes 1.** When a pin is pulled up to V_{DD} (connected to V_{DD} through resistors) or pulled down to ground (connected to ground through resistors) outside the chip, take the driving capacity and maximum current consumption of a port into consideration. When using high-resistance pull-up or pull-down resistors, apply appropriate countermeasures to ensure that noise is not attracted by the resistors. Although the optimum pull-up or pull-down resistor varies with the application circuit, in general, a resistor of 10 to 100 kilohms is suitable.

- Notes 2.** Since the $\overline{P0F0/RLS}$ pin is also used for setting the test mode, connect it directly to ground without incorporating a pull-up resistor that can be specified with the mask option, when the pin is not used.
3. When designing an application circuit which requires high reliability, be sure to design a circuit to which an external \overline{RESET} signal can be input. Since the \overline{RESET} pin is also used for setting the test mode, connect it to V_{DD} directly when not used.

Caution To fix the I/O mode, pull-up resistors that can be specified with the software, and output level of a pin, it is recommended that they should be specified repeatedly within a loop in a program.

1.4 NOTES ON USE OF THE \overline{RESET} AND $\overline{P0F0/RLS}$ PINS

The \overline{RESET} and $\overline{P0F0/RLS}$ pins have the test mode selecting function for testing the internal operation of the μ PD17149 (IC test), besides the functions shown in **Section 1.1**.

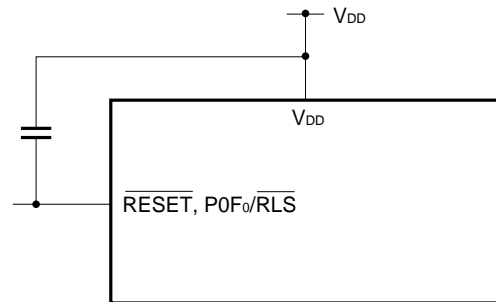
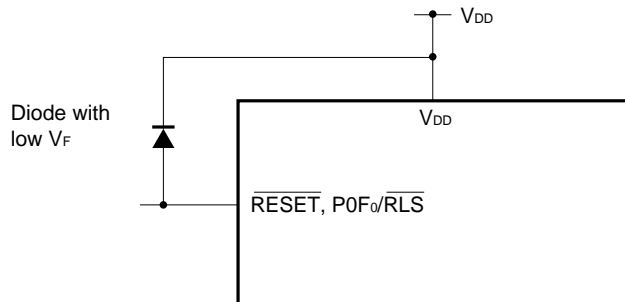
Applying a voltage exceeding V_{DD} to the \overline{RESET} and/or $\overline{P0F0/RLS}$ pin causes the μ PD17149 to enter the test mode. When noise exceeding V_{DD} comes in during normal operation, the device is switched to the test mode.

For example, if the wiring from the \overline{RESET} or $\overline{P0F0/RLS}$ pin is too long, noise may be induced on the wiring, causing this mode switching.

When installing the wiring, lay the wiring in such a way that noise is suppressed as much as possible. If noise yet arises, use an external part to suppress it as shown below.

- Connect a diode with low V_F between the pin and V_{DD} .

- Connect a capacitor between the pin and V_{DD} .



2. PROGRAM MEMORY (ROM)

Table 2-1 lists the program memory configuration for the μPD17145, μPD17147, and μPD17149.

Table 2-1 Program Memory Configuration

Product	Program memory capacity	Address range
μPD17145	2K bytes (1024 × 16 bits)	0000H - 03FFH
μPD17147	4K bytes (2048 × 16 bits)	0000H - 07FFH
μPD17149	8K bytes (4096 × 16 bits)	0000H - 0FFFH

Program memory stores the program and the constant data table.

The program memory address is specified by the program counter.

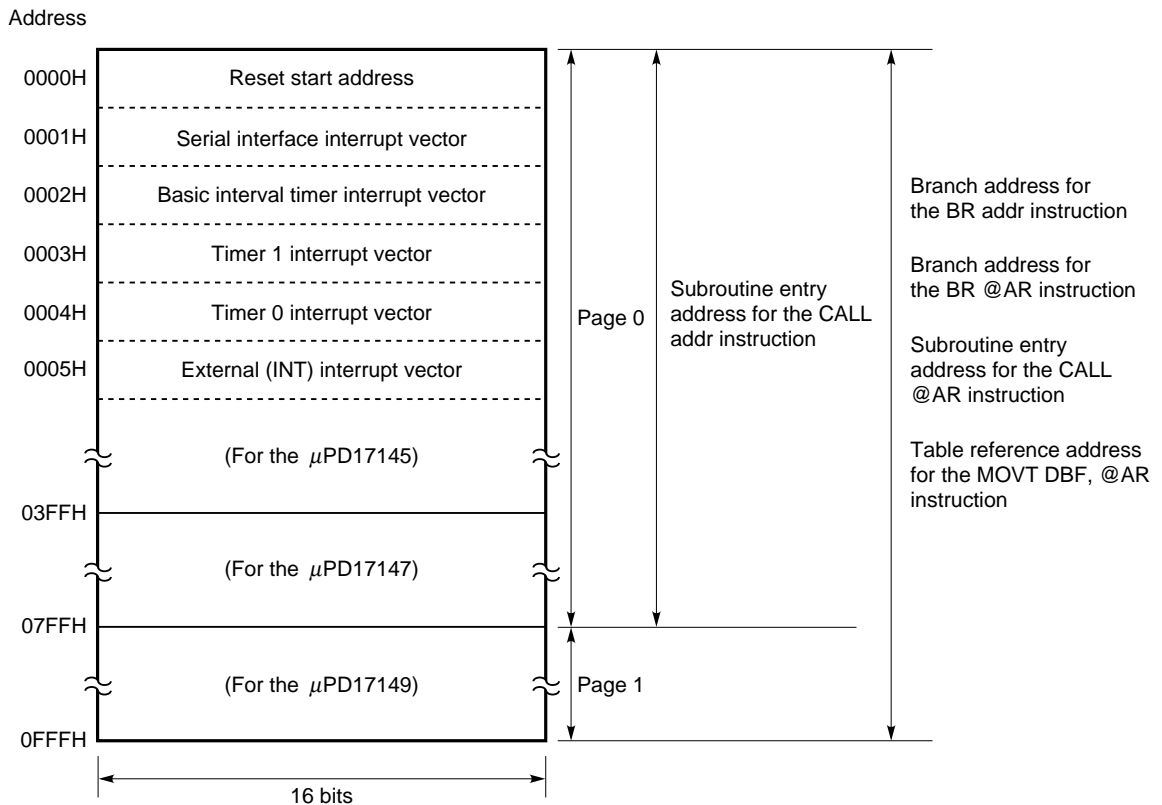
The reset start address and interrupt vector addresses are assigned to program memory 0000H to 0005H.

2.1 PROGRAM MEMORY CONFIGURATION

Fig. 2-1 shows the program memory map. A step consists of 16 bits of program memory. A 2K-step area is called a page.

Direct subroutine calls can specify address 0000H to 07FFH (page 0) in program memory. Branch instructions, indirect subroutine calls, and table references can specify any address in program memory (0000H - 0FFFH).

Fig. 2-1 Program Memory Map



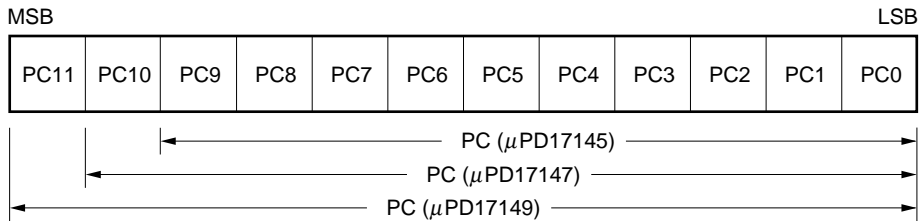
3. PROGRAM COUNTER (PC)

The program counter is used to specify an address in program memory.

3.1 PROGRAM COUNTER CONFIGURATION

As shown in Fig. 3-1, the program counter is a 10/11/12-bit binary counter.

Fig. 3-1 Program Counter



3.2 PROGRAM COUNTER OPERATION

Normally, the program counter is automatically incremented each time a command is executed. The memory address at which the next instruction to be executed is stored is assigned to the program counter under the following conditions: At reset; when a branch, subroutine call, return, or table referencing instruction is executed; or when an interrupt is received.

Fig. 3-2 Value of the Program Counter after an Instruction Is Executed

Instruction \ Program counter bit	Program counter value											
	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
During reset	0	0	0	0	0	0	0	0	0	0	0	0
BR addr	0	Value set by addr										
	1											
CALL addr	0											
BR @AR CALL @AR (MOVT DBF, @AR)	Value in the address register (AR)											
RET RETSK RETI	Value in the address stack location pointed to by the stack pointer (return address)											
During interrupt	Vector address for the interrupt											

Remark The μPD17145 does not have PC11 or PC10. The μPD17147 does not have PC11.

4. STACK

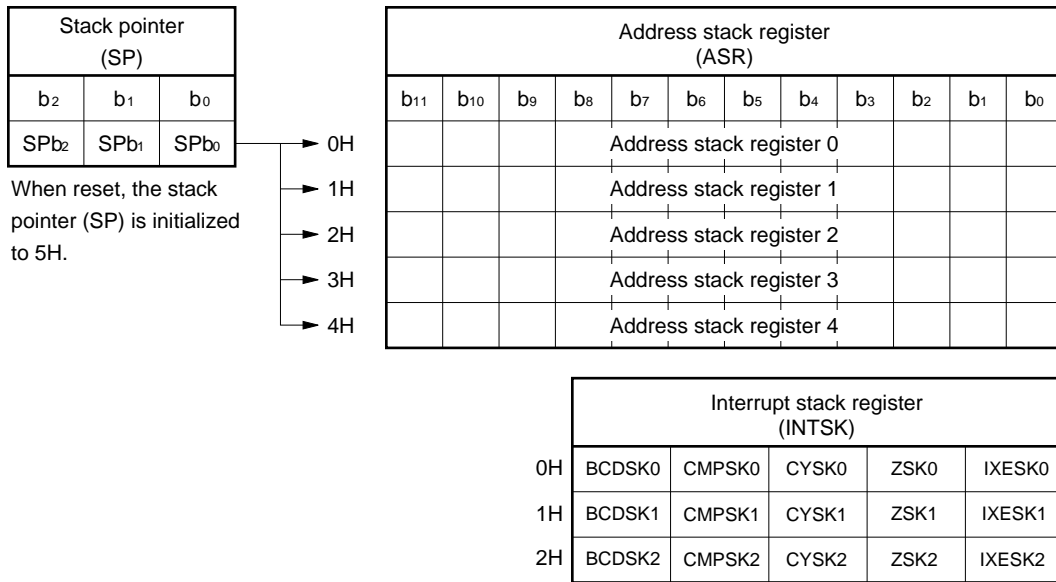
The stack is a register used to save information such as the program return address and the contents of the system register during execution of subroutine calls, interrupts and similar operations.

4.1 STACK CONFIGURATION

Fig. 4-1 shows the configuration of the stack.

The stack consists of the following parts: one 3-bit binary counter stack pointer (SP), five 10-bit (μPD17145)/11-bit (μPD17147)/12-bit (μPD17149) address stack registers (ASR), and three 5-bit interrupt stack registers (INTSK).

Fig. 4-1 Stack Configuration



4.2 FUNCTIONS OF THE STACK

The stack is used to save the return address during execution of subroutine calls and table reference instructions. When an interrupt occurs, the program return address and the program status word (PSWORD) are automatically saved in the stack. Then, all bits of the PSWORD are cleared to 0.

5. DATA MEMORY (RAM)

Data memory (RAM) stores data such as operation and control data. Data can be read from or written to data memory with an instruction during normal operation.

5.1 DATA MEMORY CONFIGURATION

Data memory locations have 7-bit addresses. The three high-order bits of each address are called the row address, and the four low-order bits are called the column address.

For example, the row address of address 1AH is 1H. The column address is 0AH.

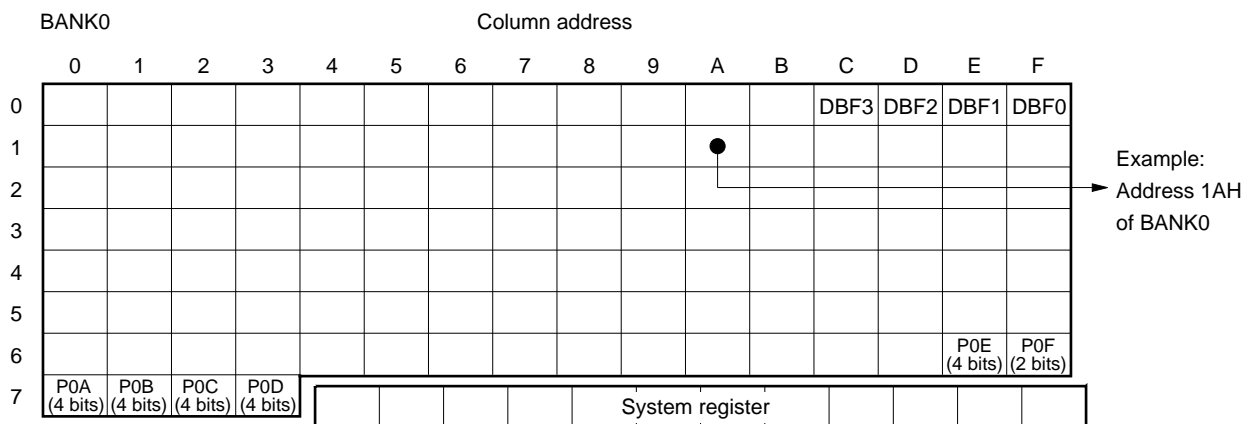
Each addressed memory location is 4-bits (one nibble) long.

Data memory contains an area to which the user is allowed to store data freely, as well as areas which are reserved for the use of specific functions.

The areas reserved for specific functions are as follows:

- System register (SYSREG) (See Chapter 7.)
- Data buffer (DBF) (See Chapter 9.)
- Port registers (See Chapter 11.)

Fig. 5-1 Organization of Data Memory



6. GENERAL REGISTER (GR)

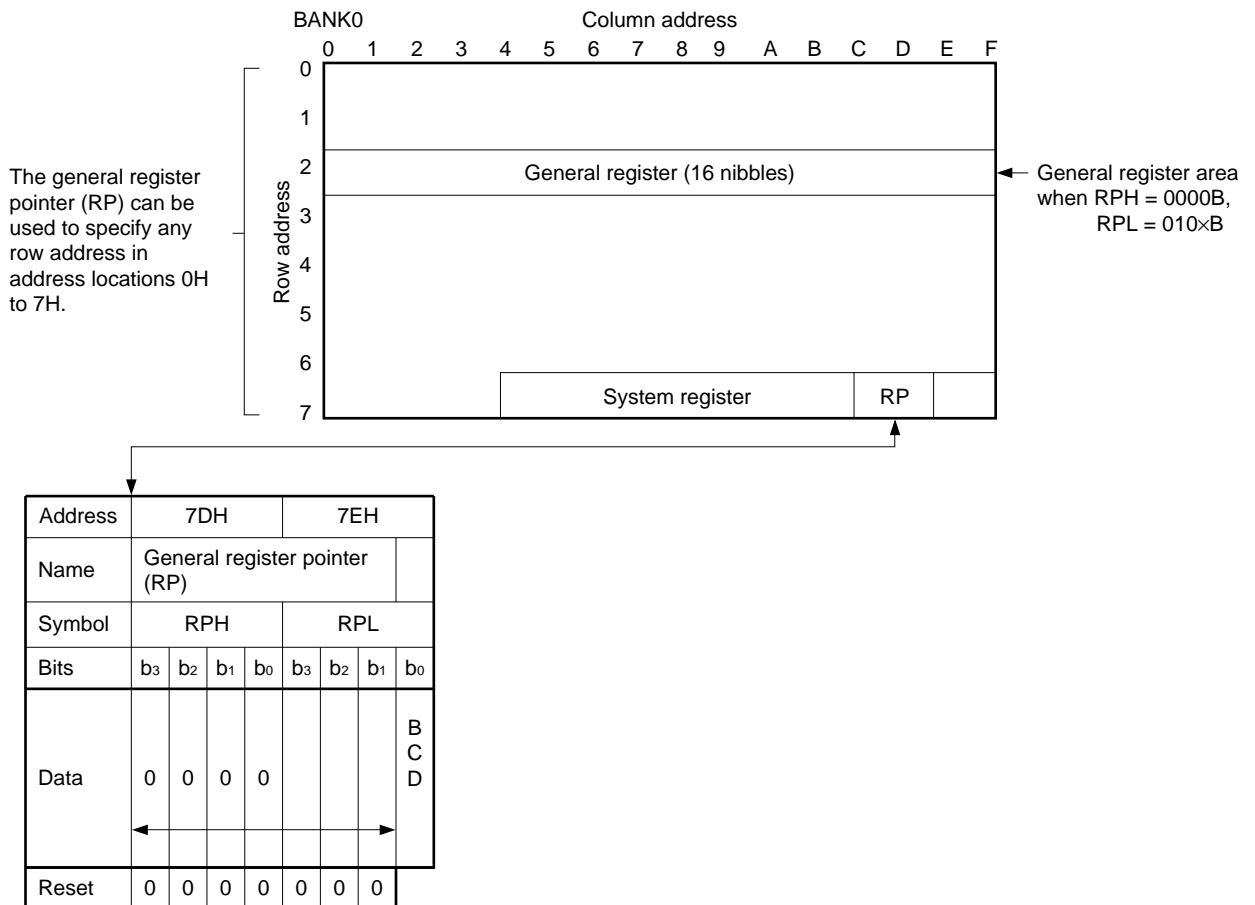
The general register, as the name implies, is a general register used for data transfer and manipulation. In the 17K series, the location of the general register is not fixed. The area used for the general register is in data memory, as specified by the general register pointer (RP). Thus, part of the data memory area can be specified as the general register as required, allowing data transfer in data memory and data memory manipulation to be performed with a single instruction.

6.1 GENERAL REGISTER POINTER (RP)

RP is a pointer used to specify part of data memory as the general register. In RP, specify a desired data memory bank and row address for the general register. RP consists of seven bits: 7DH (RPH), and the three high-order bits of 7EH (RPL) in the system register (see **Chapter 7**).

Set a bank in RPH, and a data memory row address in RPL.

Fig. 6-1 General Register Pointer Configuration



7. SYSTEM REGISTER (SYSREG)

The system register (SYSREG), located in data memory, is used for direct control of the CPU.

7.1 SYSTEM REGISTER CONFIGURATION

Fig. 7-1 shows the allocation address of the system register in data memory. As shown in Fig. 7-1, the system register is allocated in addresses 74H to 7FH of data memory.

Since the system register is allocated in data memory, it can be manipulated using any of the instructions available for manipulating data memory. Therefore, it is also possible to put the system register in the general register.

Fig. 7-1 Allocation of System Register in Data Memory

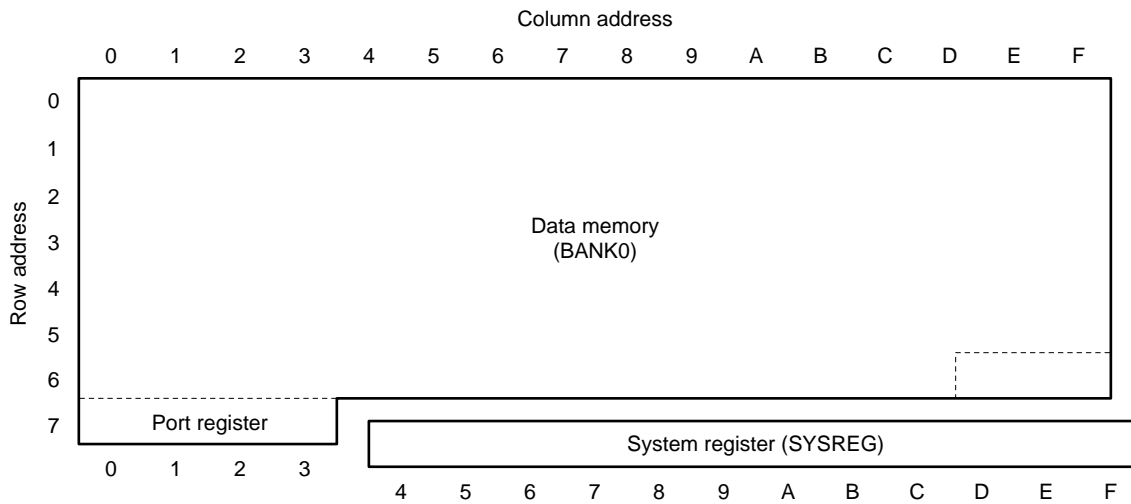


Fig. 7-2 shows the configuration of the system register. As shown in Fig. 7-2, the system register consists of the following seven registers.

- Address register (AR)
- Window register (WR)
- Bank register (BANK)
- Index register (IX)
- Data memory row address pointer (MP)
- General register pointer (RP)
- Program status word (PSWORD)

Fig. 7-2 System Register Configuration

Address	74H	75H	76H	77H	78H	79H	7AH	7BH	7CH	7DH	7EH	7FH
Name	Address register (AR)				Window register (WR)	Bank register (BANK)	Index register (IX) Data memory row address pointer (MP)			General register pointer (RP)	Program status word (PSWORD)	
Symbol	AR3	AR2	AR1	AR0	WR	BANK	IXH MPH	IXM MPL	IXL	RPH	RPL	PSW
Bit	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀
Data ^{Note 1}	0 0 0 0	Note 2 0 0 0 0				0 0 0 0	M P E	(IX) 0 0 0 0		0 0 0 0		B C D C M Y Z I X E
Initial value when re-set	0 0 0 0	0 0 0 0				0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0

- Notes**
1. A bit indicating zero is fixed to zero.
 2. Bit b₃ and b₂ of AR2 are always 0 for the μPD17145. Bit b₃ of AR2 is always 0 also for the μPD17147.

8. REGISTER FILE (RF)

The register file is a register used mainly for specifying conditions for peripheral hardware.

8.1 REGISTER FILE CONFIGURATION

8.1.1 Configuration of the Register File

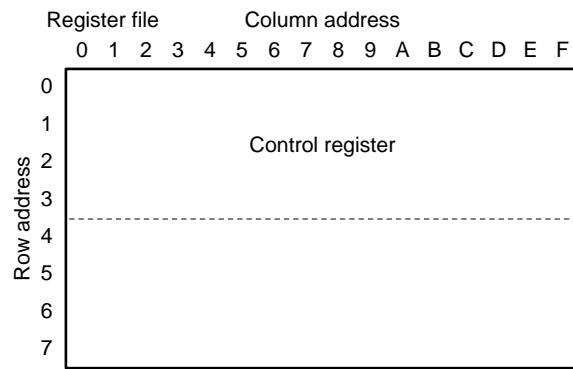
Fig. 8-1 shows the configuration of the register file.

As shown in Fig. 8-1, the register file is a register consisting of 128 nibbles (128 × 4 bits).

In the same way as with data memory, the register file is divided into addresses in units of four bits. It has a total of 128 nibbles specified in row addresses from 0H to 7H and column addresses from 0H to 0FH.

Address locations 00H to 3FH define an area called the control register.

Fig. 8-1 Register File Configuration



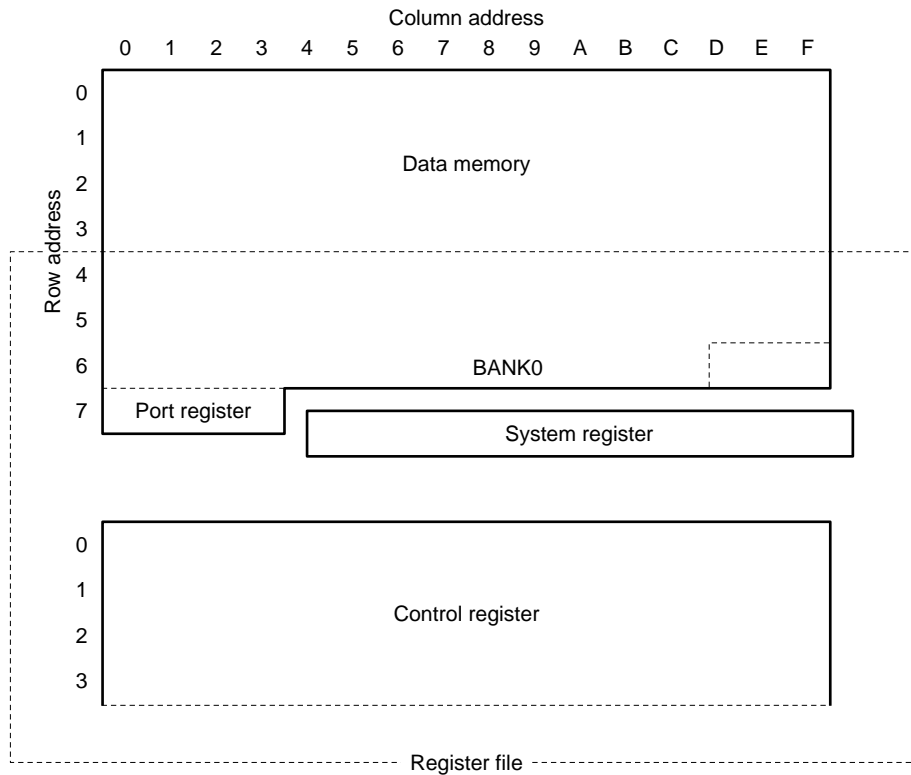
8.1.2 Relationship between the Register File and Data Memory

Fig. 8-2 shows the relationship between the register file and data memory.

As shown in Fig. 8-2, the register file overlaps with data memory at addresses 40H to 7FH.

This means that, on a program, it seems that the same memory exists in the register file at addresses 40H to 7FH and in the data memory at addresses 40H to 7FH.

Fig. 8-2 Relationship Between the Register File and Data Memory



8.2 FUNCTIONS OF THE REGISTER FILE

8.2.1 Functions of the Register File

The register file is a collection of registers in which peripheral hardware conditions are set with the PEEK instruction or POKE instruction.

The register used to control the peripheral hardware is located at addresses 00H to 3FH. This area is called the control register.

Addresses 40H to 7FH of the register file constitute normal data memory. Thus, not only the MOV instruction, but also the PEEK and POKE instructions, can be used to enable this part to perform read and write operations.

8.2.2 Control Register Functions

The peripheral hardware whose conditions can be controlled by control registers is listed below.

For details concerning peripheral hardware and the control register, see the section for the peripheral hardware concerned.

- Ports
- 8-bit timer counter (TM0, TM1)
- Basic interval timer (BTM)
- A/D converter
- Serial interface (SIO)
- Interrupt function
- Stack pointer (SP)

9. DATA BUFFER (DBF)

The data buffer consists of four nibbles allocated in addresses 0CH to 0FH in BANK0.

The data buffer acts as a data storage area for the CPU peripheral hardware (address register, serial interface, timer 0, timer 1, and A/D converter) through use of the GET and PUT instructions. It also acts as data storage used for receiving and transferring data. By using the MOVT DBF, @AR instruction, fixed data in program memory can be read into the data buffer.

9.1 DATA BUFFER CONFIGURATION

Fig. 9-1 shows the allocation of the data buffer in data memory.

As shown in Fig. 9-1, the data buffer is allocated in address locations 0CH to 0FH in data memory and consists of four nibbles (4 × 4 bits).

Fig. 9-1 Allocation of the Data Buffer

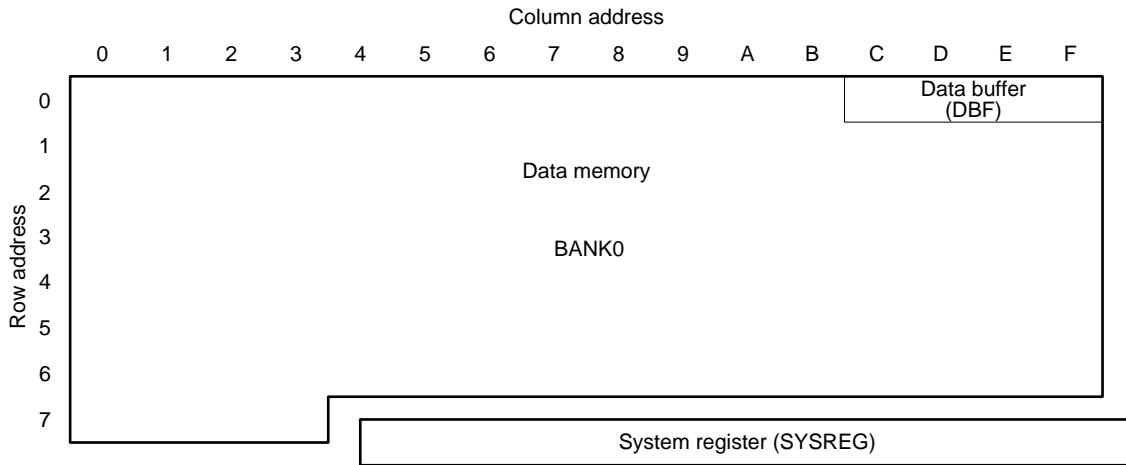


Fig. 9-2 shows the configuration of the data buffer. As shown in Fig. 9-2, the data buffer is made up of sixteen bits with its least significant bit in bit 0 of address 0FH and its most significant bit in bit 3 of address 0CH.

Fig. 9-2 Data Buffer Configuration

Data memory BANK0	Address	0CH				0DH				0EH				0FH			
	Bit	b ₃	b ₂	b ₁	b ₀	b ₃	b ₂	b ₁	b ₀	b ₃	b ₂	b ₁	b ₀	b ₃	b ₂	b ₁	b ₀
Data buffer	Bit	b ₁₅	b ₁₄	b ₁₃	b ₁₂	b ₁₁	b ₁₀	b ₉	b ₈	b ₇	b ₆	b ₅	b ₄	b ₃	b ₂	b ₁	b ₀
	Symbol	DBF3				DBF2				DBF1				DBF0			
	Data	^ M S B v				Data				^ L S B v							

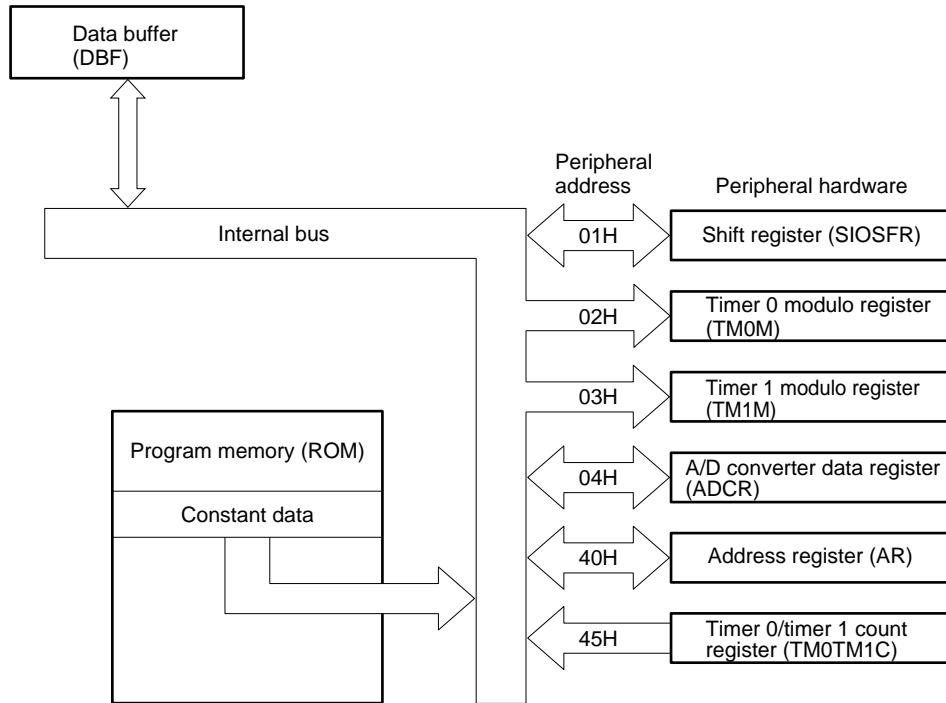
Because the data buffer is allocated in data memory, it can be used in any of the data memory manipulation instructions.

9.2 FUNCTIONS OF THE DATA BUFFER

The data buffer has two separate functions.

The data buffer is used for data transfer with peripheral hardware. The data buffer is also used for reading constant data in program memory. Fig. 9-3 shows the relationship between the data buffer and peripheral hardware.

Fig. 9-3 Relationship between the Data Buffer and Peripheral Hardware



10. ALU BLOCK

The ALU is used for performing arithmetic operations, logical operations, bit evaluations, comparison evaluations, and rotations on 4-bit data.

10.1 ALU BLOCK CONFIGURATION

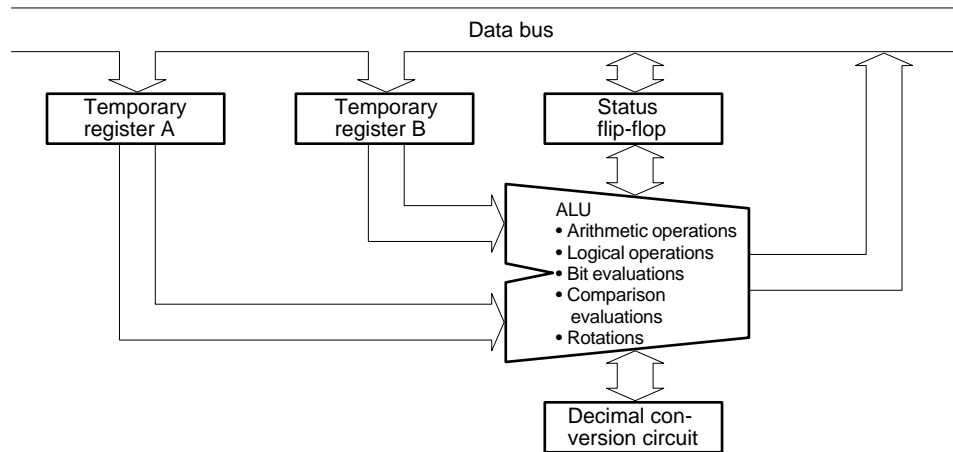
Fig. 10-1 shows the configuration of the ALU block.

As shown in Fig. 10-1, the ALU block consists of the main 4-bit data processor, temporary registers A and B, the status flip-flop for controlling the status of the ALU, and the decimal conversion circuit for use during arithmetic operations in BCD.

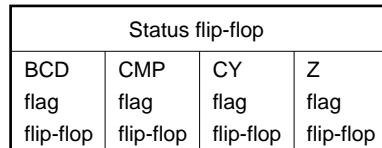
As shown in Fig. 10-1, the status flip-flop consists of the following flags: Zero flag flip-flop, carry flag flip-flop, compare flag flip-flop, and the BCD flag flip-flop.

Each flag in the status flip-flop corresponds directly to a flag in the program status word (PSWORD: addresses 7EH, 7FH) located in the system register. The flags in the program status word are the following: Zero flag (Z), carry flag (CY), compare flag (CMP), and the BCD flag (BCD).

Fig. 10-1 Configuration of the ALU



Address	7EH	7FH			
Name	Program status word (PSWORD)				
Bit	b ₀	b ₃	b ₂	b ₁	b ₀
Flag	BCD	CMP	CY	Z	IXE



Function outline	
Indicates when the result of an arithmetic operation is 0.	Z
Stores the borrow or carry from an arithmetic operation.	CY
Used to indicate whether to store the result of an arithmetic operation.	CMP
Used to indicate whether to perform decimal correction for arithmetic operations.	BCD

11. PORTS

11.1 PORT 0A (P0A₀, P0A₁, P0A₂, P0A₃)

Port 0A is a 4-bit input/output port with an output latch. It is mapped into address 70H of BANK0 in data memory. The output format is CMOS push-pull output.

Input or output can be specified in 4-bit units. Input/output is specified by P0AGIO (bit 0 at address 2CH) in the register file.

When P0AGIO is 0, each pin of port 0A is used as input port. If a read instruction is executed for the port register, pin statuses are read.

When P0AGIO is 1, each pin of port 0A is used as output port and the contents written in the output latch are output to pins. If a read instruction is executed when pins are output ports, the contents of the output latch, rather than pin statuses, are fetched.

Port 0A contains a software controlled pull-up resistor. P0AGPU (bit 0 at address 0CH) of the register file is used to determine whether port 0A contains the pull-up resistor. When P0AGPU is 1, all 4-bit pins are pulled up. If P0AGPU is 0, the pull-up resistor is not contained.

At reset, P0AGIO and P0AGPU are set to 0 and all P0A pins become input ports without a pull-up resistor. The contents of the port output latch are 0.

Table 11-1 Writing into and Reading from the Port Register (0.70H)

P0AGIO RF: 2CH, bit 0	Pin input/output	BANK0 70H	
		Write	Read
0	Input	Possible	P0A pin status
1	Output	Write to the P0A latch	Data in P0A latch

11.2 PORT 0B (P0B0, P0B1, P0B2, P0B3)

Port 0B is a 4-bit input/output port with an output latch. It is mapped into address 71H of BANK0 in data memory. The output format is CMOS push-pull output.

Input or output can be specified in 4-bit units. Input/output is specified by P0BGIO (bit 1 at address 2CH) in the register file.

When P0BGIO is 0, all pins of port 0B are used as input ports. If a read instruction is executed for the port register, pin statuses are read.

When P0BGIO is 1, all pins of port 0B are used as output ports. The contents written in the output latch are output to pins. If a read instruction is executed when pins are used as output ports, the contents of the output latch, rather than pin statuses, are fetched.

Port 0B contains a software controlled pull-up resistor. P0BGPU (bit 1 at address 0CH) is used to determine whether or not port 0B contains a pull-up resistor. When P0BGPU is 1, all 4-bit pins are pulled up. When P0BGPU is 0, a pull-up resistor is not contained.

At reset, P0BGIO and P0BGPU are 0 and all P0B pins are input ports without a pull-up resistor. The value of the port 0B output latch is 0.

Table 11-2 Writing into and Reading from the Port Register (0.71H)

P0BGIO RF: 2CH, bit 1	Pin input/output	BANK0 71H	
		Write	Read
0	Input	Possible	P0B pin status
1	Output	Write to the P0B latch	Data in P0B latch

11.3 PORT 0C (P0C0/ADC0, P0C1/ADC1, P0C2/ADC2, P0C3/ADC3)

Port 0C is a 4-bit input/output port with an output latch. It is mapped into address 72H of BANK0 in data memory. The output format is CMOS push-pull output.

Input or output can be specified bit-by-bit. Input/output can be specified by P0CBIO0 to P0CBIO3 (address 1CH) in the register file.

If P0CBIO_n is 0 (n = 0 to 3), the P0C_n pins are used as input port. If a data read instruction is executed for the port register, the pin statuses are read. If P0CBIO_n is 1 (n = 0 to 3), the P0C_n pins are used as output port and the contents written in the output latch are output to pins. If a read instruction is executed when pins are used as output ports, the contents of the latch, rather than pin statuses, are fetched.

At reset, P0CBIO0 to P0CBIO3 are 0 and all P0C pins are input ports. The contents of the port output latch are 0.

Port 0C can also be used as an analog input to the A/D converter. P0C0IDI to P0C3IDI (1BH address) in the register file are used to switch the port and analog input pin.

If P0C_nIDI is 0 (n = 0 to 3), the P0C_n/ADC_n pin functions as a port. If P0C_nIDI is 1 (n = 0 to 3), the P0C_n/ADC_n pin functions as the analog input pin for the A/D converter. If any bit of P0C_nIDI (n = 0 to 3) is 1, the P0F1/V_{REF} pin is used as the V_{REF} pin.

When using these pins for the analog input for the A/D converter, set P0C_nIDI to 1 for the pins to which analog voltage is input, immediately after reset. This setting disables the port function for the pins. Then clear P0CBIO_n (n = 0 to 3) to 0 to use the pins for input. Select which pins are used for analog input, using ADCCH0 and ADCCH1 (bits 0 and 1 at address 22H) in the register file.

At reset, P0CBIO0 to P0CBIO3, P0C0IDI to P0C3IDI, ADCCH0, and ADCCH1 are set to 0 and the P0C pins are used as input ports.

Table 11-3 Switching the Port and A/D Converter

(n = 0 to 3)

P0C _n IDI RF: 1BH	P0CBIO _n RF: 1CH	Function	BANK0 72H	
			Write	Read
0	0	Input port	Possible P0C latch	Pin status
	1	Output port	Possible P0C latch	Data in P0C latch
1	0	A/D converter analog input ^{Note 1}	Possible P0C latch	Data in P0C latch
	1	Output port and A/D converter analog input ^{Note 2}	Possible P0C latch	Data in P0C latch

Notes 1. Normal setting when the pins are used as A/D converter analog input pins.

★ 2. Functions as an output port. The analog input voltage is changed by the output from the port. To use the pins for analog input, be sure to set P0CBIO_n to 0.

11.4 PORT 0D (P0D0/ $\overline{\text{SCK}}$, P0D1/SO, P0D2/SI, P0D3/ $\overline{\text{TM1OUT}}$)

Port 0D is a 4-bit input/output port with an output latch. It is mapped into address 73H of BANK0 in data memory. The output format is N-ch open-drain output.

Input or output can be specified bit-by-bit. Input/output is specified with P0DBIO0 to P0DBIO3 (address 2BH) in the register file.

If P0DBIO_n is 0 (n = 0 to 3), the P0D_n pins are used as input port. Pin statuses are read if a data read instruction is executed for the port register. If P0DBIO_n is 1, the P0D_n pins are used as output port and the value written in the output latch are output to pins. If a data read instruction is executed when pins are used as output ports, the output latch value, rather than pin statuses, is fetched.

Port 0D contains a software controlled pull-up resistor. P0DBPU0 to P0DBPU3 (address 0DH) of the register file are used to determine whether each bit of port 0D contains the pull-up resistor. When P0DBPU_n is 1, the P0D_n pin is pulled up. If P0DBPU_n is 0, the pull-up resistor is not contained.

At reset, P0DBIO_n is set to 0 and all P0D pins become input ports. The contents of the port output latch become 0. The output latch contents remain unchanged even if P0DBIO_n changes from 1 to 0.

Port 0D can also be used for serial interface input/output or timer 1 output. SIOEN (0BH bit 0) in the register file is used to switch ports (P0D₀ to P0D₂) to serial interface input/output ($\overline{\text{SCK}}$, SO, SI) and vice versa. TM1OSEL (bit 3 at address 0BH) in the register file is used to switch a port (P0D₃) to timer 1 output ($\overline{\text{TM1OUT}}$) and vice versa. If TM1OSEL = 1 is selected, 1 is output at timer 1 reset. This output is inverted every time a timer 1 count value matches the modulo register contents.

Table 11-4 Register File Contents and Pin Functions

(n = 0 to 3)

Register file value			Pin function			
TM1OSEL RF: 0BH Bit 3	SIOEN RF: 0BH Bit 0	P0DBIO _n RF: 2BH Bit n	P0D ₀ / $\overline{\text{SCK}}$	P0D ₁ /SO	P0D ₂ /SI	P0D ₃ / $\overline{\text{TM1OUT}}$
0	0	0	Input port			
		1	Output port			
	1	0	$\overline{\text{SCK}}$	SO	SI	Input port
		1				Output port
1	0	0	Input port			
		1	Output port			
	1	0	$\overline{\text{SCK}}$	SO	SI	$\overline{\text{TM1OUT}}$
		1				

Table 11-5 Data Read from the Port Register (0.73H)

Port mode		Data read from the port register (0.73H)
Input port		Pin status
Output port		Data in output latch
$\overline{\text{SCK}}$	An internal clock is selected as a serial clock.	Data in output latch
	An external clock is selected as a serial clock.	Pin status
SI		Pin status
SO		Data in output latch
$\overline{\text{TM1OUT}}$		Data in output latch

11.5 PORT 0E (P0E0, P0E1, P0E2, P0E3)

Port 0E is a 4-bit input/output port with an output latch. It is mapped into address 6EH of BANK0 in data memory. The output format is N-ch open-drain output.

Input or output can be specified in units of four bits. Input/output is specified by P0EGIO (bit 2 at address 2CH) in the register file.

When P0EGIO is 0, each pin of port 0E is used as input port. If a read instruction is executed for the port register, pin statuses are read. When P0EGIO is 1, each pin of port 0E is used as output port and the contents written in the output latch are output to pins. If a read instruction is executed when pins are output ports, the contents of the output latch, rather than pin statuses, are fetched.

Port 0E contains a software controlled pull-up resistor. P0EGPU (bit 2 at address 0CH) of the register file is used to determine whether port 0E contains the pull-up resistor. When P0EGPU is 1, all 4-bit pins are pulled up. If P0EGPU is 0, the pull-up resistor is not contained.

At reset, P0EGIO is set to 0 and all P0E pins become input ports. The contents of the port output latch are 0.

Table 11-6 Writing into and Reading from the Port Register (0.6EH)

(n = 0 to 3)

P0EGIO _n RF: 2CH, bit 2	Pin input/output	BANK0 6EH	
		Write	Read
0	Input	Possible	P0E pin status
1	Output	Write to the P0E latch	Data in P0E latch

11.6 PORT 0F (P0F0/ $\overline{\text{RLS}}$, P0F1/ V_{REF})

Port 0F is a 2-bit input-dedicated port. It is mapped into address 6FH of BANK0 in data memory. Mask option can be used to specify whether each pin uses a built-in pull-up resistor.

If a pin of port 0F is used as an input port, a pin status is read in the two low-order bits of the port register when a data read instruction is executed for the port register (the two high-order bits are always 0). A data write instruction does not affect the port register.

The P0F0/ $\overline{\text{RLS}}$ pin can also be used for the input pin for the signal for releasing the standby mode.

The P0F1/ V_{REF} pin is used as the V_{REF} pin (reference voltage input pin for the A/D converter) when any bit of P0CnIDI (address 1BH in the register file, n = 0 to 3) is 1. If the P0F1/ V_{REF} pin functions as the V_{REF} pin, bit 1 at address 6FH is always 0 when a data read instruction is executed for the port register.

12. 8-BIT TIMER COUNTER (TM0, TM1)

Timer 0 (TM0) and timer 1 (TM1) are available as 8 bit-timer counters of the μ PD17149. By using the timer 0 counting signal as the timer 1 count clock, these two 8-bit counters can be used as one 16-bit timer.

The timers are controlled by hardware operation with the PUT/GET instruction or by register operation in the register file with the PEEK/POKE instruction.

12.1 CONFIGURATION OF 8-BIT TIMER COUNTERS

Fig. 12-1 shows the configuration of the 8-bit timer counters. An 8-bit timer counter consists of an 8-bit counter register, 8-bit modulo register, comparator (compares counter register values and modulo register values), and selector (for count pulse selection).

Cautions 1. The modulo register is a write-only register.

2. The count register is a read-only register.

Fig. 12-1 Configuration of the 8-Bit Timer Counters

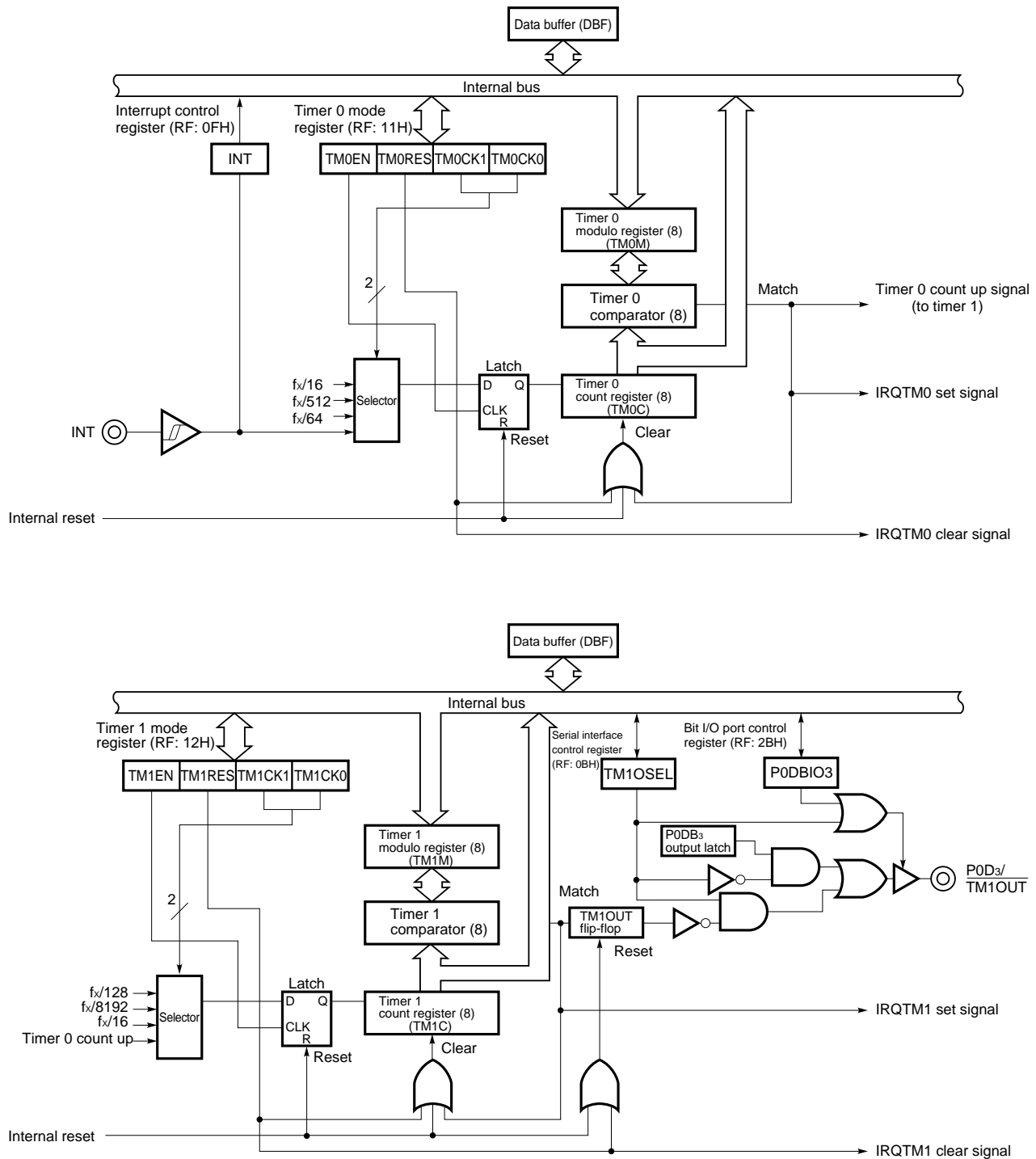


Fig. 12-2 Timer 0 Mode Register

RF: 11H

	Bit 3	Bit 2	Bit 1	Bit 0
	TM0EN	TM0RES	TM0CK1	TM0CK0
Read/write	R/W			
Initial value when reset	0	0	0	0

Read = R, write = W

TM0CK1	TM0CK0	Select the count pulse of timer 0.
0	0	$f_x/16$
0	1	$f_x/512$
1	0	$f_x/64$
1	1	INT pin

TM0RES	Controls whether to reset timer 0.
0	No effect on timer 0
1	The timer 0 count register and IRQTM0 are reset.

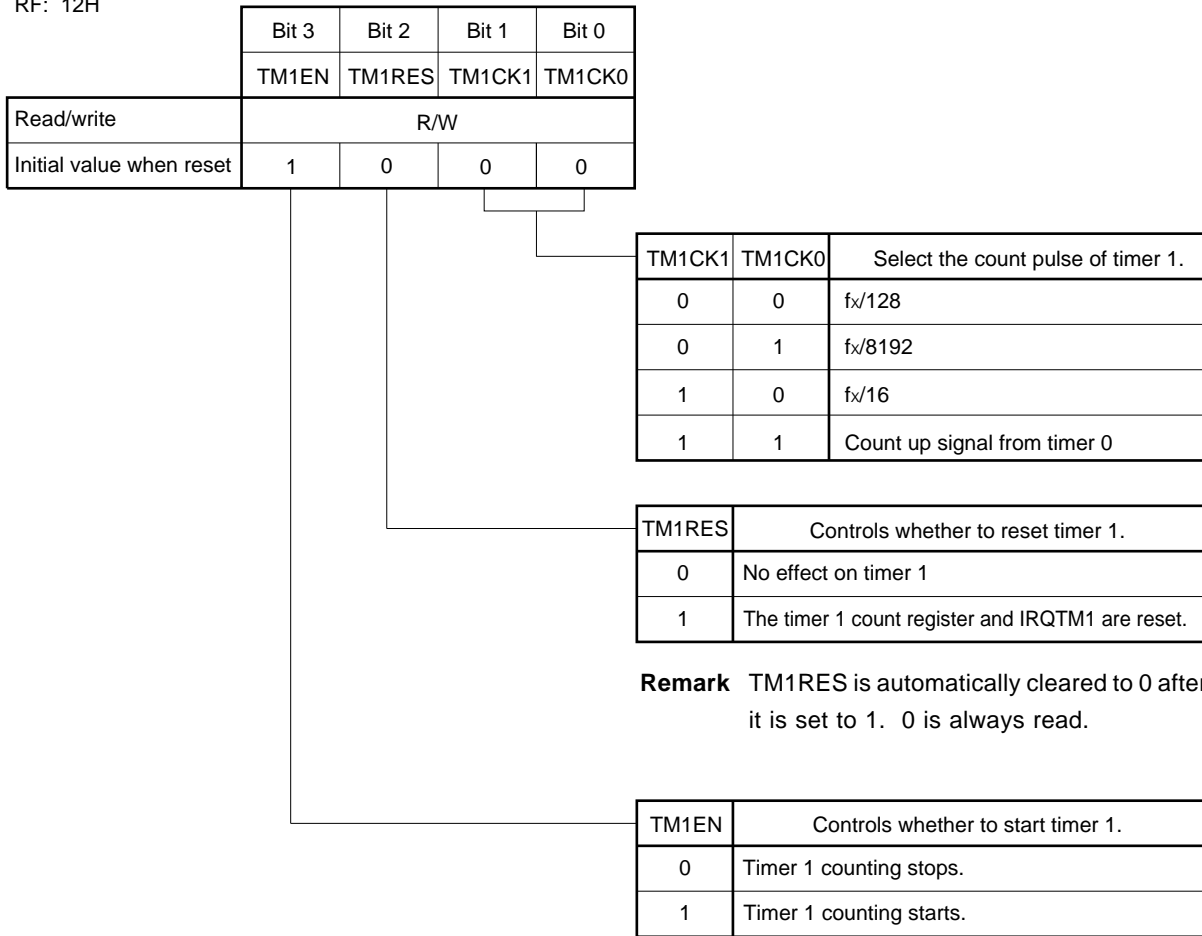
Remark TM0RES is automatically cleared to 0 after it is set to 1. 0 is always read.

TM0EN	Controls whether to start timer 0.
0	Timer 0 counting stops.
1	Timer 0 counting starts.

Remark TM0EN can be used as a status flag for detecting the counting status of timer 0. (1: Counting, 0: Not counting)

Fig. 12-3 Timer 1 Mode Register

RF: 12H



13. BASIC INTERVAL TIMER (BTM)

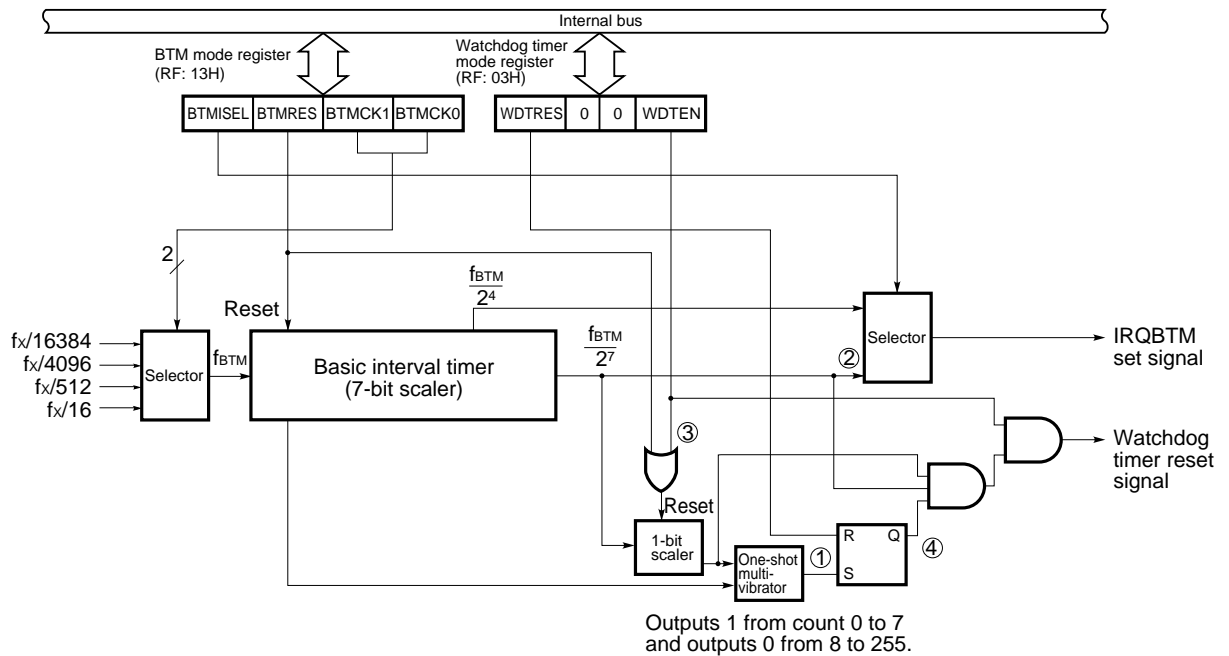
The μPD17149 provides a 7-bit basic interval timer. This timer has the following functions:

- (1) Reference time generation
- (2) Selection and counting of a wait time when standby mode is released
- (3) Watchdog timer operation for detecting software errors (infinite loops, etc.)

13.1 CONFIGURATION OF THE BASIC INTERVAL TIMER

Fig. 13-1 shows the configuration of the basic interval timer.

Fig. 13-1 Configuration of the Basic Interval Timer



Remark ① to ④ in the figure indicate the signals in the timing chart in Fig. 13-4.

13.2 REGISTERS FOR CONTROLLING THE BASIC INTERVAL TIMER

The basic interval timer is controlled by the BTM mode register and watchdog timer mode register. Fig. 13-2 and 13-3 show the configurations of the registers.

Fig. 13-2 BTM Mode Register

RF: 13H

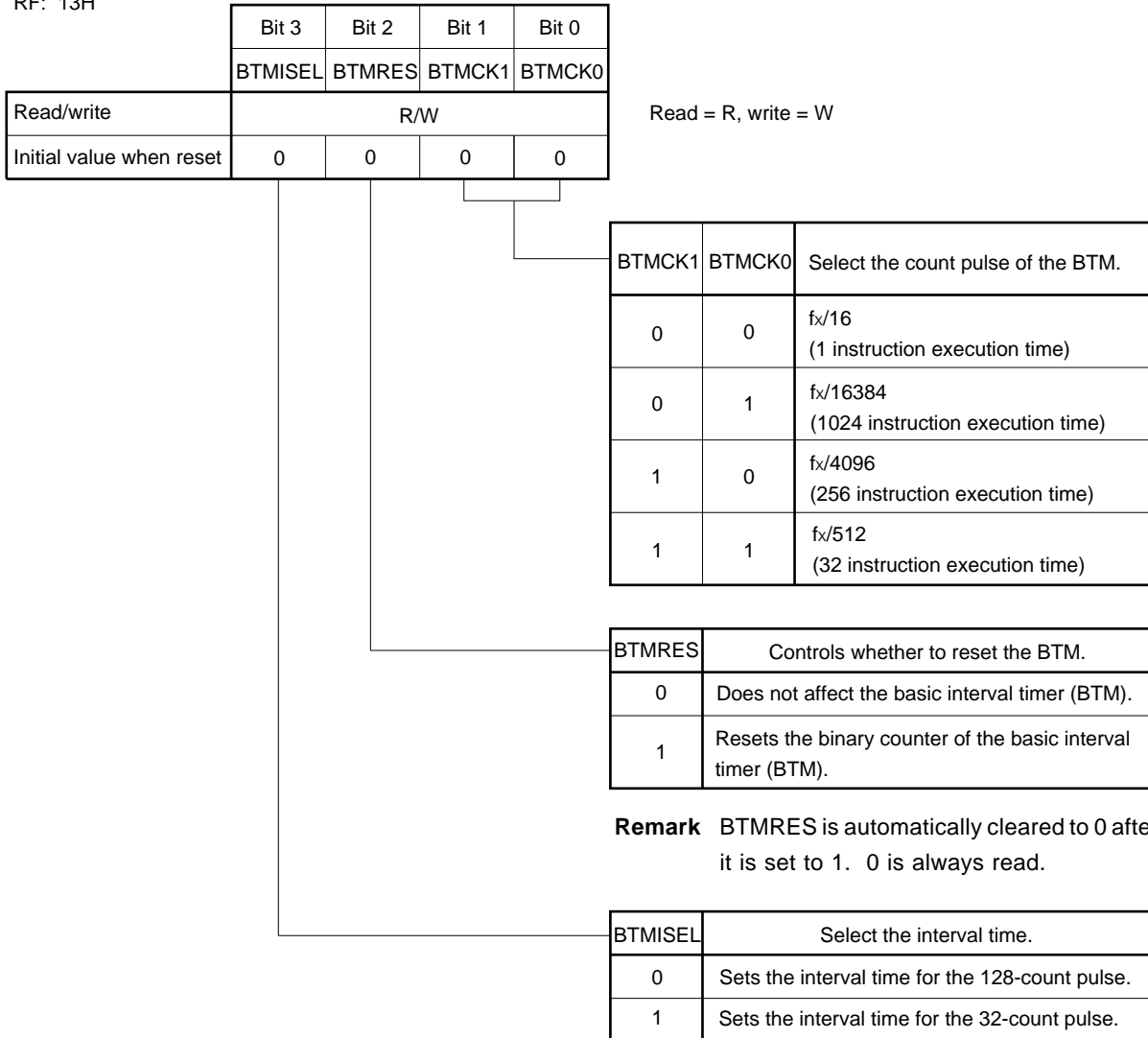


Fig. 13-3 Watchdog Timer Mode Register

RF: 03H

	Bit 3	Bit 2	Bit 1	Bit 0
	WDTRES	0	0	WDTEN
Read/write	R/W			
Initial value when reset	0	0	0	0

Read = R, write = W

WDTEN	Controls wheter to enable the watchdog timer function.
0	Puts the watchdog timer in stop status.
1	Starts watchdog timer operation.

- Remarks**
1. WDTEN cannot be cleared to 0 by the program.
 2. WDTEN is automatically cleared to 0 after it is set to 1. 0 is always read.

WDTRES	Controls wheter to reset the watchdog timer.
0	Does not affect the watchdog timer.
1	Resets the flip-flop used to retain a BTM overflow carry used for the watchdog timer.

Remark WDTRES is automatically cleared to 0 after it is set to 1. 0 is always read.

13.3 WATCHDOG TIMER FUNCTION

The basic interval timer can also be used as a watchdog timer which detects a system hang.

13.3.1 Overview of the Watchdog Timer

The watchdog timer is a counter that generates a reset signal at constant intervals. When the generation of a reset signal is being disabled every time by the program, this function enables the system to be reset (starting from address 0000H) when the system hangs up (the watchdog timer is not reset within the expected time) for some reason, such as due to external noise.

Even if a program branches to an unexpected routine due to external noise and enters an infinite loop, the system can be recovered within a certain time by the reset signal that is generated by the watchdog timer.

13.3.2 Operation of the Watchdog Timer

If 1 is written in the WDTEN flag, the 1-bit scaler starts operating, causing the basic interval timer to operate as an 8-bit watchdog timer.

Once the watchdog timer runs, the watchdog timer function can be stopped only when the device is reset and WDTEN is cleared to 0.

★ A reset by the watchdog timer can be disabled in the following two ways:

- (1) Repeating WDTRES setting in the program
- (2) Repeating BTMRES setting in the program

For (1), it is necessary to set WDTRES while the watchdog timer count is between 8 and 191 (immediately before 192), as shown in Fig. 13-4. Therefore, the program must be written so that SET1 WDTRES is executed at least once in a shorter period than that required for the watchdog timer count to reach 184.

For (2), it is necessary to set BTMRES before the basic interval timer (BTM) counts to reach 128. Therefore, the program must be written so that SET1 BTMRES is executed at least once in a shorter period than that required for the basic interval timer count to reach 128. However, using this method, interrupt handling by the basic interval timer is disabled.

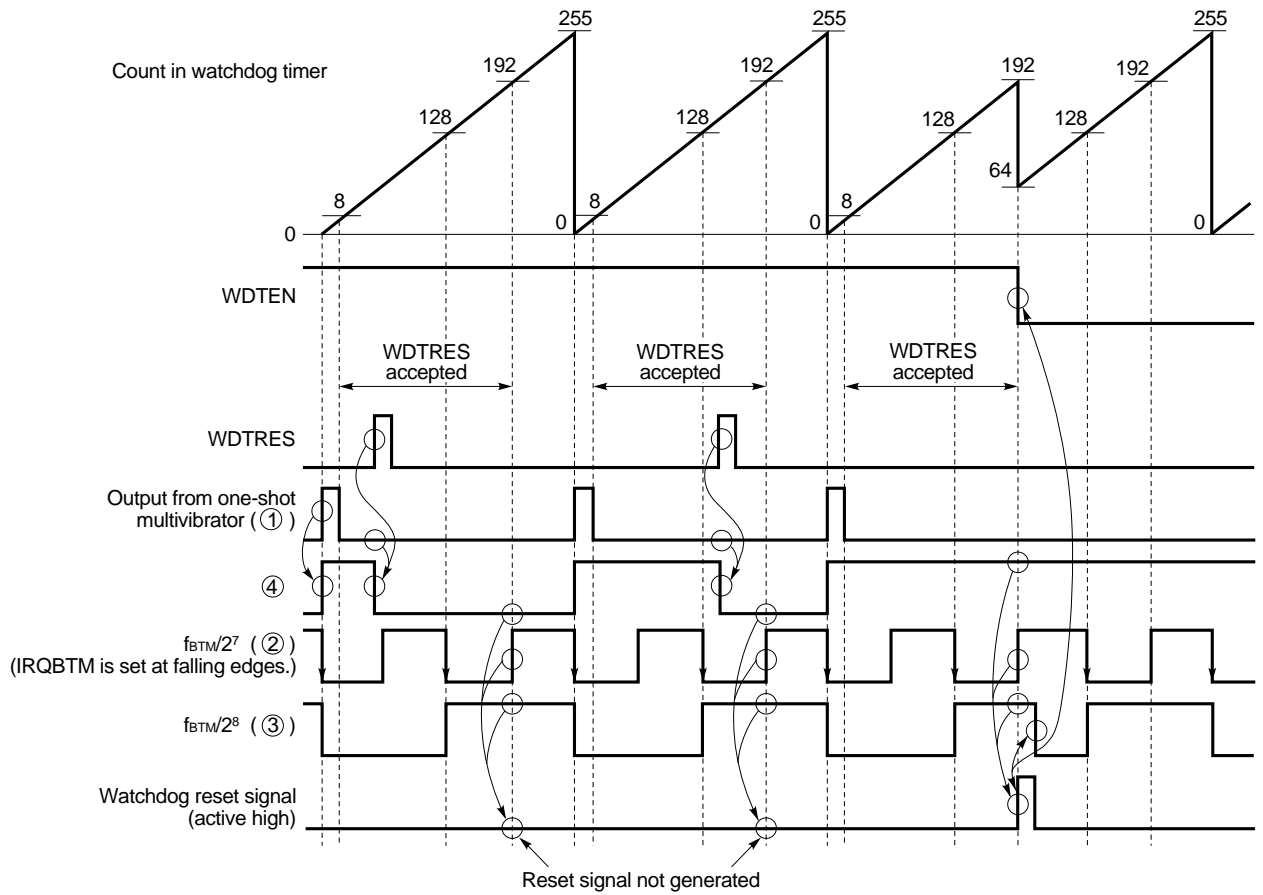
Caution Setting WDTEN does not reset the basic interval timer. So, set BTMRES before setting WDTEN, to reset the basic interval timer.

Example

```

SET1  ⋮  BTMRES
SET2  ⋮  WDTEN, WDTRES
      ⋮
    
```

Fig. 13-4 Timing Chart for the Watchdog Timer (When the WDTRES Flag is Used)



14. A/D CONVERTER

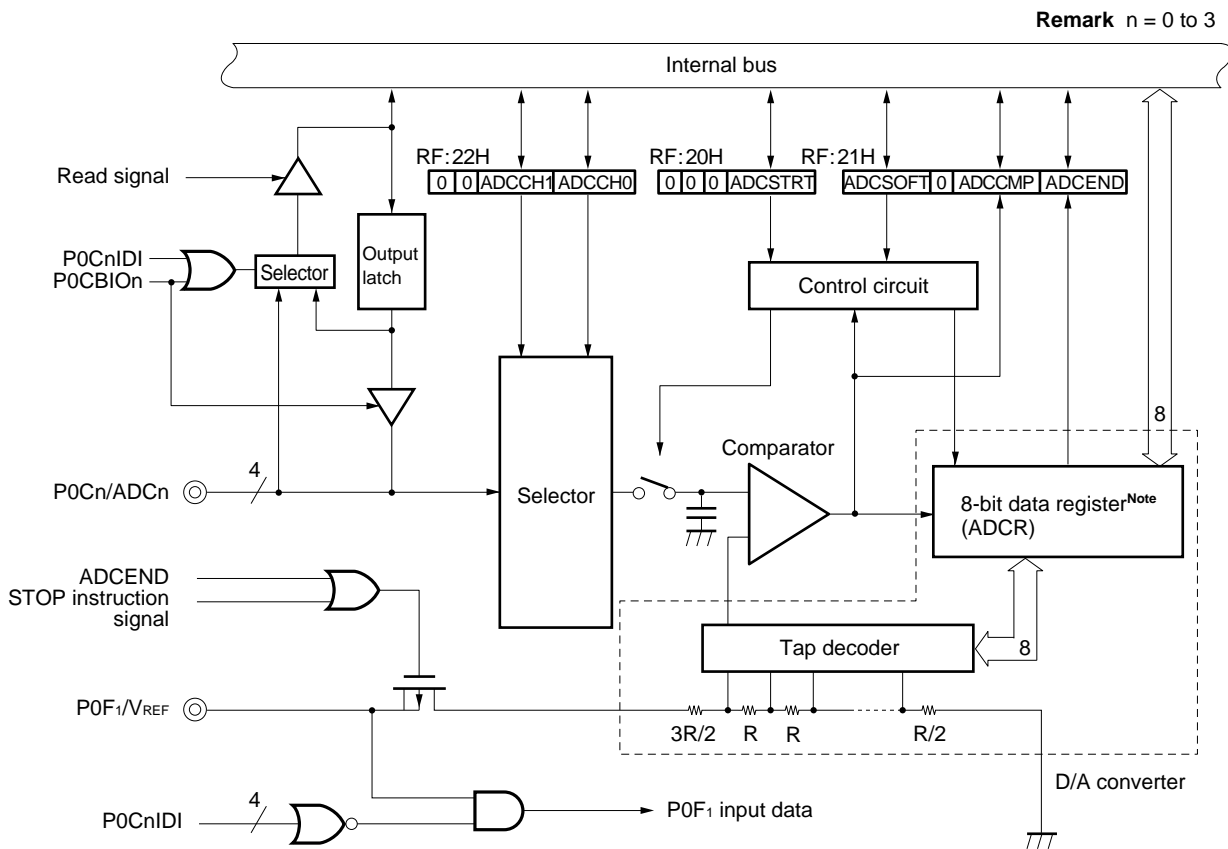
μPD17149 contains an 8-bit resolution A/D converter with 4-channel analog input (P0C0/ADC0 - P0C3/ADC3). The A/D converter uses the successive approximation method. The following two operation modes are available:

- ① Continuous mode: 8-bit A/D conversion occurs starting at high-order bits.
- ② Single mode: Comparison occurs with an arbitrary voltage value set in the 8-bit data register.

14.1 A/D CONVERTER CONFIGURATION

Fig. 14-1 shows the A/D converter configuration.

Fig. 14-1 Block Diagram for the A/D Converter



Note The 8-bit data register (ADCR) is cleared to 00H at the execution of STOP instruction.

14.2 A/D CONVERTER FUNCTIONS

(1) ADC₀ - ADC₃ pins

These pins are used to input 4-channel analog voltage to the A/D converter. The A/D converter contains a sample hold circuit. Analog input voltage is internally retained during A/D conversion.

(2) V_{REF} pin

This pin is used to input the reference voltage for the A/D converter.

A signal input to ADC₀ to ADC₃ is converted to a digital signal based on voltage applied across V_{REF} and GND. To reduce the current consumption of the microcontroller, the A/D converter has a function for automatically stopping the current which flows into the V_{REF} pin when the converter is not operating. Current flows into the V_{REF} pin in the following cases.

① **Continuous mode (ADCSOFT = 0)**

From when the ADCSTRT flag is set (1) until the ADCEND flag is set (1).

② **Single mode (ADCSOFT = 1)**

From when the ADCSTRT flag is set (1) or from when a value of the 8-bit data register is written until the result of comparison by the comparator is written in the ADCCMP flag.

Remarks 1. When the HALT instruction is executed during the A/D conversion, the A/D converter operates until the ADCEND flag is set in continuous mode or until the result of comparison is saved in the ADCCMP flag in single mode. A current flows into the V_{REF} pin while the A/D converter is operating.

2. The A/D conversion stops when the STOP instruction is executed. The A/D converter is initialized and a current does not flow into the V_{REF} pin. The A/D converter remains stopped after the STOP mode is released.

(3) 8-bit data register (ADCR)

In the continuous mode, this 8-bit data register stores A/D conversion results for successive approximation. It is read by the GET instruction. In the single mode, the data in this register is converted to analog voltage by the internal D/A converter and the comparator compares this voltage with an analog signal input from the ADC_n pin. A value can be written in this register by using the PUT instruction.

(4) Comparator

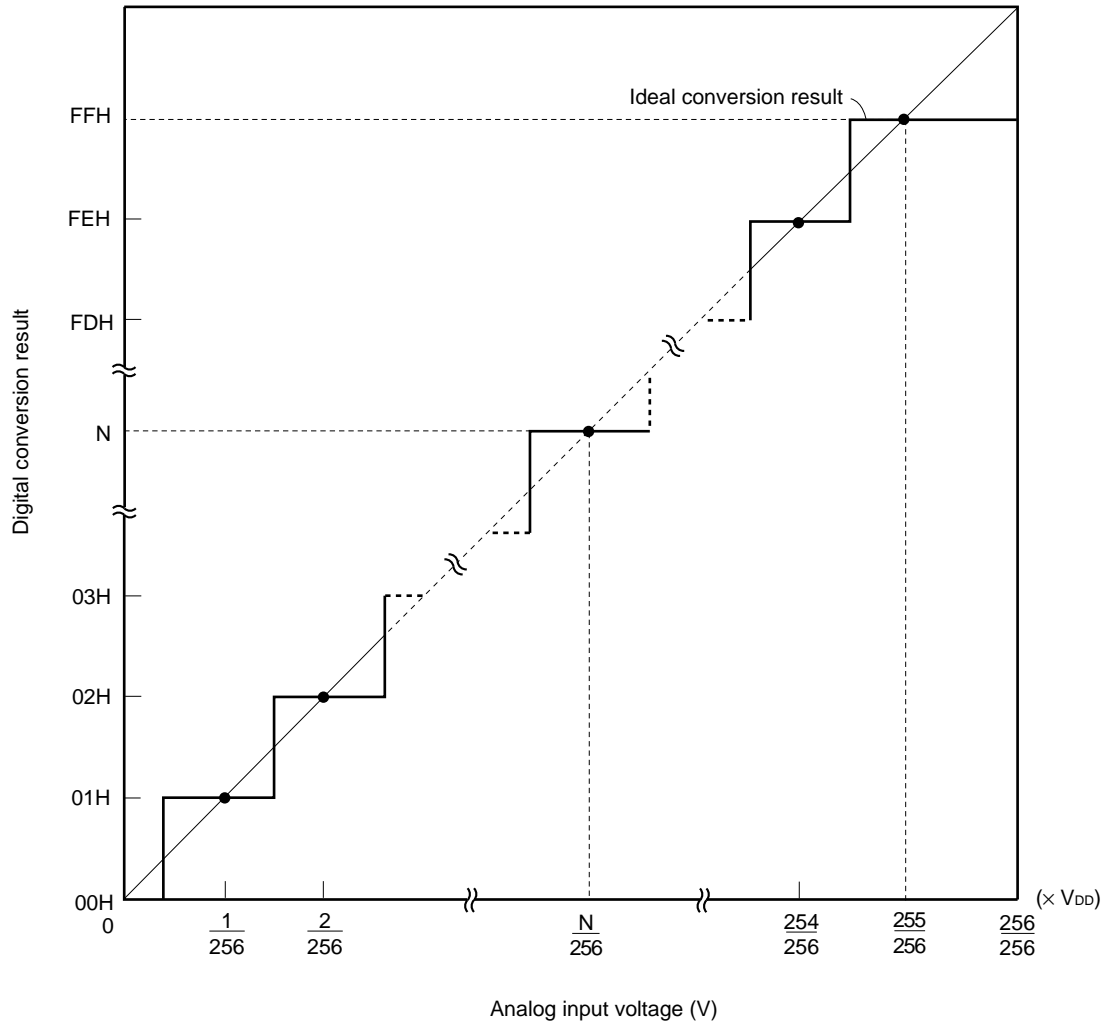
The comparator compares an analog input voltage with voltage output from the D/A converter. Value 1 is output if analog input voltage is higher. Value 0 is output if this voltage is lower. The comparison result is stored in the 8-bit data register (ADCR) in the continuous mode. It is stored in the ADCCMP flag in the single mode.

14.3 A/D CONVERTER OPERATION

The A/D converter operates in two modes: continuous mode and single mode. The mode can be switched by setting the ADCSOFT flag.

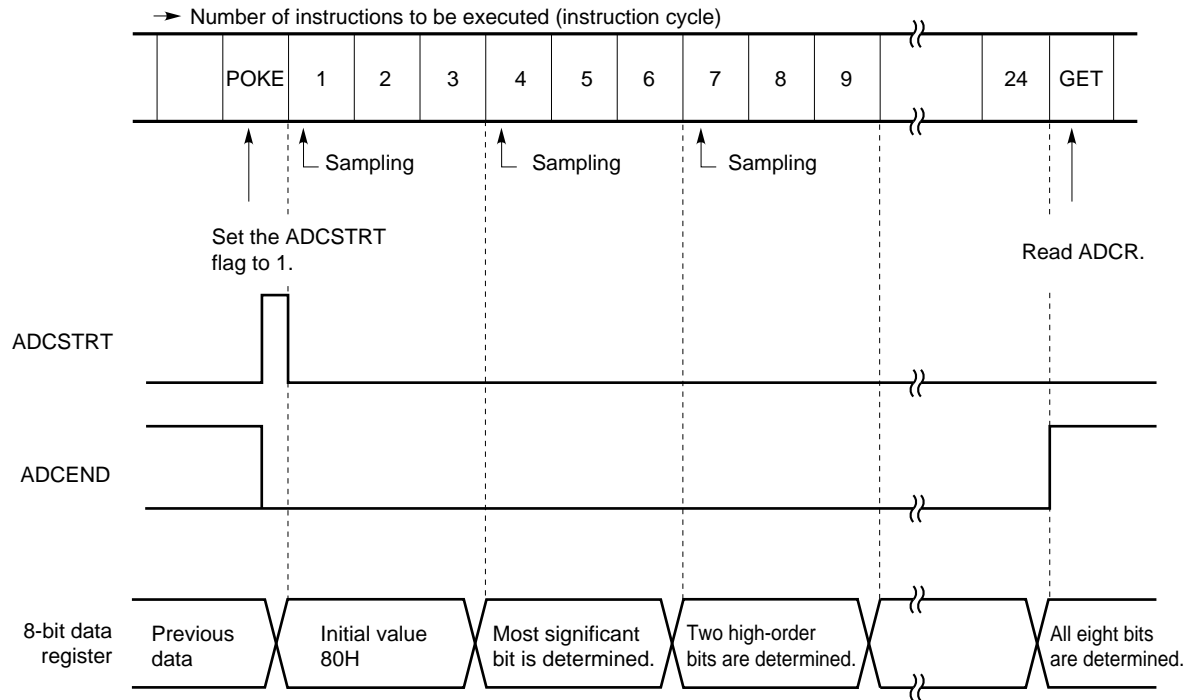
ADCSOFT	A/D converter operation mode
0	Continuous mode (A/D conversion)
1	Single mode (comparison)

Fig. 14-2 Relation between the Analog Input Voltage and Digital Conversion Result



★ (1) Timing in the continuous mode operation (A/D conversion)

Fig. 14-3 Timing in the Continuous Mode Operation (A/D Conversion)

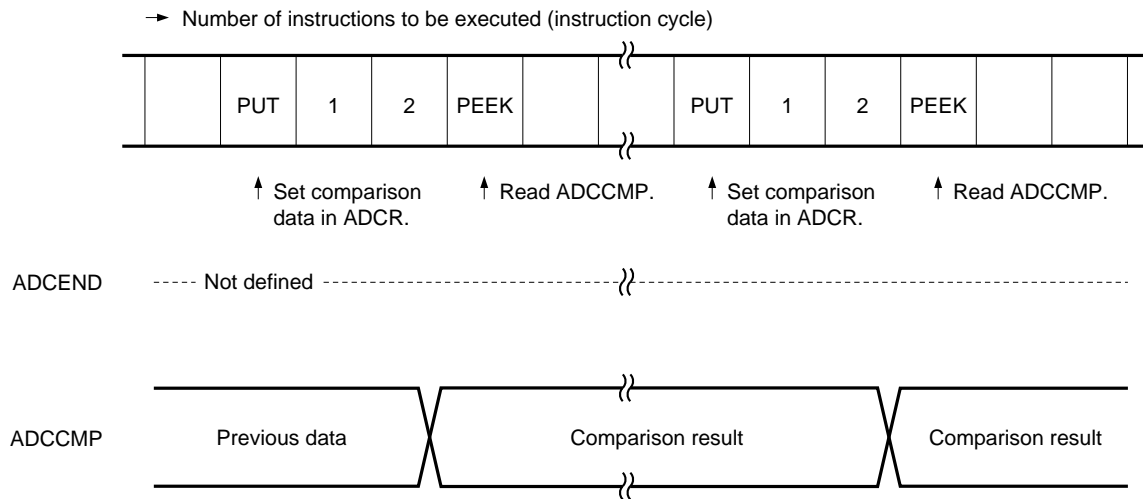


Caution Sampling is performed eight times for each A/D conversion. If the analog input voltage changes considerably during A/D conversion, accurate A/D conversion cannot be performed. To obtain accurate conversion, minimize any change in the analog input voltage during A/D conversion.

Remark Time required for one sampling operation = $14/f_x$ ($1.75 \mu\text{s}$, at $f_x = 8 \text{ MHz}$)
 Sampling cycle period = $48/f_x$ ($6 \mu\text{s}$, at $f_x = 8 \text{ MHz}$)

★ (2) Timing in the single mode operation (comparison)

Fig. 14-4 Timing in the Single Mode Operation (Comparison)



After data is set in ADCR (using the PUT instruction), the comparison result can be read after three instruction cycles.

Caution Before setting a value in ADCR, always set ADCSOFT to 1.
 If ADCSOFT = 0, no value can be set in ADCR.
 The PUT ADCR, DBF instruction is ineffective.

Remark Time required for sampling operation = $14/f_x$ (1.75 μs, at $f_x = 8$ MHz)

15. SERIAL INTERFACE (SIO)

The serial interface of the μPD17149 consists of an 8-bit shift register (SIOSFR), serial mode register, and serial clock counter. It is used for serial data input/output.

15.1 FUNCTIONS OF THE SERIAL INTERFACE

This serial interface provides three signal lines: serial clock input pin ($\overline{\text{SCK}}$), serial data output pin (SO), and serial data input pin (SI). It allows 8 bits to be sent or received in synchronization with clocks. It can be connected to peripheral input/output devices using any method with a mode compatible to that used by the μPD7500 or 75X series.

(1) Serial clock

Three types of internal clocks and one type of external clock are able to be selected. If an internal clock is selected as a serial clock, it is automatically output to the P0D0/ $\overline{\text{SCK}}$ pin.

★

Table 15-1 Serial Clock

SIOCK1	SIOCK0	Serial clock to be selected
0	0	External clock input to the SCK pin
0	1	$f_x/16$
1	0	$f_x/128$
1	1	$f_x/1024$

(2) Transmission operation

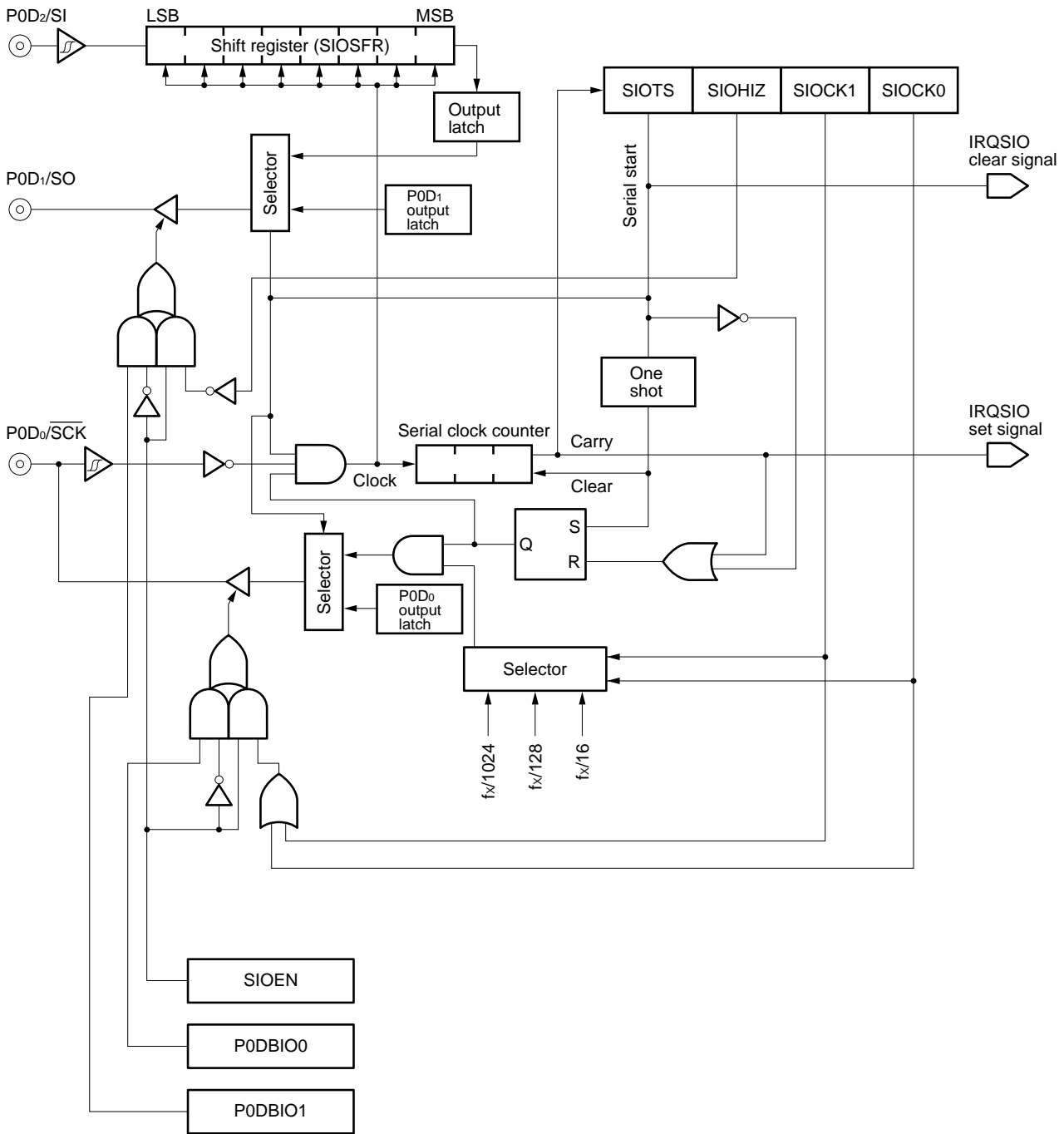
When SIOEN is set to 1, the pins of port 0D (P0D0/ $\overline{\text{SCK}}$, P0D1/SO, P0D2/SI) function as the pins of the serial interface. The serial interface operates in synchronization with the falling edge of the external or internal clock by setting SIOTS to 1. When SIOTS is set, IRQSIO is automatically cleared.

Transmission starts from the most significant bit of the shift register in synchronization with the falling edge of the serial clock. SI pin information is stored in the shift register starting at the least significant bit in synchronization with the rising edge of the clock.

When the 8-bits data transmission is terminated, SIOTS is automatically cleared and IRQSIO is set.

Remark Serial transmission starts only from the most significant bit of the shift register contents. It is not possible to transmit from the least significant bit. SI pin status is always stored in the shift register in synchronization with the rising edge of the serial clock.

Fig. 15-1 Block Diagram of the Serial Interface



Caution The output latch of the shift register is independent of that of the P0D1 pin. Therefore, even if an output instruction is executed for the P0D1 pin, the output latch status of the shift register does not change. Inputting a RESET signal clears the output latch of the shift register to 0. After that, the latch retains the LSB of the data transmitted previously.

15.2 3-WIRE SERIAL INTERFACE OPERATION MODES

Two modes can be used for the serial interface. If the serial interface function is selected, the P0D₂/SI pin always takes in data in synchronization with the serial clock.

- 8-bit transmission and reception mode (simultaneous transmission and reception)
- 8-bit reception mode (with the SO pin output set to high impedance)

Table 15-2 Serial Interface Operation Mode

SIOEN	SIOHIZ	P0D ₀ /SI pin	P0D ₁ /SO pin	Serial interface operation mode
1	0	SI	SO	8-bit transmission and reception mode
1	1	SI	P0D ₁ (input)	8-bit reception mode
0	×	P0D ₀ (I/O)	P0D ₁ (I/O)	General port mode

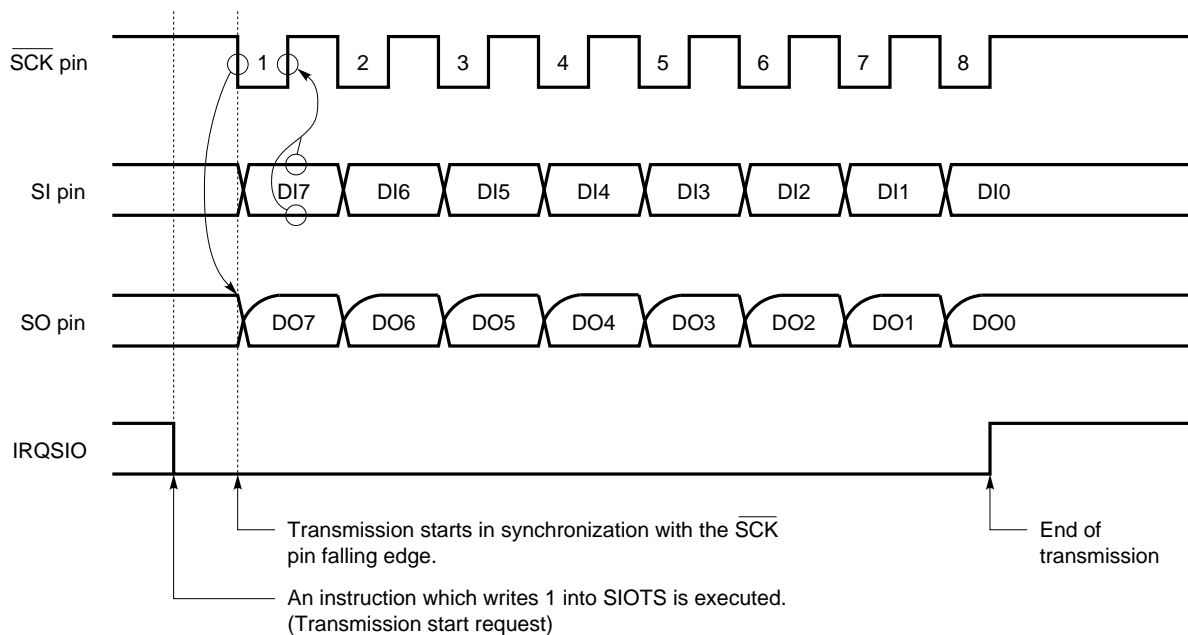
×: Don't care

(1) 8-bit transmission and reception mode (simultaneous transmission and reception)

Serial data input/output is controlled by a serial clock. The most significant bit of the shift register is output from the SO line with a falling edge of the serial clock (\overline{SCK}). The contents of the shift register is shifted one bit and at the same time, data on the SI line is loaded into the least significant bit of the shift register.

The serial clock counter (3-bit counter) counts serial clock pulses. Every time it counts eight clocks, the internal interrupt request flag (IRQSIO) is set to 1.

Fig. 15-2 Timing of 8-Bit Transmission and Reception Mode (Simultaneous Transmission and Reception)



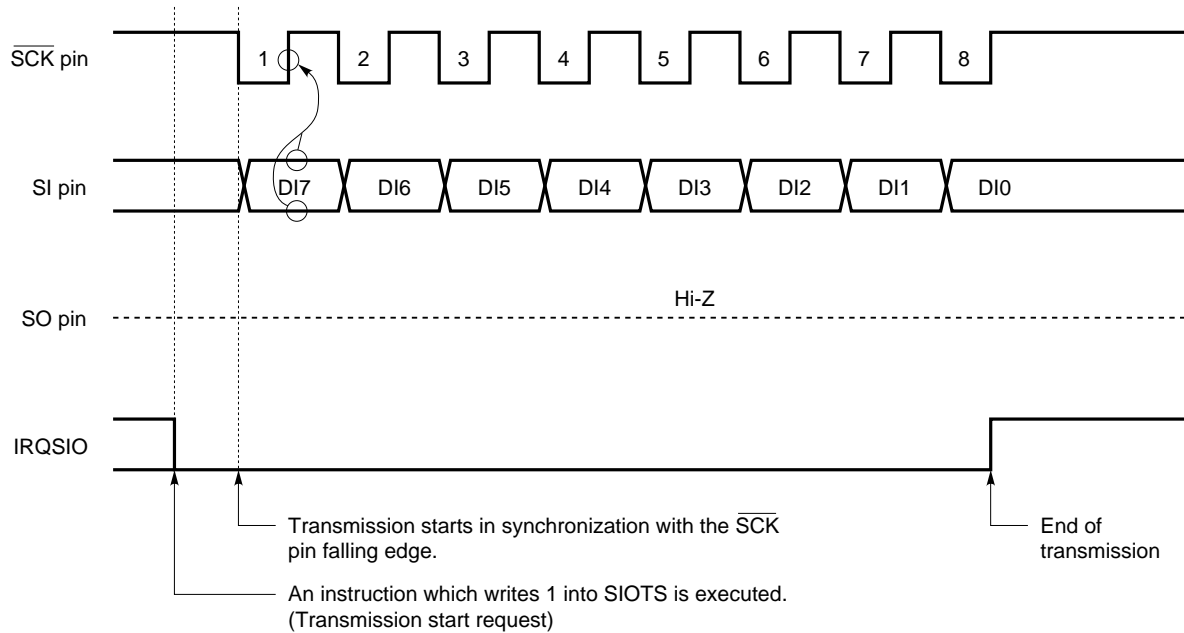
Remark DI : Input serial data
DO: Output serial data

(2) 8-bit transmission and reception mode (with the SO pin set to the high impedance status)

When SIOHIZ is 1, the P0D1/SO pin is in the output high impedance status. If serial clock supply starts by writing 1 in SIOTS, only the reception function of the serial interface operates.

The P0D1/SO pin is in the high impedance status and can be used for input port (P0D1).

Fig. 15-3 Clock Synchronization 8-Bit Reception Mode



Remark DI: Input serial data

(3) Operation stop mode

If the value in SIOTS (RF: address 02H, bit 3) is 0, the serial interface enters operation stop mode. In this mode, no serial transfer occurs.

In this mode, the shift register does not perform shifting and can be used as an ordinary 8-bit register.

16. INTERRUPT FUNCTIONS

The μPD17149 has five interrupt sources: four internal interrupt functions and one external interrupt function. It can be used in various applications.

The interrupt control circuit of the μPD17149 has the features listed below. This circuit enables very high-speed interrupt handling.

- (a) Used to determine whether an interrupt can be accepted with the interrupt mask enable flag (INTE) and interrupt enable flag (IP_{xxx}).
- (b) The interrupt request flag (IRQ_{xxx}) can be tested or cleared. (Interrupt generation can be checked by software.)
- (c) Multiple interrupts are possible (up to three levels).
- (d) Standby mode (STOP, HALT) can be released by an interrupt request. (Release conditions can be selected by the interrupt enable flag.)

Caution In interrupt handling, only the BCD, CMP, CY, Z, and IXE flags are saved in the stack automatically by the hardware for up to three levels of multiple interrupts. The DBF and WR are not saved by the hardware when peripheral hardware such as the timers or A/D converter is accessed in interrupt handling. It is recommended that the DBF and WR be saved in RAM by the software at the beginning of interrupt handling. Saved data can be loaded back into the DBF and WR immediately before the end of interrupt handling.

16.1 INTERRUPT SOURCE TYPES AND VECTOR ADDRESS

For every interrupt in the μPD17149, when the interrupt is accepted, a branch occurs to the vector address associated with the interrupt source. This method is called the vectored interrupt method. Table 16-1 lists the interrupt source types and vector addresses.

If two or more interrupt requests occur or multiple suspended interrupt requests are enabled at the same time, they are handled according to priorities shown in Table 16-1.

Table 16-1 Interrupt Source Types

Interrupt source	Priority	Vector address	IRQ flag	IP flag	IEG flag	Internal/external	Remarks
INT pin (RF: 0FH, bit 0)	1	0005H	IRQ RF: 3FH, bit 0	IP RF: 2FH, bit 0	IEGMD0,1 RF: 1FH	External	Rising edge or falling edge can be selected.
Timer 0	2	0004H	IRQTM0 RF: 3EH, bit 0	IPTM0 RF: 2FH, bit 1	-	Internal	
Timer 1	3	0003H	IRQTM1 RF: 3DH, bit 0	IPTM1 RF: 2FH, bit 2	-	Internal	
Basic interval timer	4	0002H	IRQBTM RF: 3CH, bit 0	IPBTM RF: 2FH, bit 3	-	Internal	
Serial interface	5	0001H	IRQSIO RF: 3BH, bit 0	IPSIO RF: 2EH, bit 0	-	Internal	

16.2 HARDWARE COMPONENTS OF THE INTERRUPT CONTROL CIRCUIT

The flags of the interrupt control circuit are explained below.

(1) Interrupt request flag and the interrupt enable flag

The interrupt request flag (IRQ_{xxx}) is set to 1 when an interrupt request occurs. When interrupt handling is executed, the flag is automatically cleared to 0.

An interrupt enable flag (IP_{xxx}) is provided for each interrupt request flag. If the flag is 1, an interrupt is enabled. If it is 0, the interrupt is disabled.

(2) EI/DI instruction

The EI/DI instruction is used to determine whether an accepted interrupt is to be executed.

If the EI instruction is executed, the interrupt enable flag (INTE) for enabling interrupt reception is set. Since the INTE flag is not registered in the register file, flag status cannot be checked by instructions.

The DI instruction clears the INTE flag to 0 and disables all interrupts.

At reset the INTE flag is cleared to 0 and all interrupts are disabled.

Table 16-2 Interrupt Request Flag and Interrupt Enable Flag

Interrupt request flag	Signal for setting the interrupt request flag	Interrupt enable flag
IRQ	Set by edge detection of an INT pin input signal. A detection edge is selected by IEGMD0 or IEGMD1.	IP
IRQTM0	Set by a match signal from timer 0.	IPTM0
IRQTM1	Set by a match signal from timer 1.	IPTM1
IRQBTM	Set by an overflow (reference time interval signal) from the basic interval timer.	IPBTM
IRQSIO	Set by a serial data transmission end signal from the serial interface.	IPSIO

17. STANDBY FUNCTION

17.1 OVERVIEW OF THE STANDBY FUNCTION

The μPD17149 can reduce its current by using the standby function. The standby function supports STOP and HALT modes.

In the STOP mode, the system clock is stopped and the CPU current is reduced to almost only a leak current. This mode is useful in retaining data memory contents without operating the CPU.

In the HALT mode, the oscillation of the system clock continues. However, the system clock is not supplied to the CPU, stopping CPU operation. In this mode, current reduction is less than that in the STOP mode. However, since the system clock is oscillating, operation can be started immediately after the HALT mode is released. In both STOP and HALT modes, the statuses of the data memory, registers, and output latches of the output port used immediately before the standby mode is set are maintained (except STOP 0000B). Therefore, in order to lower consumption current for the entire system, input/output port statuses should be set beforehand.

Table 17-1 Standby Mode Status

		STOP mode	HALT mode
Programmed instruction		STOP instruction	HALT instruction
Clock oscillator		Oscillation stopped	Oscillation continued
Operation status	CPU	• Operation stopped	
	RAM	• The contents held immediately before setting standby mode are retained.	
	Port	• The status existing immediately before setting standby mode is retained. ^{Note}	
	TM0	<ul style="list-style-type: none"> • Operable only when the INT input is selected as the count clock. • Stopped when the system clock is selected. (The count is retained.) 	• Operable
	TM1	<ul style="list-style-type: none"> • Operation stopped. (The count is reset to 0.) (Count-up is also inhibited.) 	• Operable
	BTM	<ul style="list-style-type: none"> • Operation stopped. (The count is retained.) 	• Operable
	SIO	<ul style="list-style-type: none"> • Operable only when the external clock is selected as the shift clock.^{Note} 	• Operable
	A/D	<ul style="list-style-type: none"> • Operation stopped^{Note} (ADCR ← 00H) 	• Operable
	INT	<ul style="list-style-type: none"> • Operable 	• Operable

Note When STOP 0000B is executed, all pins are set to input port mode even if the pins are used in dual-function mode.

Cautions 1. Always specify a NOP instruction immediately before STOP and HALT instructions.

2. When an interrupt request flag and the corresponding interrupt enable flag are both set, and the associated interrupt is specified as the standby mode release condition, the system does not enter the standby mode even if a STOP or HALT instruction is executed.

17.2 HALT MODE

17.2.1 Setting HALT Mode

Executing a HALT instruction sets HALT mode.

Operand b3b2b1b0 of the HALT instruction indicates the HALT mode release conditions.

Table 17-2 HALT Mode Release Conditions

Format: HALT b3b2b1b0B

Bit	HALT mode release conditions ^{Note 1}
b3	When this bit is 1, release by IRQ _{xxx} is permitted. ^{Notes 2, 4}
b2	Always 0
b1	When this bit is 1, forced release by IRQTM1 is permitted. ^{Notes 3, 4}
b0	When this bit is 1, release by \overline{RLS} input is permitted. ^{Note 4}

- Notes**
1. When HALT 0000B is specified, HALT mode can be released only by reset (\overline{RESET} input or POC).
 2. IP_{xxx} must be 1.
 3. HALT mode is released regardless of the IPTM1 status.
 4. If a HALT instruction is executed when IRQ_{xxx} = 1 or when the \overline{RLS} input is low, the HALT instruction is ignored (treated as a NOP instruction), and HALT mode is not set.

17.2.2 Starting Address After HALT Mode is Released

The starting address depends on the release conditions and interrupt enable conditions.

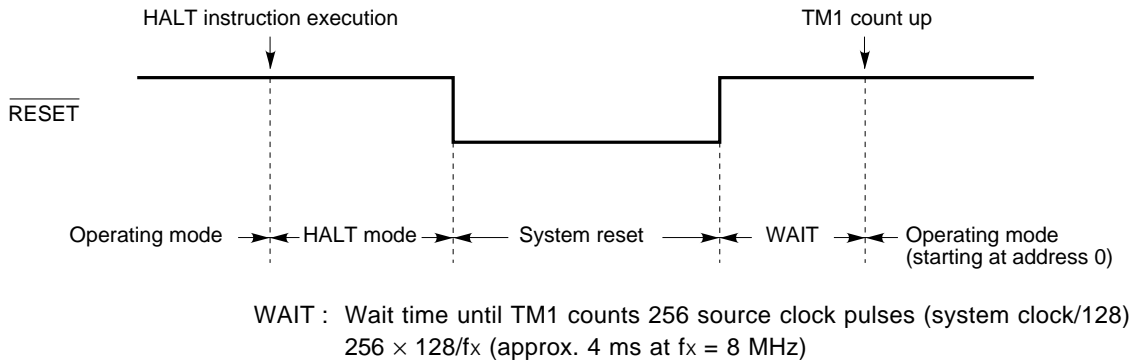
Table 17-3 Starting Address After HALT Mode is Released

Release condition	Starting address after release
Reset ^{Note 1}	Address 0
\overline{RLS}	Address subsequent to the HALT instruction
IRQ _{xxx} ^{Note 2}	For DI, address subsequent to the HALT instruction
	For EI, interrupt vector (When more than one IRQ _{xxx} is set, the interrupt vector having the highest priority)

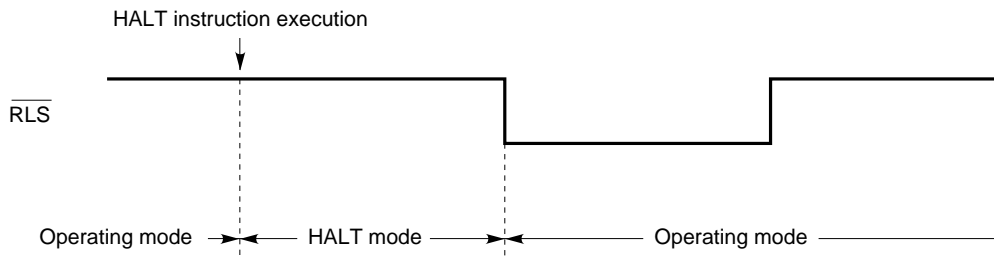
- Notes**
1. \overline{RESET} input and POC are valid.
 2. Except when forced release is made with IRQTM1, IP_{xxx} must be 1.

Fig. 17-1 Releasing HALT Mode

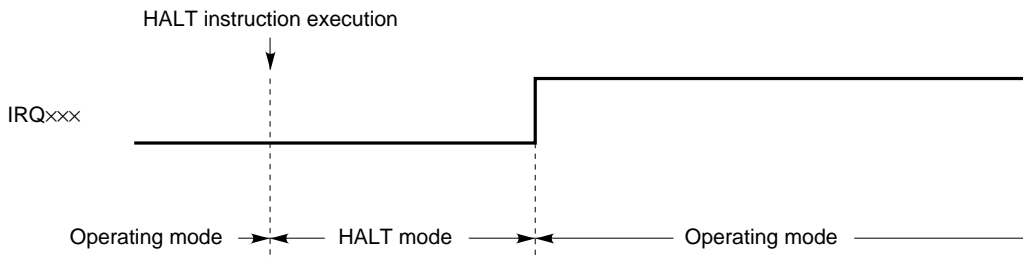
(a) Releasing HALT mode by $\overline{\text{RESET}}$ input



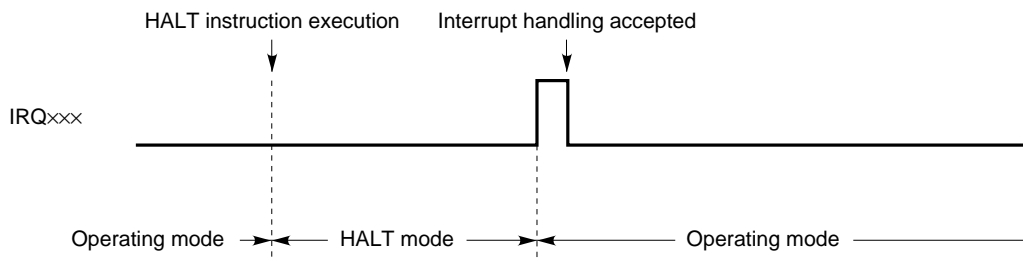
(b) Releasing HALT mode by $\overline{\text{RLS}}$



(c) Releasing HALT mode by IRQ_{xxx} (for DI)



(d) Releasing HALT mode by IRQ_{xxx} (for EI)



17.3 STOP MODE

17.3.1 Setting STOP Mode

Executing a STOP instruction results in STOP mode being set.

Operand b₃b₂b₁b₀ of the STOP instruction indicates the STOP mode release conditions.

Table 17-4 STOP Mode Release Conditions

Format: STOP b₃b₂b₁b₀B

Bit	STOP mode release condition ^{Note 1}
b ₃	When this bit is 1, release by IRQ _{xxx} is permitted. ^{Notes 2, 4}
b ₂	Always 0
b ₁	Always 0
b ₀	When this bit is 1, release by \overline{RLS} input is permitted. ^{Note 3, 4}

- Notes**
1. When STOP 0000B is specified, STOP mode can be released only with reset (\overline{RESET} input or POC). When STOP 0000B is executed, the microcomputer is initialized to the state existing immediately after the reset.
 2. IP_{xxx} must be 1. STOP mode cannot be released with IRQTM1.
 3. Setting only b₀ to 1 is not allowed. (STOP 0001B is inhibited.) To set b₀ to 1, b₃ must also be set to 1.
 4. If the STOP instruction is executed when IRQ_{xxx} = 1 or when the \overline{RLS} input is low, the STOP instruction is ignored (treated as a NOP instruction), and STOP mode is not set.

17.3.2 Starting Address After STOP Mode is Released

The starting address depends on the release conditions and interrupt enable conditions.

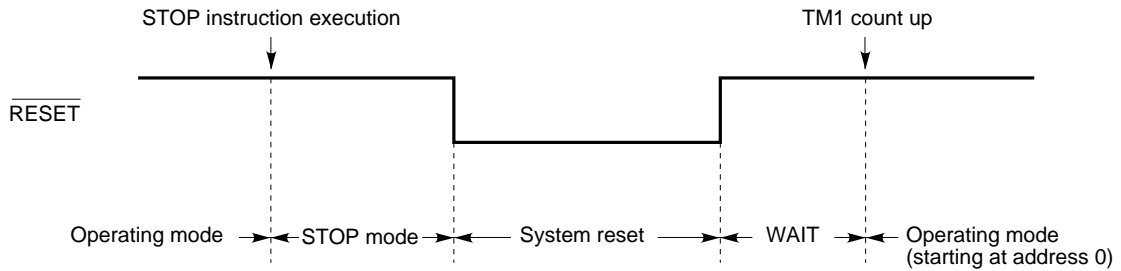
Table 17-5 Starting Address After STOP Mode is Released

Release condition	Starting address after release
Reset ^{Note 1}	Address 0
\overline{RLS}	Address subsequent to the STOP instruction
IRQ _{xxx} ^{Note 2}	For DI, address subsequent to the STOP instruction For EI, interrupt vector (When more than one IRQ _{xxx} is set, the interrupt vector having the highest priority)

- Notes**
1. \overline{RESET} input and POC are valid.
 2. IP_{xxx} must be 1. STOP mode cannot be released with IRQTM1.

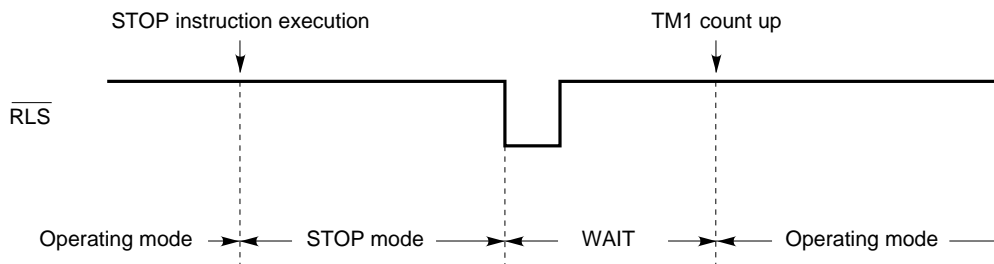
Fig. 17-2 Releasing STOP Mode (1/2)

(a) Releasing STOP mode by $\overline{\text{RESET}}$ input



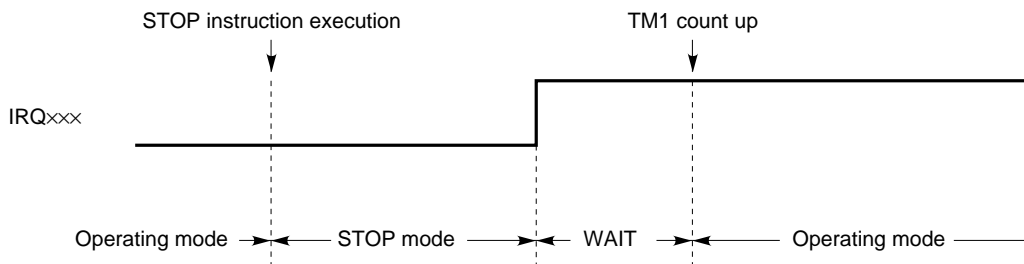
WAIT : Wait time until TM1 counts 256 source clock pulses (system clock/128)
 $256 \times 128/f_x + \alpha$ (approx. 4 ms + α at $f_x = 8$ MHz)
 α : Oscillation development time (which depends on the resonator)

(b) Releasing STOP mode by $\overline{\text{RLS}}$



WAIT : Wait time until TM1 counts (n + 1) source clock pulses (system clock/m)
 $(n + 1) \times m/f_x + \alpha$ (n and m are the values used immediately before STOP mode is set)
 α : Oscillation development time (which depends on the resonator)

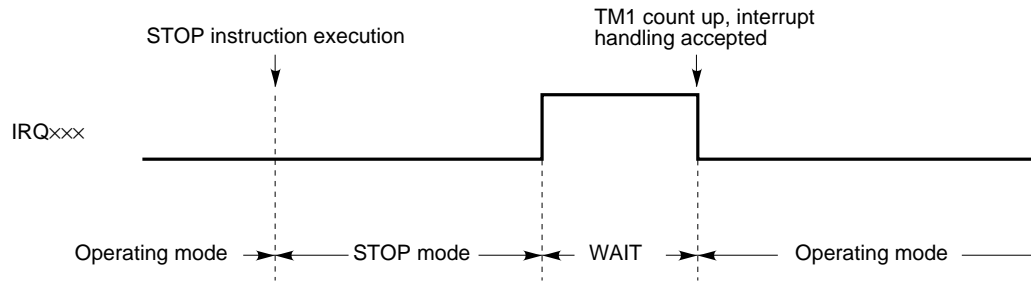
(c) Releasing STOP mode by IRQ_{xxx} (for DI)



WAIT : Wait time until TM1 counts (n + 1) source clock pulses (system clock/m)
 $(n + 1) \times m/f_x + \alpha$ (n and m are the values used immediately before STOP mode is set)
 α : Oscillation development time (which depends on the resonator)

Fig. 17-2 Releasing STOP Mode (2/2)

(d) Releasing STOP mode by IRQ_{xxx} (for EI)



WAIT : Wait time until TM1 counts (n + 1) source clock pulses (system clock/m)
 $(n + 1) \times m/f_x + \alpha$ (n and m are the values used immediately before STOP mode is set)
 α : Oscillation development time (which depends on the resonator)

18. RESET

The μPD17149 is reset when a reset signal is applied to the $\overline{\text{RESET}}$ pin, when the incorporated POC circuit detects a supply voltage drop, when the watchdog timer function detects a program crush, or when the address stack overflows or underflows. The incorporated POC circuit is specified with the mask option.

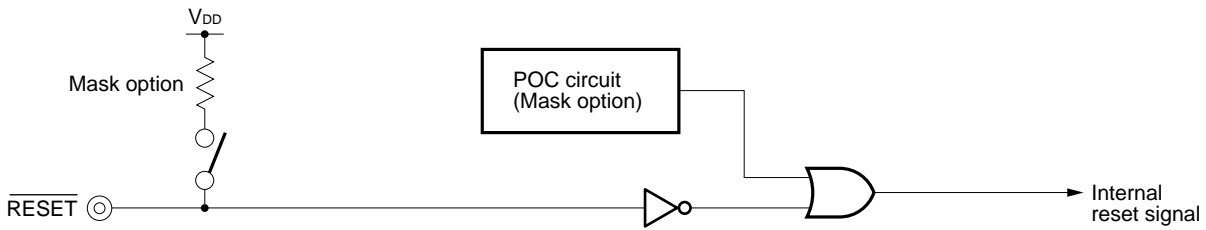
18.1 RESET FUNCTIONS

The reset functions are used to initialize device operations. The operations initialized depend on the reset type.

Table 18-1 Hardware Statuses after Reset

Reset type		• $\overline{\text{RESET}}$ input during operation • Incorporated power-on/power-down reset during operation	• $\overline{\text{RESET}}$ input in the standby mode • Incorporated power-on/power-down reset in the standby mode	• Watchdog timer overflow • Stack overflow or underflow
Hardware				
Program counter		0000H	0000H	0000H
Port	Input/output mode	Input	Input	Input
	Output latch	0	0	Not defined
General-purpose data memory	Other than DBF	Not defined	Statuses before reset are retained.	Not defined
	DBF	Not defined	Not defined	Not defined
System register	Other than WR	0	0	0
	WR	Not defined	Statuses before reset are retained.	Not defined
Control register		SP = 5H, IRQTM1 = 1, TM1EN = 1, IRQBTM = 0, and INT indicate the current status of the INT pin. The others are 0. See Chapter 8 .		SP = 5H and INT indicate the current status of the INT pin. The others retain statuses before reset.
Timer 0 and timer 1	Count register	00H	00H	Timer 0: 00H Timer 1: Not defined
	Modulo register	FFH	FFH	FFH
Basic interval timer binary counter		Not defined	Not defined	Not defined. (40H for watchdog timer overflow)
Serial interface shift register (SIOSFR)		Not defined	Statuses before reset are retained.	Not defined
A/D converter data register (ADCR)		00H	00H	00H

Fig. 18-1 Reset Block Configuration



18.2 RESETTING

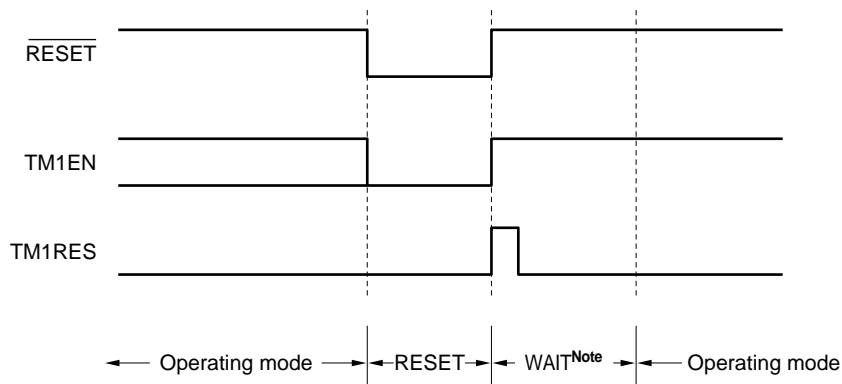
Operation when reset is caused by RESET input is shown in Fig. 18-2.

If the RESET pin is set from low to high, system clock generation starts and timer 1 generates an oscillation settling time. Program execution starts from address 0000H.

The controller also operates in the same way when the POC circuit causes a system reset.

At watchdog timer overflow reset or stack overflow and underflow reset, an oscillation settling time (WAIT) is not generated. Operation starts from address 0000H after initial statuses are internally set.

Fig. 18-2 Resetting



Note This is an oscillation settling time. Operating mode is set when timer 1 counts system clocks 128×256 times (the execution time for approx. 2048 instructions, approx. 4 ms at 8 MHz).

19. POC CIRCUIT (MASK OPTION)

The POC circuit monitors the power supply voltage. It resets the microcomputer when the power is turned on/off. It can be used in application circuits using clock frequencies (f_x) of between 400 kHz and 4 MHz.

The POC circuit can be included in the μ PD17149 by specifying a mask option.

Caution The PROM product (μ PD17P149) cannot include the POC circuit.

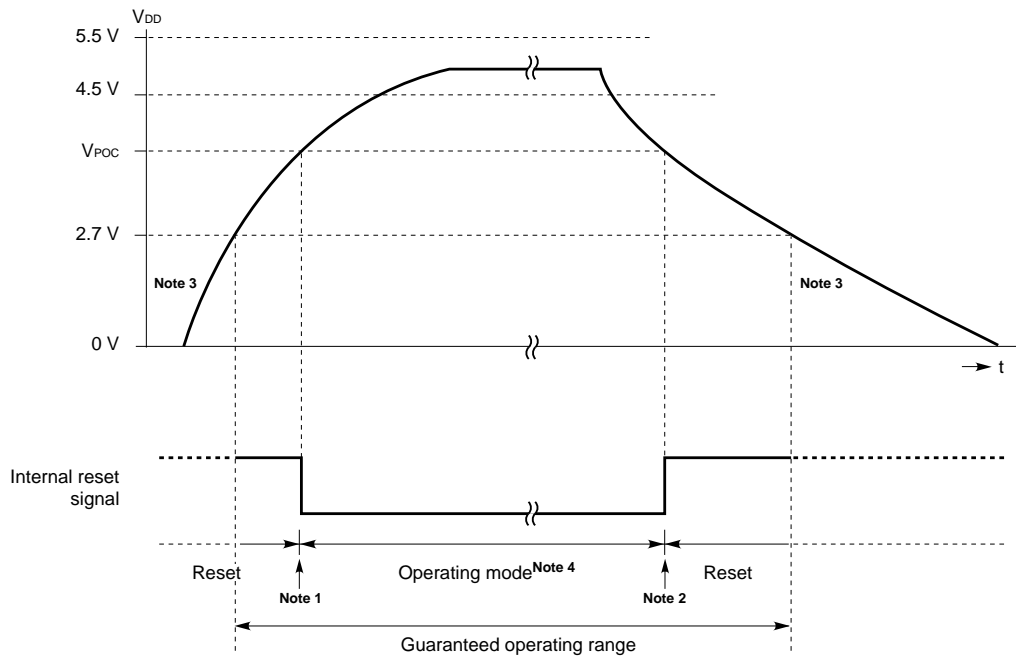
19.1 FUNCTIONS OF THE POC CIRCUIT

The POC circuit operates as follows:

- When $V_{DD} \leq V_{POC}$, an internal reset signal is generated.
- When $V_{DD} > V_{POC}$, the internal reset signal is released.

(Where, V_{DD} : power voltage, V_{POC} : POC-detected voltage)

Fig. 19-1 Operation of the POC Circuit



Notes 1. In actual operation, an oscillation settling time, controlled by timer 1, is inserted before the operating mode is set. The oscillation settling time is equal to the time needed to execute approximately 2048 instructions (approximately 8 ms at $f_x = 4$ MHz).

2. A power supply voltage fall can cause a reset only when V_{POC} or a lower voltage level is maintained for a duration equal to at least the reset detection pulse width t_{SAMP} . Thus, there is a delay of up to t_{SAMP} before reset.

3. When the supply voltage (V_{DD}) drops below 2.7 V, operations of all functions of the μ PD17149 are unpredictable. The POC circuit, however, is designed to generate an internal reset signal whenever possible, regardless of whether an oscillation is received. So, an internal reset should occur when the voltage reaches a level at which the internal circuit can operate.

★

4. When the supply voltage rises abruptly (3 V/ms or more), even during operating mode, the POC circuit may generate an internal reset signal to prevent the program running away out of control.

Remark For the values of V_{POC} and t_{SAMP} , see **Chapter 22**.

19.2 CONDITIONS UNDER WHICH THE POC CIRCUIT MAY BE USED

The POC circuit can be used when the application circuit satisfies the following conditions:

- The application circuit is not required to provide high reliability.
- The supply voltage (V_{DD}) of the application circuit is between 4.5 V and 5.5 V.
- The system clock frequency (f_x) of the application circuit is between 400 kHz and 4 MHz.
- The supply voltage (V_{DD}) characteristics satisfy the POC circuit specifications.

- Cautions 1.** When the POC circuit is used with an application circuit requiring high reliability, be sure to design the POC circuit so that the $\overline{\text{RESET}}$ signal is input from the outside.
- 2.** When the POC circuit is used, the current drawn in standby mode will be slightly higher than when the circuit is not used.

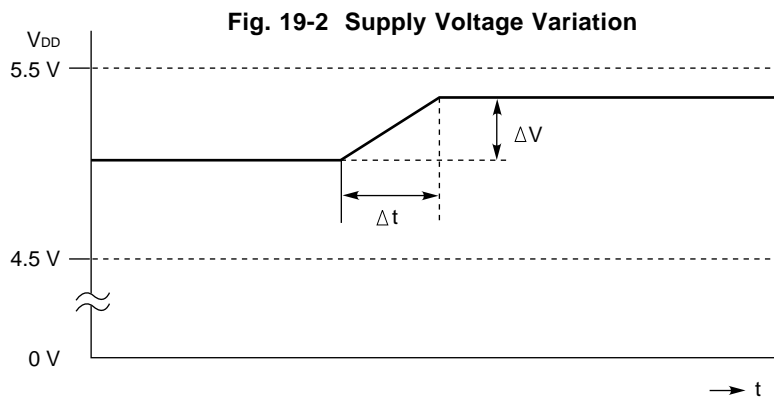
Remark POC circuit operation is guaranteed when V_{DD} is between 2.7 and 5.5 V.

★ **19.3 CAUTIONS FOR USING THE POC CIRCUIT**

The POC circuit is designed in a fail-safe configuration. It has an auxiliary function^{Note} by which if the supply voltage changes abruptly even within the rated range ($V_{DD} = 4.5$ to 5.5 V), a reset signal is issued as much as possible to avoid program crashes.

Note that if the supply voltage does not meet the conditions listed below, the POC circuit may cause a reset.

- The variation (ΔV) of the supply voltage must be within 100 mV.
- If the variation of the supply voltage is not within 100 mV, the variation slant ($\Delta V/\Delta t$) must be within 3 mV/ μs .



Note The reset function based on supply voltage variation is of auxiliary nature. It does not assure that a reset occurs without failure. There is no condition to assure that a reset occurs based on this auxiliary function. Do not count on this function when designing.

20. INSTRUCTION SET

20.1 OVERVIEW OF THE INSTRUCTION SET

b ₁₄ -b ₁₁		b ₁₅		0		1	
		BIN	HEX				
0 0 0 0	0	ADD	r, m	ADD	m, #n4		
0 0 0 1	1	SUB	r, m	SUB	m, #n4		
0 0 1 0	2	ADDC	r, m	ADDC	m, #n4		
0 0 1 1	3	SUBC	r, m	SUBC	m, #n4		
0 1 0 0	4	AND	r, m	AND	m, #n4		
0 1 0 1	5	XOR	r, m	XOR	m, #n4		
0 1 1 0	6	OR	r, m	OR	m, #n4		
0 1 1 1	7	INC	AR				
		INC	IX				
		MOVT	DBF, @AR				
		BR	@AR				
		CALL	@AR				
		RET					
		RETSK					
		EI					
		DI					
		RETI					
		PUSH	AR				
		POP	AR				
		GET	DBF, p				
		PUT	p, DBF				
		PEEK	WR, rf				
POKE	rf, WR						
RORC	r						
STOP	s						
HALT	h						
NOP							
1 0 0 0	8	LD	r, m	ST	m, r		
1 0 0 1	9	SKE	m, #n4	SKGE	m, #n4		
1 0 1 0	A	MOV	@r, m	MOV	m, @r		
1 0 1 1	B	SKNE	m, #n4	SKLT	m, #n4		
1 1 0 0	C	BR	addr (page 0)	CALL	addr		
1 1 0 1	D	BR	addr (page 1)	MOV	m, #n4		
1 1 1 0	E			SKT	m, #n		
1 1 1 1	F			SKF	m, #n		

20.2 LEGEND

AR	: Address register
ASR	: Address stack register pointed to by the stack pointer
addr	: Program memory address (11 low-order bits)
BANK	: Bank register
CMP	: Compare flag
CY	: Carry flag
DBF	: Data buffer
h	: Halt release condition
INTEF	: Interrupt enable flag
INTR	: Register automatically saved in the stack when an interrupt occurs
INTSK	: Interrupt stack register
IX	: Index register
MP	: Data memory row address pointer
MPE	: Memory pointer enable flag
m	: Data memory address specified by m _R and m _C
m _R	: Data memory row address (high-order)
m _C	: Data memory column address (low-order)
n	: Bit position (four bits)
n4	: Immediate data (four bits)
PAGE	: Page (bit 11 of the program counter)
PC	: Program counter
p	: Peripheral address
p _H	: Peripheral address (three high-order bits)
p _L	: Peripheral address (four low-order bits)
r	: General register column address
rf	: Register file address
r _R	: Register file row address (three high-order bits)
r _C	: Register file column address (four low-order bits)
SP	: Stack pointer
s	: Stop release condition
WR	: Window register
(x)	: Contents of x

20.3 LIST OF THE INSTRUCTION SET

Instruction set	Mnemonic	Operand	Operation	Instruction code			
				Op code	Operand		
Add	ADD	r, m	$(r) \leftarrow (r) + (m)$	00000	m _R	m _C	r
		m, #n4	$(m) \leftarrow (m) + n4$	10000	m _R	m _C	n4
	ADDC	r, m	$(r) \leftarrow (r) + (m) + CY$	00010	m _R	m _C	r
		m, #n4	$(m) \leftarrow (m) + n4 + CY$	10010	m _R	m _C	n4
	INC	AR	$AR \leftarrow AR + 1$	00111	000	1001	0000
		IX	$IX \leftarrow IX + 1$	00111	000	1000	0000
Subtract	SUB	r, m	$(r) \leftarrow (r) - (m)$	00001	m _R	m _C	r
		m, #n4	$(m) \leftarrow (m) - n4$	10001	m _R	m _C	n4
	SUBC	r, m	$(r) \leftarrow (r) - (m) - CY$	00011	m _R	m _C	r
		m, #n4	$(m) \leftarrow (m) - n4 - CY$	10011	m _R	m _C	n4
Logical operation	OR	r, m	$(r) \leftarrow (r) \vee (m)$	00110	m _R	m _C	r
		m, #n4	$(m) \leftarrow (m) \vee n4$	10110	m _R	m _C	n4
	AND	r, m	$(r) \leftarrow (r) \wedge (m)$	00100	m _R	m _C	r
		m, #n4	$(m) \leftarrow (m) \wedge n4$	10100	m _R	m _C	n4
	XOR	r, m	$(r) \leftarrow (r) \oplus (m)$	00101	m _R	m _C	r
		m, #n4	$(m) \leftarrow (m) \oplus n4$	10101	m _R	m _C	n4
Test	SKT	m, #n	$CMP \leftarrow 0$, if $(m) \wedge n = n$, then skip	11110	m _R	m _C	n
	SKF	m, #n	$CMP \leftarrow 0$, if $(m) \wedge n = 0$, then skip	11111	m _R	m _C	n
Compare	SKE	m, #n4	$(m) - n4$, skip if zero	01001	m _R	m _C	n4
	SKNE	m, #n4	$(m) - n4$, skip if not zero	01011	m _R	m _C	n4
	SKGE	m, #n4	$(m) - n4$, skip if not borrow	11001	m _R	m _C	n4
	SKLT	m, #n4	$(m) - n4$, skip if borrow	11011	m _R	m _C	n4
Rotation	RORC	r	$\left[\rightarrow CY \rightarrow (r)b_3 \rightarrow (r)b_2 \rightarrow (r)b_1 \rightarrow (r)b_0 \right]$	00111	000	0111	r
Transfer	LD	r, m	$(r) \leftarrow (m)$	01000	m _R	m _C	r
	ST	m, r	$(m) \leftarrow (r)$	11000	m _R	m _C	r
	MOV	@r, m	if MPE = 1: $(MP, (r)) \leftarrow (m)$ if MPE = 0: $(BANK, m_R, (r)) \leftarrow (m)$	01010	m _R	m _C	r
		m, @r	if MPE = 1: $(m) \leftarrow (MP, (r))$ if MPE = 0: $(m) \leftarrow (BANK, m_R, (r))$	11010	m _R	m _C	r
		m, #n4	$(m) \leftarrow n4$	11101	m _R	m _C	n4
	MOVT	DBF, @AR	$SP \leftarrow SP - 1$, $ASR \leftarrow PC$, $PC \leftarrow AR$, $DBF \leftarrow (PC)$, $PC \leftarrow ASR$, $SP \leftarrow SP + 1$	00111	000	0001	0000
	PUSH	AR	$SP \leftarrow SP - 1$, $ASR \leftarrow AR$	00111	000	1101	0000
	POP	AR	$AR \leftarrow ASR$, $SP \leftarrow SP + 1$	00111	000	1100	0000
	PEEK	WR, rf	$WR \leftarrow (rf)$	00111	rf _R	0011	rf _C
	POKE	rf, WR	$(rf) \leftarrow WR$	00111	rf _R	0010	rf _C
	GET	DBF, p	$DBF \leftarrow (p)$	00111	p _H	1011	p _L
PUT	p, DBF	$(p) \leftarrow DBF$	00111	p _H	1010	p _L	

Instruction set	Mnemonic	Operand	Operation	Instruction code			
				Op code	Operand		
Branch	BR	addr	Note	Note	addr		
		@AR	PC ← AR	00111	000	0100	0000
Sub-routine	CALL	addr	SP ← SP - 1, ASR ← PC, PC ← addr	11100	addr		
		@AR	SP ← SP - 1, ASR ← PC, PC ← AR	00111	000	0101	0000
	RET		PC ← ASR, SP ← SP + 1	00111	000	1110	0000
	RETSK		PC ← ASR, SP ← SP + 1 and skip	00111	001	1110	0000
	RETI		PC ← ASR, INTR ← INTSK, SP ← SP + 1	00111	100	1110	0000
Interrupt	EI		INTEF ← 1	00111	000	1111	0000
	DI		INTEF ← 0	00111	001	1111	0000
Others	STOP	s	STOP	00111	010	1111	s
	HALT	h	HALT	00111	011	1111	h
	NOP		No operation	00111	100	1111	0000

Note The following tables show the operations and op codes of a BR addr instruction for the μPD17145, μPD17147, and μPD17149.

(a) μPD17145, μPD17147

Mnemonic	Operand	Operation	Op code
BR	addr	PC ← addr, PAGE ← 0	01100

(b) μPD17149

Mnemonic	Operand	Operation	Op code
BR	addr	PC ← addr, PAGE ← 0	01100
		PC ← addr, PAGE ← 1	01101

20.4 ASSEMBLER (AS17K) BUILT-IN MACRO INSTRUCTIONS

Legend

flag n: Flag type symbol

< > : Data < > is omissible.

	Mnemonic	Operand	Operation	n
Built-in macro	SKTn	flag 1, ...flag n	if (flag 1) to (flag n) = all "1", then skip	1 - n - 4
	SKFn	flag 1, ...flag n	if (flag 1) to (flag n) = all "0", then skip	1 - n - 4
	SETn	flag 1, ...flag n	(flag 1) to (flag n) ← 1	1 - n - 4
	CLRn	flag 1, ...flag n	(flag 1) to (flag n) ← 0	1 - n - 4
	NOTn	flag 1, ...flag n	if (flag n) = "0", then (flag n) ← 1 if (flag n) = "1", then (flag n) ← 0	1 - n - 4
	INITFLG	<NOT> flag 1, ...<NOT> flag n>	if description = NOT flag n, then (flag n) ← 0 if description = flag n, then (flag n) ← 1	1 - n - 4
	BANKn		(BANK) ← n	n = 0

21. ASSEMBLER RESERVED WORDS

21.1 MASK OPTION PSEUDO INSTRUCTIONS

The μPD17149 has the following mask options.

- Built-in pull-up resistor for pin RESET
- Built-in pull-up resistors for pins P0F₁ and P0F₀
- Built-in pull-up resistor for pin INT
- Incorporated POC circuit

Specify whether these mask options are used in the source program using mask-option-definition pseudo instructions.

21.1.1 Specifying Mask Options

Mask options are coded in the assembler source program with the following pseudo instructions.

- OPTION and ENDOP pseudo instructions
- Mask-option-definition pseudo instructions

(1) OPTION and ENDOP pseudo instructions

These pseudo instructions specify the block in which mask options are coded (mask option definition block).

To specify a mask option, code the corresponding mask-option-definition pseudo instruction in the block enclosed with the OPTION pseudo instruction and ENDOP pseudo instruction.

Format:

Symbol	Mnemonic	Operand	Comment
[label:]	OPTION		[:comment]
	⋮		
	ENDOP		

(2) Mask option definition pseudo instructions

Table 21-1 Mask Option Definition Pseudo Instructions

Option	Definition pseudo instruction and format	Operand	Meaning
Built-in pull-up resistor for pin $\overline{\text{RESET}}$	OPTRES <operand>	OPEN	Without pull-up resistor
		PULLUP	With pull-up resistor
Built-in pull-up resistors for pins P0F ₁ and P0F ₀	OPTP0F <operand-1>, <operand-2> ^{Note}	OPEN	Without pull-up resistor
		PULLUP	With pull-up resistor
Built-in pull-up resistor for pin INT	OPTINT <operand>	OPEN	Without pull-up resistor
		PULLUP	With pull-up resistor
Incorporated POC circuit	OPTPOC <operand>	NOUSE	Without POC circuit
		USE	With POC circuit

Note <operand-1> and <operand-2> specify the mask options for the P0F₁ and P0F₀ pins, respectively.

(3) Example of specifying mask options

; Example of specifying mask options in μPD17149

MASK_OPTION:

```

OPTION                ; Beginning of mask option definition block
OPTRES  PULLUP        ;  $\overline{\text{RESET}}$  pin has the built-in pull-up resistor.
OPTP0F  PULLUP, OPEN  ; P0F1 pin has the built-in pull-up resistor. P0F0 pin leaves open (external pull-
                        up).
OPTINT   PULLUP        ; INT pin has the built-in pull-up resistor.
OPTPOC   NOUSE         ; Internal POC circuit is not used.
ENDOP                ; End of mask option definition block
    
```

21.2 RESERVED SYMBOLS

The reserved symbols defined in the μPD17149 device file (AS17149) are listed below.

System register (SYSREG)

Symbolic name	Attribute	Value	Read/write	Description
AR3	MEM	0.74H	R	Bits 15 to 12 of the address register
AR2	MEM	0.75H	R/W	Bits 11 to 8 of the address register
AR1	MEM	0.76H	R/W	Bits 7 to 4 of the address register
AR0	MEM	0.77H	R/W	Bits 3 to 0 of the address register
WR	MEM	0.78H	R/W	Window register
BANK	MEM	0.79H	R/W	Bank register
IXH	MEM	0.7AH	R/W	Index register high
MPH	MEM	0.7AH	R/W	Data memory row address pointer high
MPE	FLG	0.7AH.3	R/W	Memory pointer enable flag
IXM	MEM	0.7BH	R/W	Index register middle
MPL	MEM	0.7BH	R/W	Data memory row address pointer low
IXL	MEM	0.7CH	R/W	Index register low
RPH	MEM	0.7DH	R/W	General register pointer high
RPL	MEM	0.7EH	R/W	General register pointer low
PSW	MEM	0.7FH	R/W	Program status word
BCD	FLG	0.7EH.0	R/W	BCD flag
CMP	FLG	0.7FH.3	R/W	Compare flag
CY	FLG	0.7FH.2	R/W	Carry flag
Z	FLG	0.7FH.1	R/W	Zero flag
IXE	FLG	0.7FH.0	R/W	Index enable flag

Fig. 21-1 System Register Configuration

Address	74H	75H	76H	77H	78H	79H	7AH	7BH	7CH	7DH	7EH	7FH
Name	Address register (AR)				Window register (WR)	Bank register (BANK)	Index register (IX) Data memory row address pointer (MP)			General register pointer (RP)	Program status word (PSWORD)	
Symbol	AR3	AR2	AR1	AR0	WR	BANK	IXH MPH	IXM MPL	IXL	RPH	RPL	PSW
Bit	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀	b ₃ b ₂ b ₁ b ₀
Data ^{Note 1}	0 0 0 0	Note 2 0 0 0 0	Note 2 0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	B C C I C M Y Z D P X E
Initial value when re-set	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	Not defined	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0	0 0 0 0

- Notes**
1. A bit indicating zero is fixed to zero.
 2. Bit b₃ and b₂ of AR2 are always 0 for the μPD17145. Bit b₃ of AR2 is always 0 also for the μPD17147.

Data buffer (DBF)

Symbolic name	Attribute	Value	Read/write	Description
DBF3	MEM	0.0CH	R/W	DBF bits 15 to 12
DBF2	MEM	0.0DH	R/W	DBF bits 11 to 8
DBF1	MEM	0.0EH	R/W	DBF bits 7 to 4
DBF0	MEM	0.0FH	R/W	DBF bits 3 to 0

Port register

Symbolic name	Attribute	Value	Read/write	Description
P0A3	FLG	0.70H.3	R/W	Port 0A bit 3
P0A2	FLG	0.70H.2	R/W	Port 0A bit 2
P0A1	FLG	0.70H.1	R/W	Port 0A bit 1
P0A0	FLG	0.70H.0	R/W	Port 0A bit 0
P0B3	FLG	0.71H.3	R/W	Port 0B bit 3
P0B2	FLG	0.71H.2	R/W	Port 0B bit 2
P0B1	FLG	0.71H.1	R/W	Port 0B bit 1
P0B0	FLG	0.71H.0	R/W	Port 0B bit 0
P0C3	FLG	0.72H.3	R/W	Port 0C bit 3
P0C2	FLG	0.72H.2	R/W	Port 0C bit 2
P0C1	FLG	0.72H.1	R/W	Port 0C bit 1
P0C0	FLG	0.72H.0	R/W	Port 0C bit 0
P0D3	FLG	0.73H.3	R/W	Port 0D bit 3
P0D2	FLG	0.73H.2	R/W	Port 0D bit 2
P0D1	FLG	0.73H.1	R/W	Port 0D bit 1
P0D0	FLG	0.73H.0	R/W	Port 0D bit 0
P0E3	FLG	0.6EH.3	R/W	Port 0E bit 3
P0E2	FLG	0.6EH.2	R/W	Port 0E bit 2
P0E1	FLG	0.6EH.1	R/W	Port 0E bit 1
P0E0	FLG	0.6EH.0	R/W	Port 0E bit 0
P0F1	FLG	0.6FH.1	R	Port 0F bit 1
P0F0	FLG	0.6FH.0	R	Port 0F bit 0

Register file (control register)

Symbolic name	Attribute	Value	Read/write	Description
SP	MEM	0.81H	R/W	Stack pointer
SIOTS	FLG	0.82H.3	R/W	Serial interface start flag
SIOHIZ	FLG	0.82H.2	R/W	Function selection flag for the P0D ₁ /SO pin
SIOCK1	FLG	0.82H.1	R/W	Bit 1 of source clock selection flag for the serial interface
SIOCK0	FLG	0.82H.0	R/W	Bit 0 of source clock selection flag for the serial interface
WDTRES	FLG	0.83H.3	R/W	Watchdog timer reset flag
WDTEN	FLG	0.83H.0	R/W	Watchdog timer enable flag
TM1OSEL	FLG	0.8BH.3	R/W	Function selection flag for the P0D ₃ /TM1OUT pin
SIOEN	FLG	0.8BH.0	R/W	Serial interface enable flag
P0EGPU	FLG	0.8CH.2	R/W	P0E group pull-up selection flag (1: Pull-up)
P0BGPU	FLG	0.8CH.1	R/W	P0B group pull-up selection flag (1: Pull-up)
P0AGPU	FLG	0.8CH.0	R/W	P0A group pull-up selection flag (1: Pull-up)
P0DBPU3	FLG	0.8DH.3	R/W	P0D ₃ pull-up selection flag (1: Pull-up)
P0DBPU2	FLG	0.8DH.2	R/W	P0D ₂ pull-up selection flag (1: Pull-up)
P0DBPU1	FLG	0.8DH.1	R/W	P0D ₁ pull-up selection flag (1: Pull-up)
P0DBPU0	FLG	0.8DH.0	R/W	P0D ₀ pull-up selection flag (1: Pull-up)
INT	FLG	0.8FH.0	R	INT pin status flag
TM0EN	FLG	0.91H.3	R/W	Timer 0 enable flag
TM0RES	FLG	0.91H.2	R/W	Timer 0 reset flag
TM0CK1	FLG	0.91H.1	R/W	Bit 1 of source clock selection flag for timer 0
TM0CK0	FLG	0.91H.0	R/W	Bit 0 of source clock selection flag for timer 0
TM1EN	FLG	0.92H.3	R/W	Timer 1 enable flag
TM1RES	FLG	0.92H.2	R/W	Timer 1 reset flag
TM1CK1	FLG	0.92H.1	R/W	Bit 1 of source clock selection flag for timer 1
TM1CK0	FLG	0.92H.0	R/W	Bit 0 of source clock selection flag for timer 1
BTMISEL	FLG	0.93H.3	R/W	Interrupt request clock selection flag for the basic interval timer
BTMRES	FLG	0.93H.2	R/W	Basic interval timer reset flag
BTMCK1	FLG	0.93H.1	R/W	Bit 1 of source clock selection flag for the basic interval timer
BTMCK0	FLG	0.93H.0	R/W	Bit 0 of source clock selection flag for the basic interval timer
P0C3IDI	FLG	0.9BH.3	R/W	Input port disable flag for P0C ₃ (pin function selection between ADC ₃ and P0C ₃)
P0C2IDI	FLG	0.9BH.2	R/W	Input port disable flag for P0C ₂ (pin function selection between ADC ₂ and P0C ₂)
P0C1IDI	FLG	0.9BH.1	R/W	Input port disable flag for P0C ₁ (pin function selection between ADC ₁ and P0C ₁)
P0C0IDI	FLG	0.9BH.0	R/W	Input port disable flag for P0C ₀ (pin function selection between ADC ₀ and P0C ₀)
P0CBIO3	FLG	0.9CH.3	R/W	Input/output selection flag for P0C ₃ (1: Output port)
P0CBIO2	FLG	0.9CH.2	R/W	Input/output selection flag for P0C ₂ (1: Output port)
P0CBIO1	FLG	0.9CH.1	R/W	Input/output selection flag for P0C ₁ (1: Output port)
P0CBIO0	FLG	0.9CH.0	R/W	Input/output selection flag for P0C ₀ (1: Output port)
IEGMD1	FLG	0.9FH.1	R/W	Bit 1 of detection edge selection flag for the INT pin
IEGMD0	FLG	0.9FH.0	R/W	Bit 0 of detection edge selection flag for the INT pin

Register file (control register)

Symbolic name	Attribute	Value	Read/write	Description
ADCSTRT	FLG	0.0A0H.0	R/W	A/D converter start flag (always 0 when read)
ADCSOFT	FLG	0.0A1H.3	R/W	A/D converter operation mode selection flag (1: Single mode)
ADCCMP	FLG	0.0A1H.1	R	A/D converter comparison result flag (valid only in the single mode)
ADCEND	FLG	0.0A1H.0	R	A/D converter conversion end flag
ADCCH3	FLG	0.0A2H.3	R/W	Dummy flag
ADCCH2	FLG	0.0A2H.2	R/W	Dummy flag
ADCCH1	FLG	0.0A2H.1	R/W	Bit 1 of channel selection flag for the A/D converter
ADCCH0	FLG	0.0A2H.0	R/W	Bit 0 of channel selection flag for the A/D converter
P0DBIO3	FLG	0.0ABH.3	R/W	Input/output selection flag for P0D ₃ (1: Output port)
P0DBIO2	FLG	0.0ABH.2	R/W	Input/output selection flag for P0D ₂ (1: Output port)
P0DBIO1	FLG	0.0ABH.1	R/W	Input/output selection flag for P0D ₁ (1: Output port)
P0DBIO0	FLG	0.0ABH.0	R/W	Input/output selection flag for P0D ₀ (1: Output port)
P0EGIO	FLG	0.0ACH.2	R/W	Group input/output selection flag for P0E (1: All P0E pins are output ports.)
P0BGIO	FLG	0.0ACH.1	R/W	Group input/output selection flag for P0B (1: All P0B pins are output ports.)
P0AGIO	FLG	0.0ACH.0	R/W	Group input/output selection flag for P0A (1: All P0A pins are output ports.)
IPSIO	FLG	0.0AEH.0	R/W	Interrupt enable flag for the serial interface
IPBTM	FLG	0.0AFH.3	R/W	Interrupt enable flag for the basic interval timer
IPTM1	FLG	0.0AFH.2	R/W	Interrupt enable flag for timer 1
IPTM0	FLG	0.0AFH.1	R/W	Interrupt enable flag for timer 0
IP	FLG	0.0AFH.0	R/W	Interrupt enable flag for the INT pin
IRQSIO	FLG	0.0BBH.0	R/W	Interrupt request flag for the serial interface
IRQBTM	FLG	0.0BCH.0	R/W	Interrupt request flag for the basic interval timer
IRQTM1	FLG	0.0BDH.0	R/W	Interrupt request flag for timer 1
IRQTM0	FLG	0.0BEH.0	R/W	Interrupt request flag for timer 0
IRQ	FLG	0.0BFH.0	R/W	Interrupt request flag for the INT pin

Peripheral hardware register

Symbolic name	Attribute	Value	Read/write	Description
SIOSFR	DAT	01H	R/W	Peripheral address of the shift register
TM0M	DAT	02H	W	Peripheral address of the timer 0 modulo register
TM1M	DAT	03H	W	Peripheral address of the timer 1 modulo register
ADCR	DAT	04H	R/W	Peripheral address of A/D converter data register
TM0TM1C	DAT	45H	R	Peripheral address of timer 0 timer 1 count register
AR	DAT	40H	R/W	Peripheral address of the address register for GET, PUT, PUSH, CALL, BR, MOVT, and INC instructions

Others

Symbolic name	Attribute	Value	Description
SDBF	DAT	0FH	Fixed operand value for a PUT/GET/MOVT instruction
IX	DAT	01H	Fixed operand value for an INC instruction

Fig. 21-2 Control Register Configuration (1/2)

Column address																											
Row address	Item	0		1		2		3		4		5		6		7											
0 (8)	Symbol					0				S I O T S	S I O H Z	S I O C K 1	S I O C K 0	W D T R E S	0	0	0	0	W D T E N								
	When reset					0	1	0	1	0	0	0	0	0	0	0	0										
	Read/Write					R/W				R/W				R/W													
1 (9)	Symbol					T M O N S	T M O R E S	T M O R E S	T M O R E S	T M O R E S	T M O R E S	T M O R E S	T M O R E S	B T M S E L	B T M S E S	B T M S E S	B T M S E S										
	When reset					0	0	0	0	1	0	0	0	0	0	0	0										
	Read/Write					R/W				R/W				R/W													
2 (A)	Symbol	0	0	0		A D C S T R T	A D C S T R T	A D C M P	A D C E N D	A D C C H 3	A D C C H 2	A D C C H 1	A D C C H 0														
	When reset	0	0	0	0	0	0	0	0	0	0	0	0														
	Read/Write	R/W				R/W		R		R/W																	
3 (B)	Symbol																										
	When reset																										
	Read/Write																										

Remark The address enclosed in parentheses apply when the AS17K assembler is used.
 The names of all the flags in the control registers are assembler reserved words saved in the device file. Using these reserved words is useful in programming.

22. ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C)

Parameter	Symbol	Conditions		Rated value	Unit
Supply voltage	V _{DD}			-0.3 to +7.0	V
A/D converter reference voltage	V _{REF}			-0.3 to V _{DD} + 0.3	V
Input voltage	V _I	P0A, P0B, P0C, P0D, P0E, P0F, INT, RESET, and X _{IN}		-0.3 to V _{DD} + 0.3	V
Output voltage	V _O			-0.3 to V _{DD} + 0.3	V
High-level output current	I _{OH} ^{Note}	Each of P0A, P0B, and P0C pins	Peak value	-15	mA
			rms	-7.5	mA
		Total of P0A, P0B, and P0C pins	Peak value	-30	mA
			rms	-15	mA
Low-level output current	I _{OL} ^{Note}	Each of P0A, P0B, and P0C	Peak value	15	mA
			rms	7.5	mA
		Each of P0D and P0E	Peak value	30	mA
			rms	15	mA
		Total of P0A, P0B, P0C, P0D, and P0E pins	Peak value	100	mA
			rms	50	mA
Operating ambient temperature	T _A			-40 to +85	°C
Storage temperature	T _{stg}			-65 to +150	°C
Allowable dissipation	P _d	T _A = 85 °C	28-pin plastic shrink DIP	140	mW
			28-pin plastic SOP	85	mW

Note Calculate a root-mean-square value as follows: [rms value] = [peak value] × √duty.

Caution Absolute maximum ratings are rated values beyond which some physical damages may be caused to the product; if any of the parameters in the table above exceeds its rated value even for a moment, the quality of the product may deteriorate. Be sure to use the product within the rated values.

RECOMMENDED POWER VOLTAGE RANGE (T_A = -40 to +85 °C)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
Supply voltage	V _{DD}	CPU (except A/D converter and POC circuit)	f _x = 400 kHz to 2 MHz	2.7		5.5	V
			f _x = 400 kHz to 4 MHz	3.6		5.5	V
			f _x = 400 kHz to 8 MHz	4.5		5.5	V
		A/D converter	Absolute accuracy: ±1.5 LSB, 2.5 V ≤ V _{REF} ≤ V _{DD}	4.0		5.5	V
★	POC circuit (mask option)	f _x = 400 kHz to 4 MHz	4.5		5.5	V	

DC CHARACTERISTICS (V_{DD} = 2.7 to 5.5 V, T_A = -40 to +85 °C)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
High-level input voltage	V _{IH1}	P0A, P0B, P0C, P0D, P0E, and P0F		0.7V _{DD}		V _{DD}	V
	V _{IH2}	RESET, SCK, SI, and INT		0.8V _{DD}		V _{DD}	V
	V _{IH3}	X _{IN}		V _{DD} - 0.5		V _{DD}	V
Low-level input voltage	V _{IL1}	P0A, P0B, P0C, P0D, P0E, and P0F		0		0.3V _{DD}	V
	V _{IL2}	RESET, SCK, SI, and INT		0		0.2V _{DD}	V
	V _{IL3}	X _{IN}		0		0.4	V
High-level output voltage	V _{OH}	P0A, P0B, and P0C	4.5 - V _{DD} - 5.5 I _{OH} = -1.0 mA	V _{DD} - 0.3			V
			2.7 - V _{DD} < 4.5 I _{OH} = -0.5 mA	V _{DD} - 0.3			V
Low-level output voltage	V _{OL1}	P0A, P0B, P0C, P0D, and P0E	4.5 - V _{DD} - 5.5 I _{OL} = 1.0 mA			0.3	V
			2.7 - V _{DD} < 4.5 I _{OL} = 0.5 mA			0.3	V
	V _{OL2}	P0D and P0E I _{OL} = 15 mA	4.5 - V _{DD} - 5.5			1.0	V
			2.7 - V _{DD} < 4.5			2.0	V
High-level input leakage current	I _{LIH}	P0A, P0B, P0C, P0D, P0E, P0F, RESET, and INT V _{IN} = V _{DD}				3	μA
Low-level input leakage current	I _{LIL}	P0A, P0B, P0C, P0D, P0E, P0F, RESET, and INT V _{IN} = 0 V				-3	μA
High-level output leakage current	I _{LOH}	P0A, P0B, P0C, P0D, and P0E V _{OUT} = V _{DD}				3	μA
Low-level output leakage current	I _{LOL}	P0A, P0B, P0C, P0D, and P0E V _{OUT} = 0 V				-3	μA
Built-in pull-up resistance ^{Note 1}	R _{PULL}	P0A, P0B, P0E, P0F, RESET, and INT		50	100	200	kΩ
		P0D		3	10	30	kΩ
Power supply current ^{Note 2}	I _{DD1}	Normal operation mode	f _x = 8.0 MHz, V _{DD} = 5 V ±10 %		2.0	4.5	mA
			f _x = 4.0 MHz, V _{DD} = 5 V ±10 %		1.4	3.3	mA
			f _x = 2.0 MHz, V _{DD} = 5 V ±10 %		1.0	2.5	mA
			f _x = 2.0 MHz, V _{DD} = 3 V ±10 %		0.8	2.5	mA
			f _x = 1.0 MHz, V _{DD} = 5 V ±10 %		0.7	2.0	mA
			f _x = 400 kHz	V _{DD} = 5 V ±10 %	0.9	1.7	mA
		V _{DD} = 3 V ±10 %	0.3	1.0	mA		
	I _{DD2}	HALT mode	f _x = 8.0 MHz, V _{DD} = 5 V ±10 %		1.0	2.0	mA
			f _x = 4.0 MHz, V _{DD} = 5 V ±10 %		0.9	1.9	mA
			f _x = 2.0 MHz, V _{DD} = 3 V ±10 %		0.5	1.7	mA
			f _x = 1.0 MHz, V _{DD} = 5 V ±10 %		0.5		mA
			f _x = 400 kHz	V _{DD} = 5 V ±10 %	0.7	1.5	mA
			V _{DD} = 3 V ±10 %	0.3	0.9	mA	
I _{DD3}	STOP mode	V _{DD} = 5 V ±10 %			3.0	10	μA
		V _{DD} = 3 V ±10 %			2.0	10	μA

Notes 1. The pull-up resistors for the P0F, RESET, and INT pins are specified with mask options.

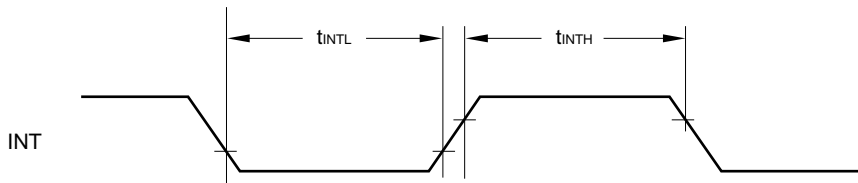
2. This current excludes the current which flows through the A/D converter, POC circuit, and built-in pull-up resistors.

AC CHARACTERISTICS ($V_{DD} = 2.7$ to 5.5 V, $T_A = -40$ to $+85$ °C)

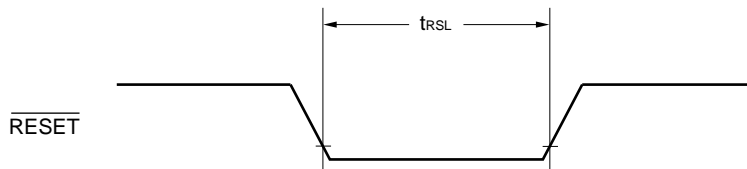
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
CPU clock cycle time (instruction execution time)	t_{CY}	$V_{DD} = 4.5$ to 5.5 V	1.9		41	μ S
		$V_{DD} = 3.6$ to 5.5 V	3.9		41	μ S
			7.9		41	μ S
INT input frequency (TM0 count clock input)	f_{INT}		0		400	kHz
INT high/low level width (external interrupt input)	t_{INTH} ,	$V_{DD} = 4.5$ to 5.5 V	10			μ S
	t_{INTL}		50			μ S
$\overline{\text{RESET}}$ low-level width	t_{RSL}	$V_{DD} = 4.5$ to 5.5 V	10			μ S
			50			μ S
$\overline{\text{RLS}}$ low-level width	t_{RLSL}	$V_{DD} = 4.5$ to 5.5 V	10			μ S
			50			μ S

Remark $t_{CY} = 16/f_x$ (f_x : frequency of system clock oscillator)

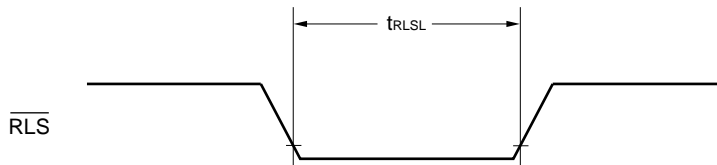
Interrupt input timing



$\overline{\text{RESET}}$ input timing



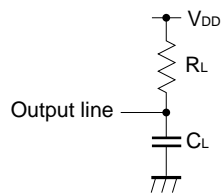
$\overline{\text{RLS}}$ input timing



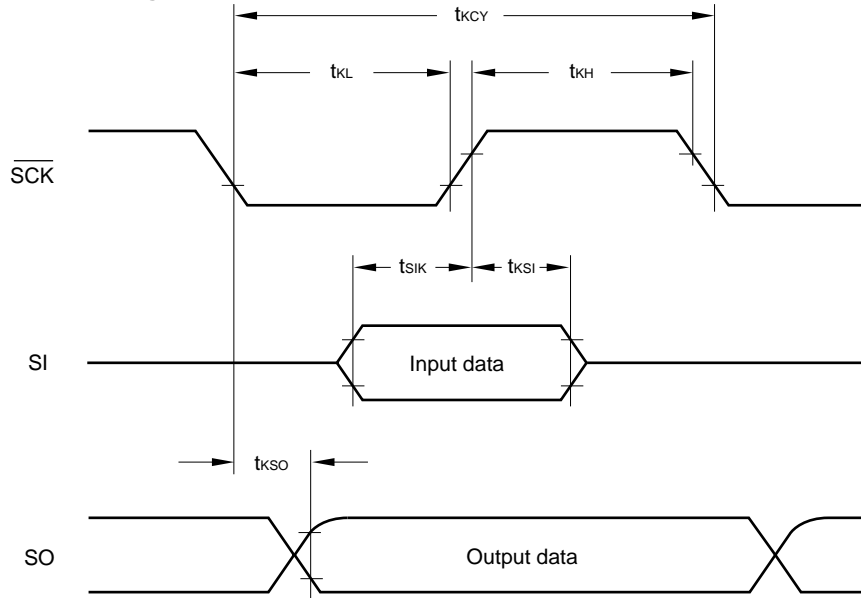
SERIAL TRANSFER OPERATION (V_{DD} = 2.7 to 5.5 V, T_A = -40 to +85 °C)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit	
$\overline{\text{SCK}}$ cycle time	t_{KCY}	Input	V _{DD} = 4.5 to 5.5 V		2.0			μs
					10			μs
		Output	R _L = 1 kΩ, C _L = 100 pF	V _{DD} = 4.5 to 5.5 V	2.0			μs
					8			μs
			Built-in pull-up resistor, C _L = 100 pF	V _{DD} = 4.5 to 5.5 V	32			μs
					64			μs
$\overline{\text{SCK}}$ high/low level width	t_{KH} , t_{KL}	Input	V _{DD} = 4.5 to 5.5 V		1.0			μs
					5.0			μs
		Output	R _L = 1 kΩ, C _L = 100 pF	V _{DD} = 4.5 to 5.5 V	$t_{\text{KCY}}/2-0.6$			μs
					$t_{\text{KCY}}/2-1.2$			μs
			Built-in pull-up resistor, C _L = 100 pF	V _{DD} = 4.5 to 5.5 V	$t_{\text{KCY}}/2-12$			μs
					$t_{\text{KCY}}/2-24$			μs
SI setup time (with respect to $\overline{\text{SCK}}\uparrow$)	t_{SIK}			100			ns	
SI hold time (with respect to $\overline{\text{SCK}}\uparrow$)	t_{KSI}			100			ns	
Delay from $\overline{\text{SCK}}\downarrow$ to SO	t_{KSO}	R _L = 1 kΩ, C _L = 100 pF	V _{DD} = 4.5 to 5.5 V			0.8	μs	
						1.4	μs	
		Built-in pull-up resistor, C _L = 100 pF	V _{DD} = 4.5 to 5.5 V			14	μs	
						26	μs	

Remark R_L: a resistive load for the output line
 C_L: a capacitive load for the output line



Serial transfer timing



A/D CONVERTER ($V_{DD} = 4.5$ to 5.5 V, $T_A = -40$ to $+85$ °C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Resolution			8	8	8	bit
Absolute accuracy ^{Note 1}		$2.5\text{ V} \leq V_{REF} \leq V_{DD}$			± 1.5	LSB
Conversion time ^{Note 2}	t_{CONV}				$25 t_{CY}$	μs
Analog signal input voltage	V_{ADIN}		0		V_{REF}	V
Reference input voltage	V_{REF}		2.5		V_{DD}	V
A/D converter circuit current	I_{ADC}	When A/D converter is operating		1.0	2.0	mA
V_{REF} pin current	I_{REF}			0.1	0.3	mA

- Notes**
1. Absolute accuracy excluding quantization error (± 0.5 LSB)
 2. Time from conversion start instruction execution to conversion end ($ADCEND = 1$) (at $f_x = 8$ MHz, $50 \mu\text{s}$).

Remark $t_{CY} = 16/f_x$ (f_x : frequency of system clock oscillator)

POC CIRCUIT (MASK OPTION^{Note 1}) ($V_{DD} = 2.7$ to 5.5 V, $T_A = -40$ to $+85$ °C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
POC detection voltage ^{Note 2}	V_{POC}		3.6	4.0	4.45	V
Supply voltage fall speed	t_{POCS}				0.08	V/ms
Reset detection pulse width	t_{SAMP}		1			ms
POC circuit current	I_{POC}			3.0	10	μA

- Notes**
1. This circuit can be used in an application circuit where V_{DD} is 4.5 to 5.5 V and the clock frequency (f_x) ranges from 400 kHz to 4 MHz.
 2. This is the voltage at which the POC circuit releases the internal reset. When V_{POC} becomes less than V_{DD} , the internal reset is released.

CHARACTERISTICS OF THE SYSTEM CLOCK OSCILLATOR (V_{DD} = 2.7 to 5.5 V, T_A = -40 to +85 °C)

Resonator ^{Note}	Parameter	Conditions	Min.	Typ.	Max.	Unit
Ceramic resonator	Oscillation frequency (f _x)		0.39		2.04	MHz
		V _{DD} = 3.6 to 5.5 V	0.39		4.08	MHz
		V _{DD} = 4.5 to 5.5 V	0.39		8.16	MHz

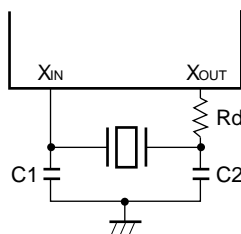
Note Do not use a resonator having an oscillation generation time of 2 ms or more.

RECOMMENDED CERAMIC RESONATORS (T_A = -40 to +85 °C)

Manufacturer	Part number	Recommended constants			Supply voltage [V] ^{Note 1}		Remarks
		C1 [pF]	C2 [pF]	Rd [kΩ]	Min.	Max.	
Murata Mfg.	CSB400P	220	220	5.6	2.7	5.5	Electrical equipment for automobiles
	CSA2. 00MG040	100	100	0	2.7	5.5	
	CST2. 00MG040	Not required ^{Note 2}		0	2.7	5.5	
	CSA4. 00MG	30	30	0	3.6	5.5	
	CST4. 00MGW	Not required ^{Note 2}		0	3.6	5.5	
	CSA8. 00MG	30	30	0	4.5	5.5	
	CST8. 00MGW	Not required ^{Note 2}		0	4.5	5.5	
	CSB400JA	220	220	5.6	2.7	5.5	
	CSA2. 00MGA040	100	100	0	2.7	5.5	
	CST2. 00MGA040	Not required ^{Note 2}		0	2.7	5.5	
	CSA4. 00MGA	30	30	0	3.6	5.5	
	CST4. 00MGWA	Not required ^{Note 2}		0	3.6	5.5	
	CSA8. 00MTZA	30	30	0	4.5	5.5	
	CST8. 00MTWA	Not required ^{Note 2}		0	4.5	5.5	
Kyocera	KBR-400BK	470	470	0	2.7	5.5	
	KBR-2. 0MS	47	47	0	2.7	5.5	
	KBR-4. 0MSA	33	33	0	3.6	5.5	
	KBR-8. 0M	33	33	0	4.5	5.5	
TDK	FCR400K3	330	330	0	2.7	5.5	
	FCR2. 0M3	100	100	0	2.7	5.5	
	FCR2. 0MC3	Not required ^{Note 2}		1.5	2.7	5.5	
	FCR4. 0M5	33	33	0	3.6	5.5	
	CCR4. 0MC3	Not required ^{Note 2}		0	3.6	5.5	
	FCR4. 0MC5	Not required ^{Note 2}		0	3.6	5.5	
	FCR8. 0M2S	33	33	0	4.5	5.5	
	FCR8. 0MC	Not required ^{Note 2}		0	4.5	5.5	

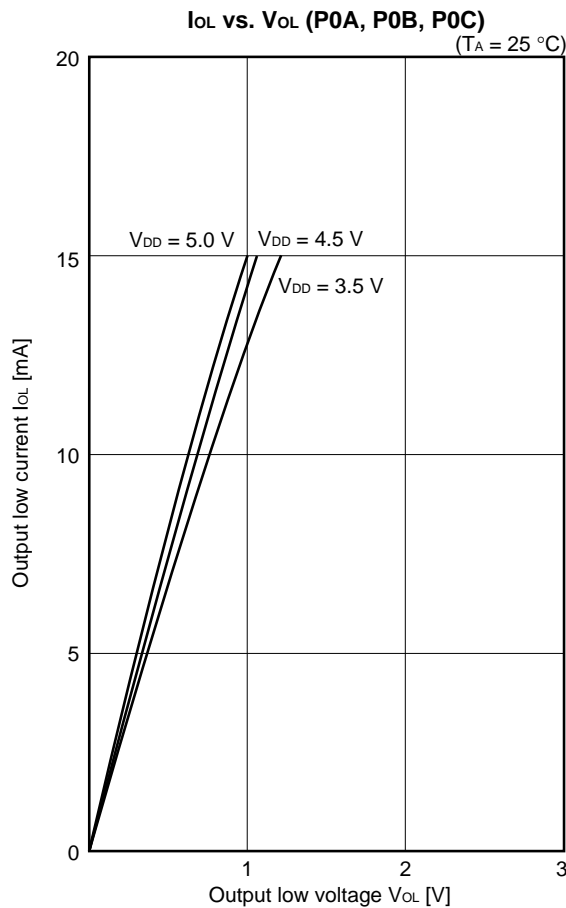
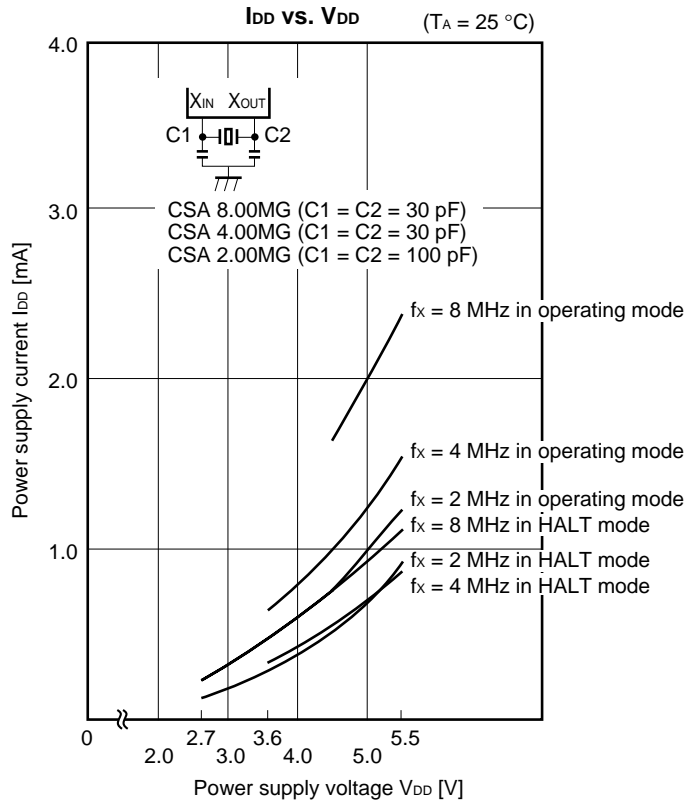
- Notes** 1. When the POC circuit (mask option) is not used
 2. Capacitors are contained.

Example of an external circuit

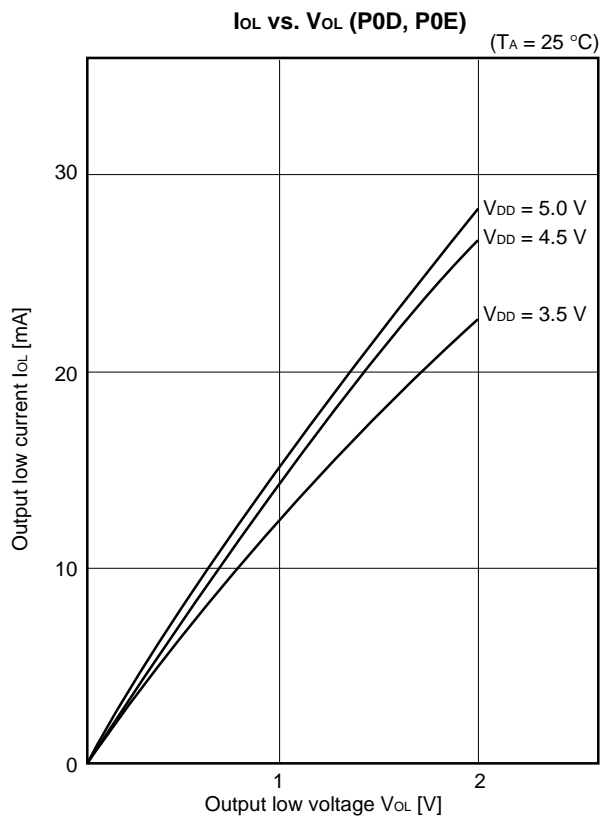


23. CHARACTERISTIC CURVES (FOR REFERENCE)

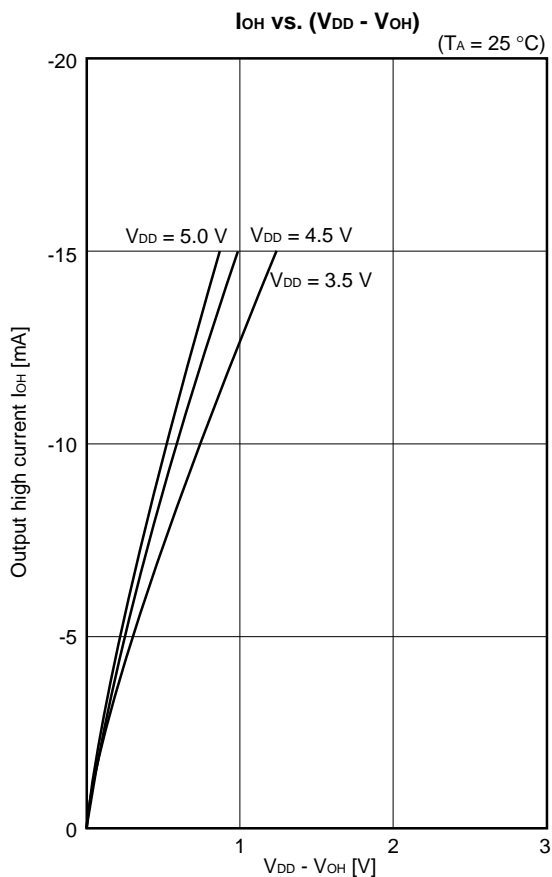
★



Caution Absolute maximum rating of output current is 15 mA (peak value) per pin.



Caution Absolute maximum rating of output current is 30 mA (peak value) per pin.

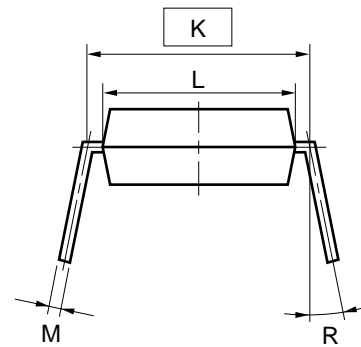
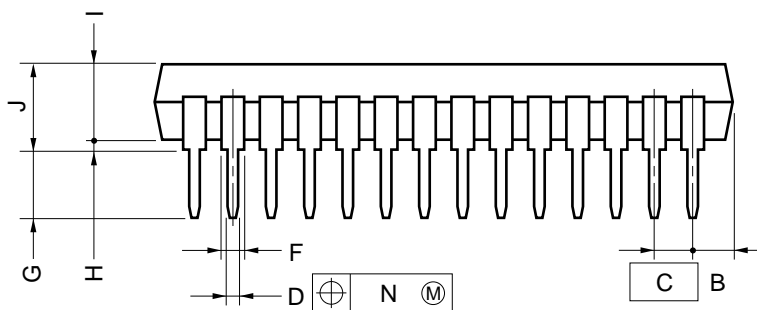
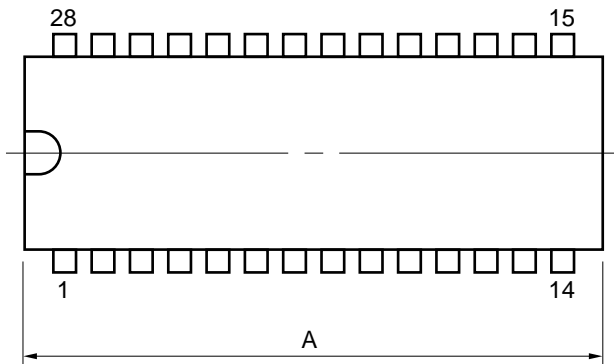


Caution Absolute maximum rating of output current is -15 mA (peak value) per pin.

24. PACKAGE DRAWINGS

PACKAGE DRAWINGS OF MASS-PRODUCED PRODUCTS (1/2)

28 PIN PLASTIC SHRINK DIP (400 mil)



NOTES

- 1) Each lead centerline is located within 0.17 mm (0.007 inch) of its true position (T.P.) at maximum material condition.
- 2) Item "K" to center of leads when formed parallel.

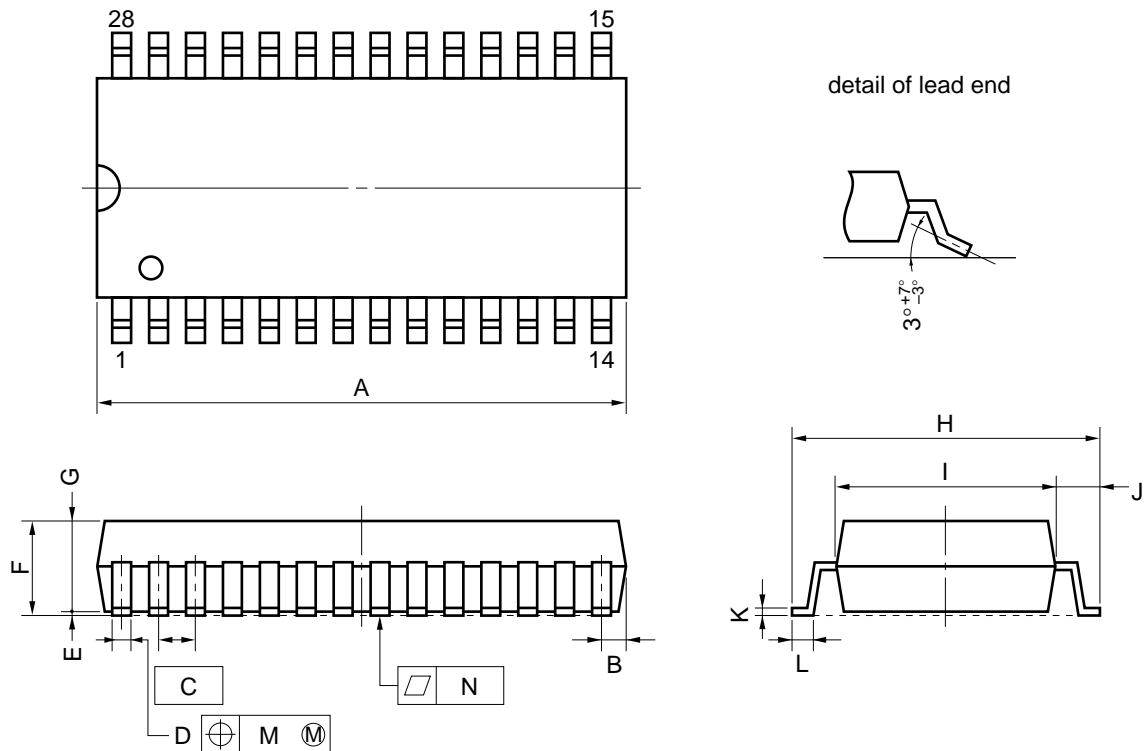
ITEM	MILLIMETERS	INCHES
A	28.46 MAX.	1.121 MAX.
B	2.67 MAX.	0.106 MAX.
C	1.778 (T.P.)	0.070 (T.P.)
D	0.50±0.10	0.020 ^{+0.004} _{-0.005}
F	0.85 MIN.	0.033 MIN.
G	3.2±0.3	0.126±0.012
H	0.51 MIN.	0.020 MIN.
I	4.31 MAX.	0.170 MAX.
J	5.08 MAX.	0.200 MAX.
K	10.16 (T.P.)	0.400 (T.P.)
L	8.6	0.339
M	0.25 ^{+0.10} _{-0.05}	0.010 ^{+0.004} _{-0.003}
N	0.17	0.007
R	0°A15°	0°A15°

S28C-70-400B-1

Caution The ES is different from the corresponding mass-produced products in shape and material. See "ES PACKAGE DRAWINGS (1/2)."

PACKAGE DRAWINGS OF MASS-PRODUCED PRODUCTS (2/2)

28 PIN PLASTIC SOP (375 mil)



P28GT-50-375B-1

NOTE

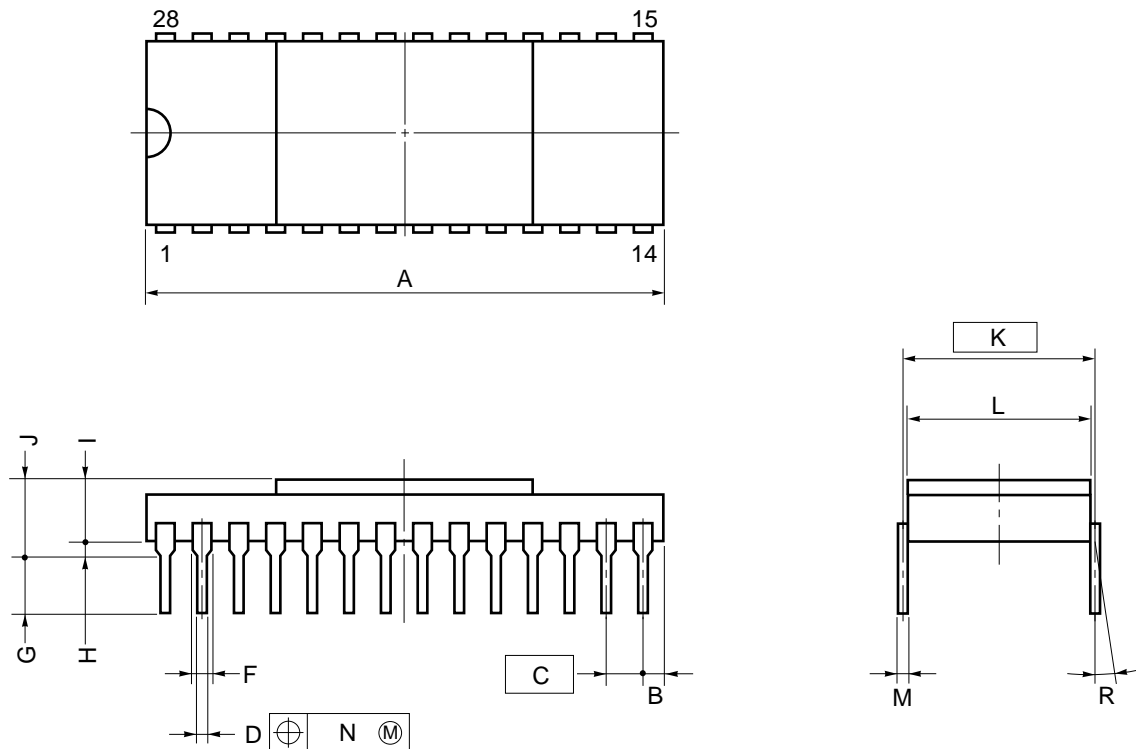
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.2 MAX.	0.717 MAX.
B	0.845 MAX.	0.034 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ^{+0.10} _{-0.05}	0.016 ^{+0.004} _{-0.003}
E	0.125±0.075	0.005±0.003
F	2.9 MAX.	0.115 MAX.
G	2.50±0.2	0.098 ^{+0.009} _{-0.008}
H	10.3±0.3	0.406 ^{+0.012} _{-0.013}
I	7.2±0.2	0.283 ^{+0.009} _{-0.008}
J	1.6±0.2	0.063±0.008
K	0.15 ^{+0.10} _{-0.05}	0.006 ^{+0.004} _{-0.002}
L	0.8±0.2	0.031 ^{+0.009} _{-0.008}
M	0.12	0.005
N	0.10	0.004

Caution The ES is different from the corresponding mass-produced products in shape and material. See "ES PACKAGE DRAWINGS (2/2)."

ES PACKAGE DRAWINGS (1/2)

28 PIN CERAMIC SHRINK DIP (400mil) (FOR ES)



NOTES

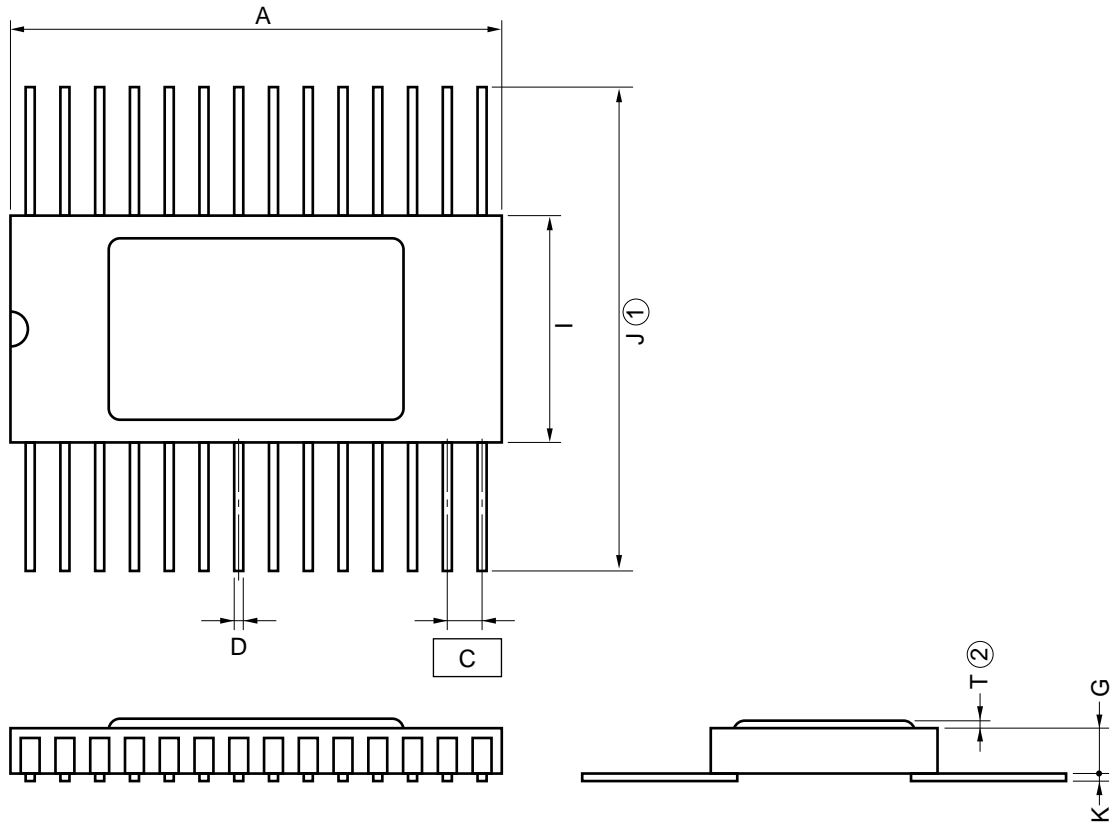
- 1) Each lead centerline is located within 0.25 mm (0.01 inch) of its true position (T.P.) at maximum material condition.
- 2) Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS	INCHES
A	28.0 MAX.	1.103 MAX.
B	5.1 MAX.	0.201 MAX.
C	1.778 (T.P.)	0.070 (T.P.)
D	0.46±0.05	0.018±0.002
F	0.8 MIN.	0.031 MIN.
G	3.0±1.0	0.118±0.04
H	1.0 MIN.	0.039 MIN.
I	2.7	0.106
J	4.3 MAX.	0.170 MAX.
K	10.16 (T.P.)	0.400 (T.P.)
L	9.84	0.387
M	0.25±0.05	0.010 ^{+0.002} _{-0.003}
N	0.25	0.010
R	0~15°	0~15°

P28D-70-400B-1

ES PACKAGE DRAWINGS (2/2)

28 PIN CERAMIC SOP (FOR ES)



NOTE

The lengths of leads (①) and the height of potting (②) are not to be specified because the lead cutting process and the potting process are not controlled.

ITEM	MILLIMETERS	INCHES
A	18.0±0.2	0.709 ^{+0.008} _{-0.009}
C	1.27 (T.P.)	0.05 (T.P.)
D	0.4±0.05	0.016 ^{+0.002} _{-0.003}
G	1.52±0.15	0.06±0.006
I	8.4±0.15	0.331 ^{+0.006} _{-0.007}
J	16.4	0.646
K	0.15±0.025	0.006±0.001
T	1.0	0.039

X28B-50B1

★ 25. RECOMMENDED SOLDERING CONDITIONS

The conditions listed below shall be met when soldering this product.

For details of the recommended soldering conditions, refer to our document *SMD Surface Mount Technology Manual* (C10535E).

Please consult with our sales offices in case any other soldering process is used, or in case soldering is done under different conditions.

Table 25-1 Soldering Conditions for Surface-Mount Devices

- μPD17145GT-xxx: 28-pin plastic SOP (375 mil)
- μPD17147GT-xxx: 28-pin plastic SOP (375 mil)
- μPD17149GT-xxx: 28-pin plastic SOP (375 mil)
- μPD17145GT(A)-xxx: 28-pin plastic SOP (375 mil)
- μPD17147GT(A)-xxx: 28-pin plastic SOP (375 mil)
- μPD17149GT(A)-xxx: 28-pin plastic SOP (375 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak package's surface temperature: 235 °C Reflow time: 30 seconds or less (at 210 °C or more) Maximum allowable number of reflow processes: 2 Exposure limit ^{Note} : 7 days (20 hours of pre-baking is required at 125 °C afterward.) <Caution> Non-heat resistant trays, such as magazine and taping trays, cannot be baked before unpacking.	IR35-207-2
VPS	Peak package's surface temperature: 215 °C Reflow time: 40 seconds or less (at 200 °C or more) Maximum allowable number of reflow processes: 2 Exposure limit ^{Note} : 7 days (20 hours of pre-baking is required at 125 °C afterward.) <Caution> Non-heat resistant trays, such as magazine and taping trays, cannot be baked before unpacking.	VP15-207-2
Partial heating method	Terminal temperature: 300 °C or less Heat time: 3 seconds or less (for each side of device)	-

Note Exposure limit before soldering after dry-pack package is opened.

Storage conditions: Temperature of 25 °C and maximum relative humidity at 65 % or less

Caution Do not apply more than a single process at once, except for "Partial heating method."

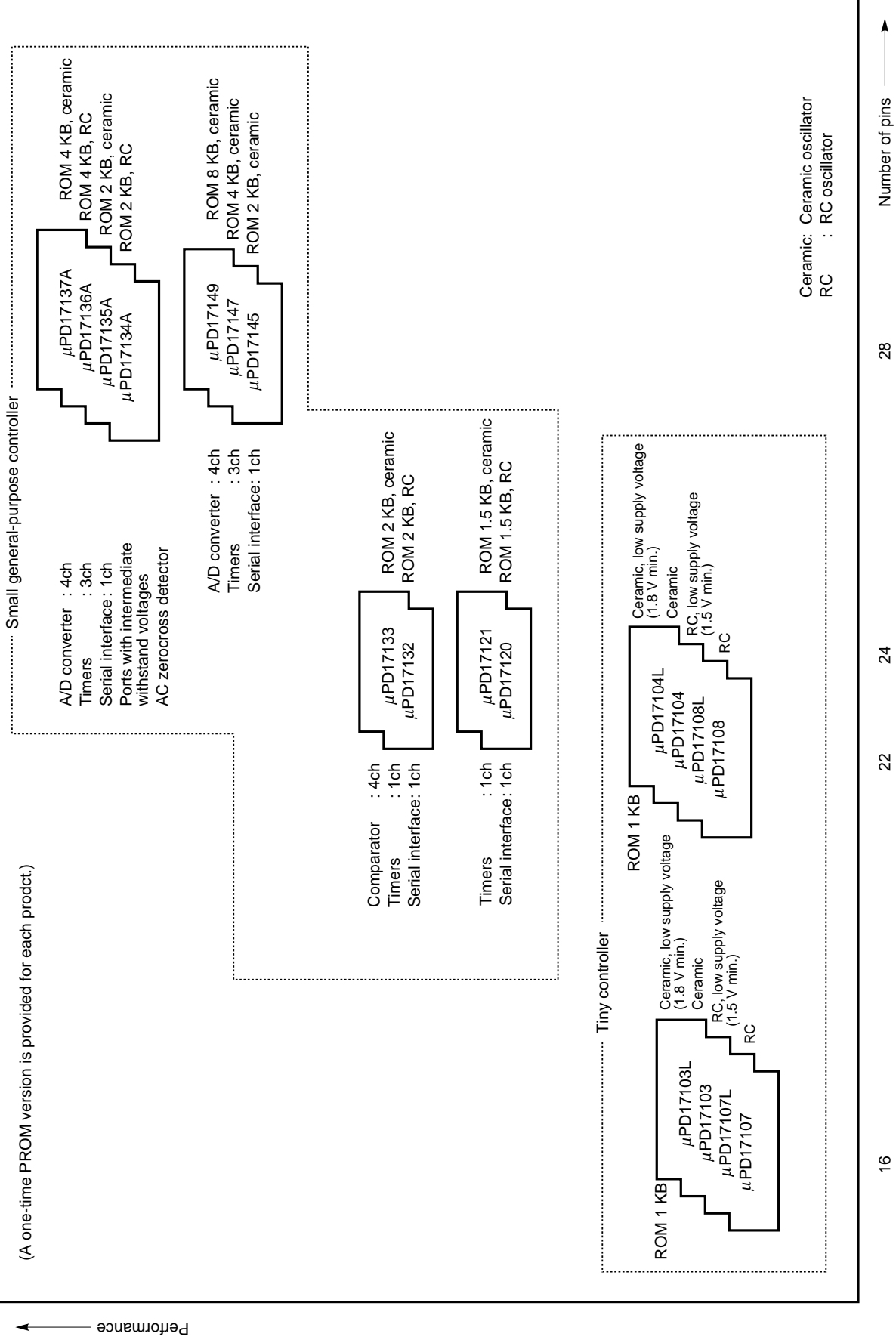
Table 25-2 Soldering Conditions for Through Hole Mount Devices

- μPD17145CT-xxx: 28-pin plastic shrink DIP (400 mil)**
- μPD17147CT-xxx: 28-pin plastic shrink DIP (400 mil)**
- μPD17149CT-xxx: 28-pin plastic shrink DIP (400 mil)**
- μPD17145CT(A)-xxx: 28-pin plastic shrink DIP (400 mil)**
- μPD17147CT(A)-xxx: 28-pin plastic shrink DIP (400 mil)**
- μPD17149CT(A)-xxx: 28-pin plastic shrink DIP (400 mil)**

Soldering process	Soldering conditions
Wave soldering (only for pins)	Solder temperature: 260 °C or less Flow time: 10 seconds or less
Partial heating method	Terminal temperature: 300 °C or less Heat time: 3 seconds or less (for each terminal)

Caution In wave soldering, apply solder only to the pins. Care must be taken that jet solder does not come in contact with the main body of the package.

APPENDIX A. DEVELOPMENT OF THE μPD171×× SUB-SERIES



APPENDIX B. COMPARISON OF FUNCTIONS OF μPD17145 SUB-SERIES, μPD17135A, AND μPD17137A

		μPD17145	μPD17147	μPD17149	μPD17135A	μPD17137A
ROM		2K bytes	4K bytes	8K bytes	2K bytes	4K bytes
RAM		110 × 4 bits			112 × 4 bits	
Stack		Five levels of address stack Three levels of interrupt stack				
★	Instruction execution time (clock, operating voltage)		2 μs (fx = 8 MHz, VDD = 4.5 to 5.5 V) 4 μs (fx = 4 MHz, VDD = 3.6 to 5.5 V) 8 μs (fx = 2 MHz, VDD = 2.7 to 5.5 V)		2 μs (fx = 8 MHz, VDD = 4.5 to 5.5 V) 4 μs (fx = 4 MHz, VDD = 2.7 to 5.5 V)	
	I/O	CMOS I/O	12 (P0A, P0B, P0C)			
		Dedicated to input	2 (P0F0, P0F1)		1 (P1B0)	
		Sense input	1 (INT) Pull-up by mask option enabled		1 (INT)	
	N-ch open-drain I/O	8 (P0D, P0E Withstand voltage : VDD) P0D pull-up resistor : Software P0E pull-up resistor : Software		8 (P0D, P1A Withstand voltage : 9 V) P0D pull-up resistor : Mask option P1A pull-up resistor : Mask option		
Built-in pull-up resistance		100 kΩ TYP. (other than P0D) 10 kΩ TYP. (P0D)		100 kΩ TYP.		
A/D converter (operating voltage)		Four 8-bit channels (VDD = 4.0 to 5.5 V)		Four 8-bit channels (VDD = 4.5 to 5.5 V)		
	Reference voltage pin	VREF (VREF = 2.5 V to VDD)		None (VREF = VADC = VDD)		
Timer	8-bit (TM0, TM1)	2 (Timer output : TM1OUT) TM0 clock : fx/512 fx/64 fx/16 INT TM1 clock : fx/8192 fx/128 fx/16 TM0 count-up		2 (Timer output : TM0OUT) TM0 clock : fx/256 fx/64 fx/16 INT TM1 clock : fx/1024 fx/512 fx/256 TM0 count-up		
	Basic interval (BTM)	1 (Also used as a watchdog timer) Count clock : fx/16384 fx/4096 fx/512 fx/16		1 (Also used as a watchdog timer) Count clock : fx/8192 fx/4096 TM0 count-up INT		
Inter-rupt	External	1		1 (AC zero cross detection is performed.)		
	Internal	4 (TM0, TM1, BTM, SIO)				
SIO		1 (Synchronous three-wire)				
	Output latch	Independent of P0D1 latch		Also used for P0D1 latch		
Standby function		HALT, STOP (Input pin RLS is provided for cancellation.)		HALT, STOP		
Oscillation settling time		128 × 256 count		512 × 256 count		

	μPD17145	μPD17147	μPD17149	μPD17135A	μPD17137A
POC function	Mask option			Built-in	
Package	28-pin plastic SDIP (400 mil) 28-pin plastic SOP (375 mil)				
One-time PROM	μPD17P149			μPD17P137A	

Caution μPD17145 sub-series, μPD17135A, and μPD17137A are not pin-compatible. Furthermore, the μPD17145 sub-series does not feature units that are equivalent to the μPD17134A and μPD17136A (RC oscillation type). For the electrical characteristics of these units, refer to the data sheet for each unit.

APPENDIX C. DEVELOPMENT TOOLS

The following support tools are available for developing programs for the μPD17145, μPD17147, μPD17149, μPD17145(A), μPD17147(A), and μPD17149(A).

Hardware

Name	Description
In-circuit emulator [IE-17K IE-17K-ET ^{Note 1} EMU-17K ^{Note 2}]	The IE-17K, IE-17K-ET, and EMU-17K are in-circuit emulators applicable to the 17K series. The IE-17K and IE-17K-ET are connected to the PC-9800 series (host machine) or IBM PC/AT™ through the RS-232-C interface. The EMU-17K is inserted into the extension slot of the PC-9800 series (host machine). Use the system evaluation board (SE board) corresponding to each product together with one of these in-circuit emulators. <i>SIMPLEHOST™</i> , a man machine interface, implements an advanced debug environment. The EMU-17K also enables user to check the contents of the data memory in real time.
SE board (SE-17145)	The SE-17145 is an SE board for the μPD17145 sub-series. It is used solely for evaluating the system. It is also used for debugging in combination with the in-circuit emulator.
Emulation probe (EP-17K28CT)	The EP-17K28CT is an emulation probe for the 17K series 28-pin shrink DIP (400 mil).
Emulation probe (EP-17K28GT)	The EP-17K28GT is an emulation probe for the 17K series 28-pin SOP (375 mil). Use this probe together with the conversion adapter EV-9500GT-28 ^{Note 3} , to check the target system with the corresponding SE board.
Conversion adapter (EV-9500GT-28 ^{Note 3})	The EV-9500GT-28 is an adapter for the 28-pin SOP (375 mil). Use this conversion adapter to connect the emulation probe, EP-17K28GT, to the target system.
★ PROM programmer ^{Note 4} [AF-9703 ^{Note 4} AF-9704 ^{Note 4} AF-9705 ^{Note 4} AF-9706 ^{Note 4}]	The AF-9703, AF-9704, AF-9705, and AF-9706 are PROM programmers for the μPD17P149. Use one of these PROM programmers with the program adapter, AF-9808M, to program the μPD17P149.
Programmer adapter ^{Note 4} (AF-9808M)	The AF-9808M is a socket unit for the μPD17P149. It is used with the AF-9703, AF-9704, AF-9705, or AF-9706.

- Notes**
1. Low-end model, operating on an external power supply
 2. The EMU-17K is a product of I.C Corporation. Contact I.C Corporation (Tokyo, 03-3447-3793) for details.
 3. An EP-17K28GT is supplied together with two EV-9500GT-28s. A set of five EV-9500GT-28s is also available.
 4. The AF-9703, AF-9704, AF-9705, AF-9706, and AF-9808M are products of Ando Electric Co., Ltd. Contact Ando Electric Co., Ltd. (Tokyo, 03-3733-1163) for details.

Software

Name	Description	Host machine	OS	Distribution media	Part number	
17K series assembler (AS17K)	AS17K is an assembler applicable to the 17K series. In developing μPD17145, μPD17147, or μPD17149 programs, AS17K is used in combination with a device file (AS17145).	PC-9800 series	MS-DOS™	5.25-inch, 2HD	μS5A10AS17K	
				3.5-inch, 2HD	μS5A13AS17K	
		IBM PC/AT	PC DOS™	5.25-inch, 2HC	μS7B10AS17K	
				3.5-inch, 2HC	μS7B13AS17K	
Device file (AS17145)	AS17145 contains device files for the μPD17145, μPD17147, and μPD17149. They are used together with the assembler (AS17K) which is applicable to the 17K series.	PC-9800 series	MS-DOS	5.25-inch, 2HD	μS5A10AS17145	
				3.5-inch, 2HD	μS5A13AS17145	
		IBM PC/AT	PC DOS	5.25-inch, 2HC	μS7B10AS17145	
				3.5-inch, 2HC	μS7B13AS17145	
Support software (SIMPLEHOST)	SIMPLEHOST, running on the Windows™, provides man-machine-interface in developing programs by using a personal computer and the in-circuit emulator.	PC-9800 series	MS-DOS	Windows	5.25-inch, 2HD	μS5A10IE17K
					3.5-inch, 2HD	μS5A13IE17K
		IBM PC/AT	PC DOS		5.25-inch, 2HC	μS7B10IE17K
					3.5-inch, 2HC	μS7B13IE17K

Remark The following table lists the versions of the operating systems described in the above table.

OS	Versions
MS-DOS	Ver. 3.30 to Ver. 5.00A ^{Note}
PC DOS	Ver. 3.1 to Ver. 5.0 ^{Note}
Windows	Ver. 3.0 to Ver. 3.1

Note MS-DOS versions 5.00 and 5.00A and PC DOS Ver. 5.0 are provided with a task swap function. This function, however, cannot be used in these software packages.

[MEMO]

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note: Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note: No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS device behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note: Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

Regional Information

Some information contained in this document may vary from country to country. Before using any NEC product in your application, please contact the NEC office in your country to obtain a list of authorized representatives and distributors. They will verify:

- Device availability
- Ordering information
- Product release schedule
- Availability of related technical literature
- Development environment specifications (for example, specifications for third-party tools and components, host computers, power plugs, AC supply voltages, and so forth)
- Network requirements

In addition, trademarks, registered trademarks, export restrictions, and other legal issues may also vary from country to country.

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 Fax: 800-729-9288

NEC Electronics (Germany) GmbH

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 Fax: 0211-65 03 490

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 Fax: 01908-670-290

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 Fax: 02-528-4411

NEC Electronics Singapore Pte. Ltd.

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 Tel: 253-8311
 Fax: 250-3583

NEC Electronics Taiwan Ltd.

Taipei, Taiwan
 Tel: 02-719-2377
 Fax: 02-719-5951

NEC do Brasil S.A.

Sao Paulo-SP, Brasil
 Tel: 011-889-1680
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